Smoke Detector Flash MCU
with 12V Piezoelectric Horn Driver

BA45F5320

Revision: V1.00 Date: August 31, 2021

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Table of Contents

Features

CPU Features

- Operating Voltage
  - f_{SYS}=8MHz: 2.2V~5.5V
- Up to 0.5μs instruction cycle with 8MHz system clock at V_{DD}=5V
- Power down and wake-up functions to reduce power consumption
- Oscillators
  - Internal High Speed 8MHz RC Oscillator – HIRC
  - Internal Low Speed 32kHz RC Oscillator – LIRC
- Fully integrated internal oscillators require no external components
- Multi-mode operation: FAST, SLOW, IDLE and SLEEP
- All instructions executed in one or two instruction cycles
- Table read instructions
- 61 powerful instructions
- 4-level subroutine nesting
- Bit manipulation instruction

Peripheral Features

- Flash Program Memory: 1K×14
- RAM Data Memory: 64×8
- Emulated EEPROM Memory: 32×14
- Watchdog Timer function
- Up to 4 bidirectional I/O lines
- Single pin-shared external interrupt
- A Timer Module for time measurement, input capture, compare match output, PWM output function or single pulse output function
- Dual Time-Base functions for generation of fixed time interrupt signals
- 3 external channel 10-bit resolution A/D converter
- Sink current generator for constant current output
- Smoke Detector AFE including two operational amplifiers
- Low voltage reset function
- Package type: 20-pin SSOP

Piezoelectric Horn Driver Feature

- Input voltage (BDV_{DD}): 2.2V~5.5V
- Supports self-driving(3-pin) or external-driving(2-pin) buzzer
- Integrated 12V boost converter

General Description

The BA45F5320 is an 8-bit high performance RISC architecture microcontroller, which includes a piezoelectric horn driver with boost converter and integrates a smoke detector AFE and a dual channel IR LED constant driving circuit, designed especially for Stand-alone type Smoke Detector applications.

For memory features, the Flash Memory offers users the convenience of multi-programming features. Other memory includes an area of RAM Data Memory as well as an area of Emulated EEPROM memory for storage of non-volatile data such as serial numbers, calibration data etc.

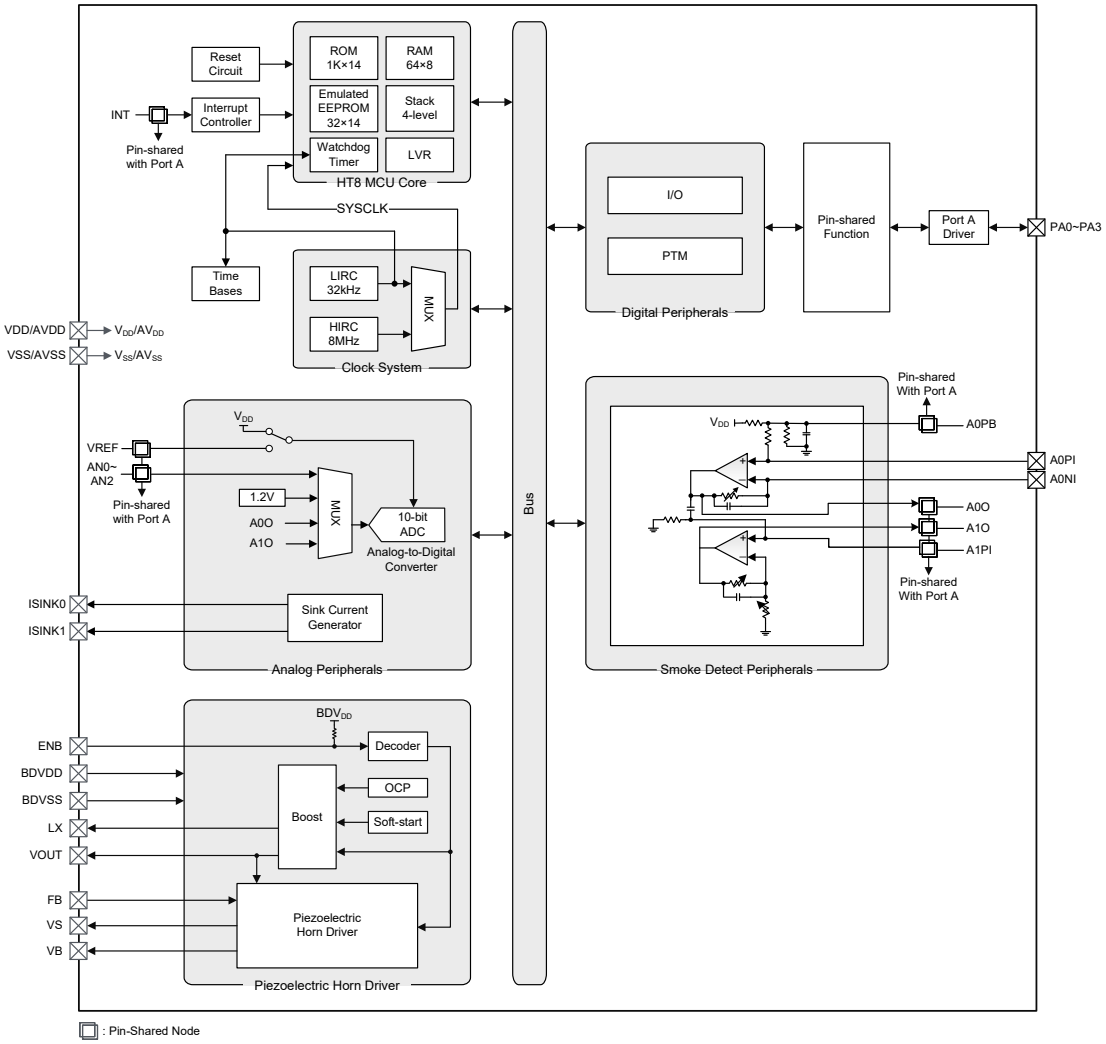
Analog features include a multi-channel 10-bit A/D converter and two internal operational amplifiers. One extremely flexible Timer Module provides timing, pulse generation and PWM generation functions. Protective features such as an internal Watchdog Timer and Low Voltage Reset function coupled with excellent noise immunity and ESD protection ensure that reliable operation is maintained in hostile electrical environments.

A full choice of internal high and low oscillators functions is provided including two fully integrated system oscillators which require no external components for their implementation. The ability to operate and switch dynamically between a range of operating modes using different clock sources gives users the ability to optimise microcontroller operation and minimise power consumption.

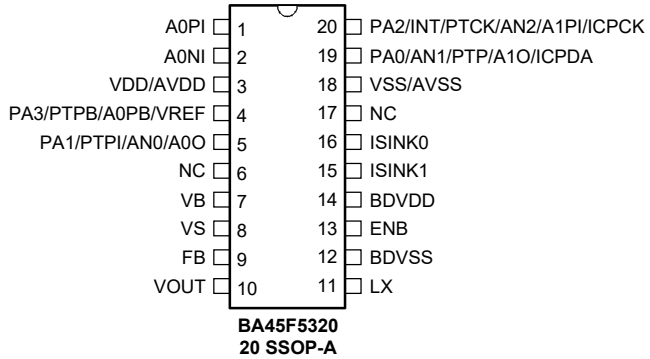
The device contains a piezoelectric horn driver with a 12V boost converter. The piezoelectric horn driver supports 2-pin or 3-pin buzzer.

The inclusion of flexible I/O programming features, Time-Base functions, piezoelectric horn driver along with many other features ensure that the device will find excellent use in the smoke detector applications.

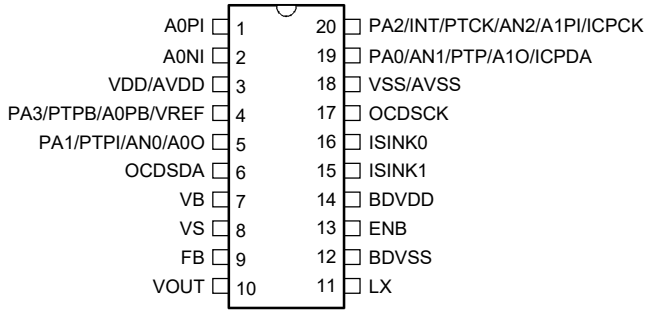
Block Diagram



Pin Assignment



BA45F5320
20 SSOP-A



BA45V5320
20 SOP-A

Note: 1. If the pin-shared pin functions have multiple outputs simultaneously, the desired pin-shared function is determined by the corresponding software control bits.
2. The OCDSDA and OCDSCK pins are supplied for the OCDS dedicated pins and as such only available for the BA45V5320 device which is the OCDS EV chip for the BA45F5320 device.
3. There is no OCDS EV chip applied in the 20-pin SSOP package.

Pin Description

The function of each pin is listed in the following table, however the details behind how each pin is configured is contained in other sections of the datasheet.

Pin Name	Function	OPT	I/T	O/T	Description
PA0/AN1/PTP/A1O/ICPDA	PA0	PAWU PAPU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	AN1	PAS0	AN	—	A/D Converter analog input channel
	PTP	PAS0	—	CMOS	PTM non-inverting output
	A1O	PAS0	—	AN	OPA1 output
	ICPDA	—	ST	CMOS	ICP data/address
PA1/PTPI/AN0/A0O	PA1	PAWU PAPU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	PTPI	PAS0	ST	—	PTM capture input
	AN0	PAS0	AN	—	A/D Converter analog input channel
	A0O	PAS0	—	AN	OPA0 output
PA2/INT/PTCK/AN2/A1PI/ICPCK	PA2	PAWU PAPU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	INT	INTEG INTC0 PAS0	ST	—	External interrupt
	PTCK	PAS0	ST	—	PTM clock input
	AN2	PAS0	AN	—	A/D Converter analog input channel
	A1PI	PAS0	AN	—	OPA1 non-inverting input
	ICPCK	—	ST	—	ICP clock pin
PA3/PTPB/A0PB/VREF	PA3	PAWU PAPU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up.
	PTPB	PAS0	—	CMOS	PTM inverting output
	A0PB	PAS0	AN	—	OPA0 non-inverting pin bias input
	VREF	PAS0	AN	—	A/D Converter external reference input
ISINK0	ISINK0	—	—	AN	Sink current 0 source

Pin Name	Function	OPT	I/T	O/T	Description
ISINK1	ISINK1	—	—	AN	Sink current 1 source
A0NI	A0NI	—	AN	—	OPA0 inverting input
A0PI	A0PI	—	AN	—	OPA0 non-inverting input
OCDSCK	OCDSCK	—	ST	—	OCDS clock, for EV chip only
OCDSDA	OCDSDA	—	ST	CMOS	OCDS data/address, for EV chip only
VDD/AVDD	VDD	—	PWR	—	Digital positive power supply
	AVDD	—	PWR	—	ADC positive power supply
VSS/AVSS	VSS	—	PWR	—	Digital negative power supply, ground
	AVSS	—	PWR	—	ADC negative power supply
BDVDD	BDVDD	—	PWR	—	Piezoelectric horn driver positive power supply
BDVSS	BDVSS	—	PWR	—	Piezoelectric horn driver negative power supply, ground
VOUT	VOUT	—	—	PWR	Boost converter output
LX	LX	—	—	PWR	Power switch output
ENB	ENB	—	ST	—	Enable pin with pull-high resister, used to control boost converter and buzzer driver mode
FB	FB	—	ST	—	Feedback pin for self-driving (3-pin) buzzer driver
VS	VS	—	—	CMOS	Output for buzzer driver
VB	VB	—	—	CMOS	Complementary output for buzzer driver

Note: I/T: Input type
OPT: Optional by register option
ST: Schmitt Trigger input
AN: Analog signal
O/T: Output type
PWR: Power
CMOS: CMOS output

Absolute Maximum Ratings

MCU Absolute Maximum Ratings

Supply Voltage ..... V_{SS}-0.3V to 6.0V
Input Voltage ..... V_{SS}-0.3V to V_{DD}+0.3V
Storage Temperature ..... -50°C to 125°C
Operating Temperature ..... -40°C to 85°C
I_{OL} Total 80mA
I_{OH} Total ..... -80mA
Total Power Dissipation 500mW

Piezoelectric Horn Driver Absolute Maximum Ratings

Output Voltage ..... V_{SS}-0.3V to +18V
I_{OL} Total 200mA
I_{OH} Total ..... -200mA

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

D.C. Electrical Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency, pin load conditions, temperature and program instruction type, etc., can all exert an influence on the measured values.

Operating Voltage Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{DD}	Operating Voltage – HIRC	f_{SYS}=8MHz	2.2	—	5.5	V
	Operating Voltage – LIRC	f_{SYS}=32kHz	2.2	—	5.5	

Standby Current Characteristics

Ta=25°C, unless otherwise specified

Symbol	Standby Mode	Test Conditions		Min.	Typ.	Max.	Max. @85°C	Unit
		V_{DD}	Conditions					
I_{STB}	SLEEP Mode	2.2V	WDT on	—	1.2	2.4	2.9	μA
		3V		—	1.5	3.0	3.6	
		5V		—	3	5	6	
	IDLE0 Mode – LIRC	2.2V	f_{SUB} on	—	2.4	4.0	4.8	μA
		3V		—	3	5	6	
		5V		—	5	10	12	
	IDLE1 Mode – HIRC	2.2V	f_{SUB} on, f_{SYS}=8MHz	—	288	400	480	μA
		3V		—	360	500	600	
		5V		—	600	800	960	

Note: When using the characteristic table data, the following notes should be taken into consideration:
1. Any digital inputs are setup in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.
4. All Standby Current values are taken after a HALT instruction execution thus stopping all instruction execution.

Operating Current Characteristics

Ta=25°C

Symbol	Operating Mode	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{DD}	SLOW Mode – LIRC	2.2V	f_{SYS}=32kHz	—	8	16	μA
		3V		—	10	20	
		5V		—	30	50	
	FAST Mode – HIRC	2.2V	f_{SYS}=8MHz	—	0.6	1.0	mA
		3V		—	0.8	1.2	
		5V		—	1.6	2.4	

Note: When using the characteristic table data, the following notes should be taken into consideration:
1. Any digital inputs are setup in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.
4. All Operating Current values are measured using a continuous NOP instruction program loop.

A.C. Electrical Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency and temperature etc., can all exert an influence on the measured values.

High Speed Internal Oscillator – HIRC – Frequency Accuracy

During the program writing operation the writer will trim the HIRC oscillator at a user selected HIRC frequency and user selected voltage of either 3V or 5V.

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Temp.				
f_{HIRC}	8MHz Writer Trimmed HIRC Frequency	3V/5V	25°C	-1%	8	+1%	MHz
			-40°C~85°C	-2%	8	+2%	
		2.2V~5.5V	25°C	-2.5%	8	+2.5%	
			-40°C~85°C	-3%	8	+3%	

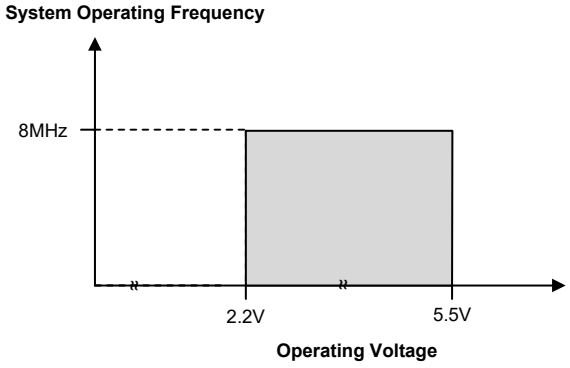
Note: 1. The 3V/5V values for V_{DD} are provided as these are the two selectable fixed voltages at which the HIRC frequency is trimmed by the writer.

2. The row below the 3V/5V trim voltage row is provided to show the values for the full V_{DD} range operating voltage. It is recommended that the trim voltage is fixed at 3V for application voltage ranges from 2.2V to 3.6V and fixed at 5V for application voltage ranges from 3.3V to 5.5V.

Low Speed Internal Oscillator Characteristics – LIRC

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Temp.				
f_{LIRC}	LIRC Frequency	2.2V~5.5V	-40°C~85°C	-7%	32	+7%	kHz
t_{START}	LIRC Start-up Time	—	25°C	—	—	100	μs

Operating Frequency Characteristics Curves



System Start Up Time Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
t_{SST}	System Start-up Time Wake-up from Condition Where f_{SYS} is Off	—	$f_{SYS}=f_H\sim f_H/64$, $f_H=f_{HIRC}$	—	16	—	t_{HIRC}
		—	$f_{SYS}=f_{SUB}=f_{LIRC}$	—	2	—	t_{LIRC}
	System Start-up Time Wake-up from Condition Where f_{SYS} is On	—	$f_{SYS}=f_H\sim f_H/64$, $f_H=f_{HIRC}$	—	2	—	t_H
		—	$f_{SYS}=f_{SUB}=f_{LIRC}$	—	2	—	t_{SUB}
	System Speed Switch Time FAST to SLOW Mode or SLOW to FAST Mode	—	f_{HIRC} switches from off → on	—	16	—	t_{HIRC}
t_{RSTD}	System Reset Delay Time Reset Source from Power-on Reset or LVR Hardware Reset	—	RR_{POR}=5V/ms	42	48	54	ms
	System Reset Delay Time WDTC/LVRC Software Reset	—	—				
	System Reset Delay Time Reset Source from WDT Overflow	—	—	14	16	18	ms
t_{SRESET}	Minimum Software Reset Width to Reset	—	—	45	90	120	μs

Note: 1. For the System Start-up time values, whether f_{SYS} is on or off depends upon the mode type and the chosen f_{SYS} system oscillator. Details are provided in the System Operating Modes section.
2. The time units, shown by the symbols t_{HIRC}, are the inverse of the corresponding frequency values as provided in the frequency tables. For example $t_{HIRC}=1/f_{HIRC}$, $t_{SYS}=1/f_{SYS}$ etc.
3. The System Speed Switch Time is effectively the time taken for the newly activated oscillator to start up.

Input/Output Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{IL}	Input Low Voltage for I/O Ports	5V	—	0	—	1.5	V
		—	—	0	—	$0.2V_{DD}$	
V_{IH}	Input High Voltage for I/O Ports	5V	—	3.5	—	5.0	V
		—	—	$0.8V_{DD}$	—	V_{DD}	
I_{OL}	Sink Current for I/O Pins	3V	$V_{OL}=0.1V_{DD}$	16	32	—	mA
		5V		32	65	—	
I_{OH}	Source Current for I/O Pins	3V	$V_{OH}=0.9V_{DD}$	-4	-8	—	mA
		5V		-8	-16	—	
R_{PH}	Pull-high Resistance for I/O Ports (1)	3V	—	20	60	100	kΩ
		5V	—	10	30	50	
I_{LEAK}	Input Leakage Current	5V	$V_{IN}=V_{DD}$ or $V_{IN}=V_{SS}$	—	—	±1	μA
t_{TCK}	PTM Clock Input Pin Minimum Pulse Width	—	—	0.3	—	—	μs
t_{TPI}	PTM Capture Input Pin Minimum Pulse Width	—	—	0.1	—	—	μs
t_{INT}	External Interrupt Minimum Pulse Width	—	—	10	—	—	μs
f_{TMCLK}	PTM Maximum Timer Clock Source Frequency	5V	—	—	—	1	f_{SYS}
t_{CPW}	PTM Minimum Capture Pulse Width	—	—	2	—	—	t_{TMCLK}

Note: 1. The R_{PH} internal pull high resistance value is calculated by connecting to ground and enabling input pin with pull-high resistor and then measuring the pin current at the specified supply voltage level. Dividing the voltage by this measured current provides the R_{PH} value.
2. $t_{TMCLK}=1/f_{TMCLK}$.
3. If PTCAPTS=0, then $t_{CPW}=\max(2\times t_{TMCLK}, t_{TPI,min})$; if PTCAPTS=1, then $t_{CPW}=\max(2\times t_{TMCLK}, t_{TCK,min})$.

Memory Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
Flash Program / Emulated EEPROM Memory							
V_{DD}	Operating Voltage	—	—	2.2	—	5.5	V
t_{DEW}	Erase / Write Time – Flash Program Memory	5V	—	—	2	3	ms
	Erase / Write Cycle Time – Emulated EEPROM Memory	—	EWRTS[1:0]=00B	—	2	3	ms
		—	EWRTS[1:0]=01B	—	4	6	
		—	EWRTS[1:0]=10B	—	8	12	
		—	EWRTS[1:0]=11B	—	16	24	
I_{DDPGM}	Programming / Erase Current on V_{DD}	5V	—	—	—	5.0	mA
E_P	Cell Endurance	—	—	10K	—	—	E/W
t_{RETD}	ROM Data Retention time	—	—	—	40	—	Year
RAM Data Memory							
V_{DD}	Operating Voltage for Read/Write	—	—	V_{DDmin}	—	V_{DDmax}	V
V_{DR}	RAM Data Retention Voltage	—	Device in SLEEP Mode	1.0	—	—	V

Note: 1. The Emulated EEPROM erase/write operation can only be executed when the f_{SYS} clock frequency is equal to or greater than 2MHz.
2. "E/W" means Erase/Write times.

Reference Voltage Electrical Characteristics

Ta=25°C, unless otherwise specified.

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{BGREF}	Bandgap Reference Voltage	—	Ta=-40°C~85°C	-1%	1.2	+1%	V
I_{BGREF}	Operating Current	5.5V	Ta=-40°C~85°C	—	25	40	μA
PSRR	Power Supply Rejection Ratio	—	V_{RIPPLE}=1V_{P-P}, f_{RIPPLE}=100Hz	75	—	—	dB
En	Output Noise	—	No load current, f=0.1Hz~10Hz	—	300	—	μV_{RMS}
I_{DRV}	Buffer Driving Capability	—	ΔV_{BGREF}=-1%	1	—	—	mA
I_{SD}	Shutdown Current	—	VBGREN=0	—	—	0.1	μA
t_{START}	Startup Time	2.2V~5.5V	—	—	—	400	μs

Note: 1. All the above parameters are measured under conditions of no load condition unless otherwise described.
2. A 0.1μF ceramic capacitor should be connected between VDD and ground.
3. The V_{BGREF} voltage can be used as the A/D converter signal input.

LVR Electrical Characteristics

Ta=25°C, unless otherwise specified.

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DD}	Operating voltage	—	—	1.65	—	5.50	V
V_{LVR}	Low Voltage Reset Voltage	—	LVR enable, voltage select 2.1V, Ta=-40°C~85°C	-5%	2.1	+5%	V
I_{LVR}	Additional Current for LVR Enable	3V	LVR enable, V_{LVR}=2.1V	—	—	15	μA
		5V		—	15	25	μA
t_{LVR}	Minimum Low Voltage Width to Reset	—	—	120	240	480	μs

Sink Current Generator Electrical Characteristics

Ta=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{SINK0}	Sink Current for ISINK0 Pin	5V	V_{ISINK0}=3.0V, ISGDATA0[4:0]=00000B	47.5	50.0	52.5	mA
		—	Ta=-40°C~85°C, V_{ISINK0}=1.0V~4.5V ISGDATA0[4:0]=00000B	41	50	59	
		—	Ta=-40°C~85°C, V_{ISINK0}=0.7V~1.0V ISGDATA0[4:0]=00000B	37.5	50.0	50.0	
		5V	V_{ISINK0}=3.0V, ISGDATA0[4:0]=11111B	330	360	390	
		—	Ta=-40°C~85°C, V_{ISINK0}=1.0V~4.5V ISGDATA0[4:0]=11111B	295	360	425	
		—	Ta=-40°C~85°C, V_{ISINK0}=0.7V~1.0V ISGDATA0[4:0]=11111B	270	360	360	
I_{SINK1}	Sink Current for ISINK1 Pin	5V	V_{ISINK1}=3.0V, ISGDATA1[4:0]=00000B	43.5	50.0	56.5	mA
		—	Ta=-40°C~85°C, V_{ISINK1}=1.0V~4.5V ISGDATA1[4:0]=00000B	41	50	59	
		—	Ta=-40°C~85°C, V_{ISINK1}=0.7V~1.0V ISGDATA1[4:0]=00000B	37.5	50.0	50.0	
		5V	V_{ISINK1}=3.0V, ISGDATA1[4:0]=11111B	178	205	231	
		—	Ta=-40°C~ 85°C, V_{ISINK1}=1.0V~4.5V ISGDATA1[4:0]=11111B	168	205	242	
		—	Ta=-40°C~85°C, V_{ISINK1}=0.7V~1.0V ISGDATA1[4:0]=11111B	154	205	205	

Operational Amplifier Electrical Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{OPA}	Operating Current	5V	SDAnBW [1:0]=00B, no load	—	3	5	μA
			SDAnBW [1:0]=01B, no load	—	10	16	
			SDAnBW [1:0]=10B, no load	—	80	128	
			SDAnBW [1:0]=11B, no load	—	200	320	
V_{OS}	Input Offset Voltage	5V	Without calibration (SDAnOF[5:0]=100000B)	-15	—	15	mV
			With calibration	-2	—	2	
I_{OS}	Input Offset Current	5V	V_{IN}=1/2V_{CM}	—	1	10	nA
V_{CM}	Common Mode Voltage Range	5V	SDAnBW [1:0]=00, 01, 10, 11	V_{SS}	—	V_{DD}-1.4	V
PSRR	Power Supply Rejection Ratio	5V	SDAnBW [1:0]=00, 01, 10, 11	50	70	—	dB
CMRR	Common Mode Rejection Ratio	5V	SDAnBW [1:0]=00, 01, 10, 11	50	80	—	dB
A_{OL}	Open Loop Gain	5V	SDAnBW [1:0]=00, 01, 10, 11	60	80	—	dB
SR	Slew Rate	5V	R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=00	0.5	1.5	—	V/ms
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=01	5	15	—	
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=10	180	500	—	
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=11	600	1800	—	

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
GBW	Gain Bandwidth	5V	R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=00	2.5	5.0	—	kHz
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=01	20	40	—	
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=10	400	600	—	
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=11	1300	2000	—	
V_{OR}	Maximum Output Voltage Range	5V	SDAnBW [1:0]=00, 01, R_{LOAD}=5kΩ to V_{DD}/2	V_{SS}+140	—	V_{DD}-160	mV
			SDAnBW [1:0]=10, 11, R_{LOAD}=5kΩ to V_{DD}/2	V_{SS}+120	—	V_{DD}-140	
I_{SC}	Output Short Circuit Current	5V	R_{LOAD}=5.1Ω, SDAnBW [1:0]=00,01	±6	±12	—	mA
			R_{LOAD}=5.1Ω, SDAnBW [1:0]=10,11	±10	±20	—	

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{OPA}	Operating Current	—	SDAnBW [1:0]=00B, no load	—	2.5	4.0	μA
			SDAnBW [1:0]=01B, no load	—	10	16	
			SDAnBW [1:0]=10B, no load	—	80	128	
			SDAnBW [1:0]=11B, no load	—	200	320	
V_{OS}	Input Offset Voltage	—	Without calibration (SDAnOF[5:0]=100000B)	-15	—	15	mV
			With calibration	-2	—	2	
I_{OS}	Input Offset Current	—	V_{IN}=1/2V_{CM}	—	1	10	nA
V_{CM}	Common Mode Voltage Range	—	SDAnBW [1:0]=00, 01, 10, 11	V_{SS}	—	V_{DD}-1.4	V
PSRR	Power Supply Rejection Ratio	—	SDAnBW [1:0]=00, 01, 10, 11	50	70	—	dB
CMRR	Common Mode Rejection Ratio	—	SDAnBW [1:0]=00, 01, 10, 11	50	80	—	dB
A_{OL}	Open Loop Gain	—	SDAnBW [1:0]=00, 01, 10, 11	60	80	—	dB
SR	Slew Rate	—	R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=00	0.5	1.5	—	V/ms
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=01	5	15	—	
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=10	180	500	—	
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=11	600	1800	—	
GBW	Gain Bandwidth	—	R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=00	2	5	—	kHz
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=01	15	40	—	
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=10	250	600	—	
			R_{LOAD}=1MΩ, C_{LOAD}=60pF, SDAnBW [1:0]=11	800	2000	—	
V_{OR}	Maximum Output Voltage Range	—	SDAnBW [1:0]=00, 01 R_{LOAD}=5kΩ to V_{DD}/2	V_{SS}+140	—	V_{DD}-160	mV
			SDAnBW [1:0]=10, 11 R_{LOAD}=5kΩ to V_{DD}/2	V_{SS}+120	—	V_{DD}-140	

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{SC}	Output Short Circuit current	—	R_{LOAD}=5.1Ω, SDAnBW [1:0]=00, 01	±1.2	±12	—	mA
			R_{LOAD}=5.1Ω, SDAnBW [1:0]=10, 11	±2	±20	—	

Note: These parameters are characterized but not tested.

A/D Converter Electrical Characteristics

Ta=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{ADI}	Input Voltage	—	—	0	—	V_{REF}	V
V_{REF}	Reference Voltage	—	—	2	—	AV_{DD}	V
N_R	Resolution	—	—	—	—	10	Bit
DNL	Differential Non-linearity	—	V_{REF}=AV_{DD}, t_{ADCK}=0.5μs Ta=-40°C~85°C	-1.5	—	+1.5	LSB
INL	Integral Non-linearity	—	V_{REF}=AV_{DD}, t_{ADCK}=0.5μs Ta=-40°C~85°C	-2	—	+2	LSB
I_{ADC}	Additional Current for ADC Enable	2.2V	No load (t_{ADCK}=0.5μs)	—	300	420	μA
		3V		—	340	500	
		5V		—	500	700	
t_{ADCK}	Clock Period	—	—	0.5	—	10.0	μs
t_{ON2ST}	ADC On-to-Start Time	—	—	4	—	—	μs
t_{ADC}	Conversion Time (Include ADC Sample and Hold Time)	—	—	—	14	—	t_{ADCK}

Piezoelectric Horn Driver Electrical Characteristics

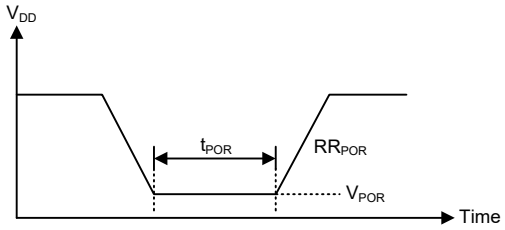
BDV_{DD}=V_{DD}=3V, V_{OUT}=12V, Ta=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		BDV_{DD}	Conditions				
Supply Voltage							
BDV_{DD}	Input Voltage Range	—	—	—	V_{DD}	—	V
I_{IN}	Supply Current	—	No load, boost converter enable, external-driving buzzer mode, f=4kHz	—	2	4	mA
I_{SHDN}	Shutdown Current	—	V_{ENB}=BDV_{DD}	—	0.5	1.0	μA
Boost Converter							
V_{OUT}	Output Voltage Range	—	—	10.8	12.0	13.2	V
I_{OCP}	Over Current Protection Current	—	—	—	0.95	—	A
f_{SW}	Switching Frequency	—	V_{OUT}=12V	0.8	1.0	1.2	MHz
Piezoelectric Horn Driver							
V_{IH}	High-Level Input Voltage	—	FB Pin	0.7V_{OUT}	—	V_{OUT}	V
			ENB Pin	0.7BDV_{DD}	—	BDV_{DD}	V
V_{IL}	Low-Level Input Voltage	—	FB Pin	0	—	0.3V_{OUT}	V
			ENB Pin	0	—	0.3BDV_{DD}	V
I_{OH}	Source Current for VB and VS Pins	—	V_{OUT}=12V, V_{OH}=0.9V_{OUT}	-120	-150	—	mA
I_{OL}	Sink Current for VB and VS Pins	—	V_{OUT}=12V, V_{OL}=0.1V_{OUT}	120	150	—	mA
I_{LEAK}	Input Leakage Current	—	V_{FB}=V_{OUT} or =V_{SS}	—	—	±0.1	μA
			V_{ENB}=BDV_{DD}	—	—	-0.1	μA
R_{PH}	Pull-high Resistance	—	ENB Pin	0.7	1.0	1.3	MΩ

Power-on Reset Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{POR}	V_{DD} Start Voltage to Ensure Power-on Reset	—	—	—	—	100	mV
RR_{POR}	V_{DD} Rising Rate to Ensure Power-on Reset	—	—	0.035	—	—	V/ms
t_{POR}	Minimum Time for V_{DD} Stays at V_{POR} to Ensure Power-on Reset	—	—	1	—	—	ms



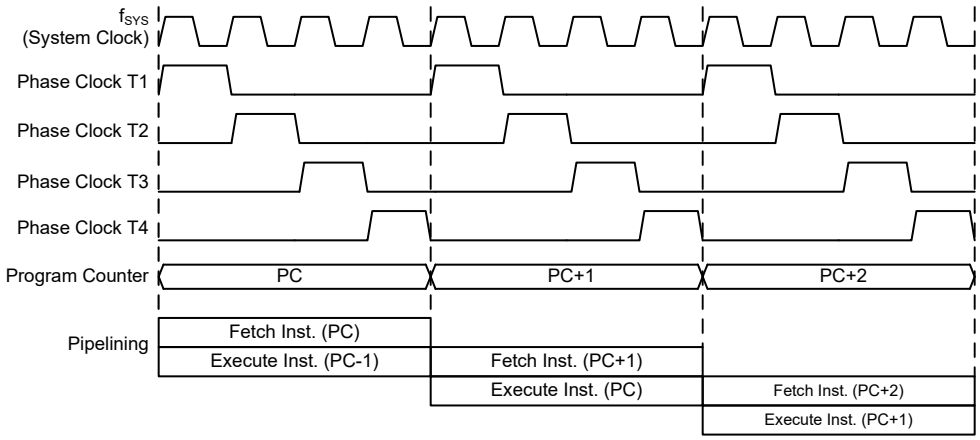
System Architecture

A key factor in the high-performance features of the range of microcontrollers is attributed to their internal system architecture. The device takes advantage of the usual features found within RISC microcontrollers providing increased speed of operation and enhanced performance. The pipelining scheme is implemented in such a way that instruction fetching and instruction execution are overlapped, hence instructions are effectively executed in one cycle, with the exception of branch or call instructions which need one more cycle. An 8-bit wide ALU is used in practically all instruction set operations, which carries out arithmetic operations, logic operations, rotation, increment, decrement, branch decisions, etc. The internal data path is simplified by moving data through the Accumulator and the ALU. Certain internal registers are implemented in the Data Memory and can be directly or indirectly addressed. The simple addressing methods of these registers along with additional architectural features ensure that a minimum of external components is required to provide a functional I/O and A/D control system with maximum reliability and flexibility. This makes the device suitable for low-cost, high-volume production for controller applications.

Clocking and Pipelining

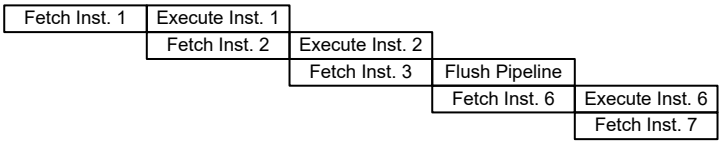
The main system clock, derived from either an HIRC or LIRC oscillator is subdivided into four internally generated non-overlapping clocks, T1~T4. The Program Counter is incremented at the beginning of the T1 clock during which time a new instruction is fetched. The remaining T2~T4 clocks carry out the decoding and execution functions. In this way, one T1~T4 clock cycle forms one instruction cycle. Although the fetching and execution of instructions takes place in consecutive instruction cycles, the pipelining structure of the microcontroller ensures that instructions are effectively executed in one instruction cycle. The exception to this are instructions where the contents of the Program Counter are changed, such as subroutine calls or jumps, in which case the instruction will take one more instruction cycle to execute.

For instructions involving branches, such as jump or call instructions, two machine cycles are required to complete instruction execution. An extra cycle is required as the program takes one cycle to first obtain the actual jump or call address and then another cycle to actually execute the branch. The requirement for this extra cycle should be taken into account by programmers in timing sensitive applications.



System Clocking and Pipelining

```
1          MOV A,[12H]
2          CALL DELAY
3          CPL [12H]
4          :
5          :
6  DELAY:  NOP
```



Instruction Fetching

Program Counter

During program execution, the Program Counter is used to keep track of the address of the next instruction to be executed. It is automatically incremented by one each time an instruction is executed except for instructions, such as "JMP" or "CALL" that demands a jump to a non-consecutive Program Memory address. Only the lower 8 bits, known as the Program Counter Low Register, are directly addressable by the application program.

When executing instructions requiring jumps to non-consecutive addresses such as a jump instruction, a subroutine call, interrupt or reset, etc., the microcontroller manages program control by loading the required address into the Program Counter. For conditional skip instructions, once the condition has been met, the next instruction, which has already been fetched during the present instruction execution, is discarded and a dummy cycle takes its place while the correct instruction is obtained.

Program Counter	
Program Counter High Byte	**PCL Register**
PC9~PC8	PCL7~PCL0

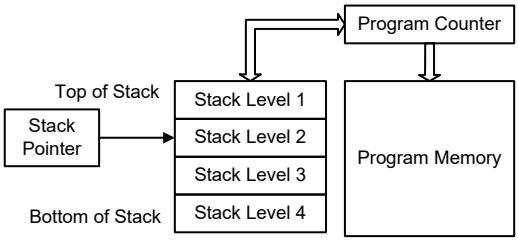
Program Counter

The lower byte of the Program Counter, known as the Program Counter Low register or PCL, is available for program control and is a readable and writeable register. By transferring data directly into this register, a short program jump can be executed directly. However, as only this low byte is available for manipulation, the jumps are limited to the present page of memory, that is 256 locations. When such program jumps are executed it should also be noted that a dummy cycle will be inserted. Manipulating the PCL register may cause program branching, so an extra cycle is needed to pre-fetch.

Stack

This is a special part of the memory which is used to save the contents of the Program Counter only. The stack is organized into 4 levels and neither part of the data nor part of the program space, and is neither readable nor writeable. The activated level is indexed by the Stack Pointer, and is neither readable nor writeable. At a subroutine call or interrupt acknowledge signal, the contents of the Program Counter are pushed onto the stack. At the end of a subroutine or an interrupt routine, signaled by a return instruction, RET or RETI, the Program Counter is restored to its previous value from the stack. After a device reset, the Stack Pointer will point to the top of the stack.

If the stack is full and an enabled interrupt takes place, the interrupt request flag will be recorded but the acknowledge signal will be inhibited. When the Stack Pointer is decremented, by RET or RETI, the interrupt will be serviced. This feature prevents stack overflow allowing the programmer to use the structure more easily. However, when the stack is full, a CALL subroutine instruction can still be executed which will result in a stack overflow. Precautions should be taken to avoid such cases which might cause unpredictable program branching. If the stack is overflow, the first Program Counter save in the stack will be lost.



Arithmetic and Logic Unit – ALU

The arithmetic-logic unit or ALU is a critical area of the microcontroller that carries out arithmetic and logic operations of the instruction set. Connected to the main microcontroller data bus, the ALU receives related instruction codes and performs the required arithmetic or logical operations after which the result will be placed in the specified register. As these ALU calculation or operations may result in carry, borrow or other status changes, the status register will be correspondingly updated to reflect these changes. The ALU supports the following functions:

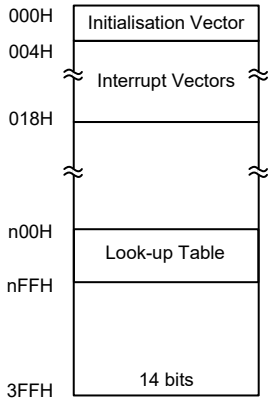
- Arithmetic operations:
  ADD, ADDM, ADC, ADCM, SUB, SUBM, SBC, SBCM, DAA
- Logic operations:
  AND, OR, XOR, ANDM, ORM, XORM, CPL, CPLA
- Rotation:
  RRA, RR, RRCA, RRC, RLA, RL, RLCA, RLC
- Increment and Decrement:
  INCA, INC, DECA, DEC
- Branch decision:
  JMP, SZ, SZA, SNZ, SIZ, SDZ, SIZA, SDZA, CALL, RET, RETI

Flash Program Memory

The Program Memory is the location where the user code or program is stored. For this device the Program Memory is Flash type, which means it can be programmed and re-programmed a large number of times, allowing the user the convenience of code modification on the same device. By using the appropriate programming tools, the Flash device offer users the flexibility to conveniently debug and develop their applications while also offering a means of field programming and updating.

Structure

The Program Memory has a capacity of 1K×14 bits. The Program Memory is addressed by the Program Counter and also contains data, table information and interrupt entries. Table data, which can be setup in any location within the Program Memory, is addressed by a separate table pointer register.



Program Memory Structure

Special Vectors

Within the Program Memory, certain locations are reserved for the reset and interrupts. The location 000H is reserved for use by the device reset for program initialisation. After a device reset is initiated, the program will jump to this location and begin execution.

Look-up Table

Any location within the Program Memory can be defined as a look-up table where programmers can store fixed data. To use the look-up table, the table pointer must first be setup by placing the address of the look up data to be retrieved in the table pointer register, TBLP. The register defines the total address of the look-up table.

After setting up the table pointer, the table data can be retrieved from the Program Memory using the “TABRD [m]” or “TABRDL [m]” instructions, respectively. When the instruction is executed, the lower order table byte from the Program Memory will be transferred to the user defined Data Memory register [m] as specified in the instruction. The higher order table data byte from the Program Memory will be transferred to the TBLH special register. Any unused bits in this transferred higher order byte will be read as 0.

The accompanying diagram illustrates the addressing data flow of the look-up table.

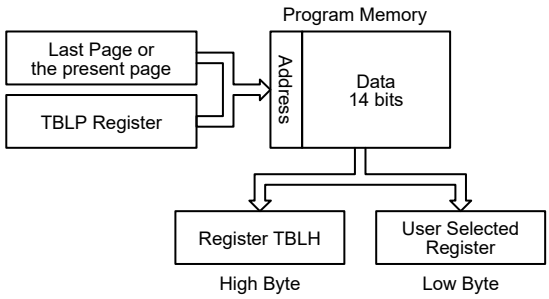


Table Program Example

The following example shows how the table pointer and table data is defined and retrieved from the microcontroller. This example uses raw table data located in the Program Memory which is stored there using the ORG statement. The value at this ORG statement is "300H" which refers to the start address of the last page within the 1K words Program Memory of the microcontroller. The table pointer low byte register is setup here to have an initial value of "06H". This will ensure that the first data read from the data table will be at the Program Memory address "306H" or 6 locations after the start of the last page. Note that the value for the table pointer is referenced to the specified address pointed by the TBLP register in the present page if the "TABRD [m]" instruction is being used. The high byte of the table data which in this case is equal to zero will be transferred to the TBLH register automatically when the "TABRD [m]" instruction is executed.

Because the TBLH register is a read-only register and cannot be restored, care should be taken to ensure its protection if both the main routine and Interrupt Service Routine use table read instructions. If using the table read instructions, the Interrupt Service Routines may change the value of the TBLH and subsequently cause errors if used again by the main routine. As a rule it is recommended that simultaneous use of the table read instructions should be avoided. However, in situations where simultaneous use cannot be avoided, the interrupts should be disabled prior to the execution of any main routine table-read instructions. Note that all table related instructions require two instruction cycles to complete their operation.

Table Read Program Example

```
tempreg1 db ?      ; temporary register #1
tempreg2 db ?      ; temporary register #2
:
mov a, 06h         ; initialise low table pointer - note that this address is referenced
mov tblp, a        ; to the last page or present page
:
tabrdl tempreg1    ; transfers value in table referenced by table pointer data at program
                   ; memory address "306H" transferred to tempreg1 and TBLH
dec tblp           ; reduce value of table pointer by one
tabrdl tempreg2    ; transfers value in table referenced by table pointer data at program
                   ; memory address "305H" transferred to tempreg2 and TBLH in this
                   ; example the data 1AH is transferred to tempreg1 and data "0FH" to
                   ; register tempreg2
                   ; the value "00H" will be transferred to the high byte register TBLH
:
org 300h           ; sets initial address of program memory
dc 00Ah, 00Bh, 00Ch, 00Dh, 00Eh, 00Fh, 01Ah, 01Bh
:
```

In Circuit Programming – ICP

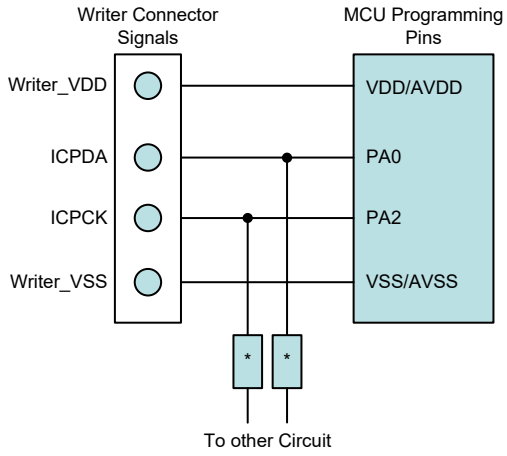
The provision of Flash type Program Memory provides the user with a means of convenient and easy upgrades and modifications to their programs on the same device. As an additional convenience, Holtek has provided a means of programming the microcontroller in-circuit using a 4-pin interface. This provides manufacturers with the possibility of manufacturing their circuit boards complete with a programmed or un-programmed microcontroller, and then programming or upgrading the program at a later stage. This enables product manufacturers to easily keep their manufactured products supplied with the latest program releases without removal and re-insertion of the device.

The Holtek Flash MCU to Writer Programming Pin correspondence table is as follows:

Holtek Writer Pins	MCU Programming Pins	Pin Description
ICPDA	PA0	Programming Serial Data/Address
ICPCK	PA2	Programming Clock
VDD	VDD/AVDD	Power Supply
VSS	VSS/AVSS	Ground

The Program Memory can be programmed serially in-circuit using this 4-wire interface. Data is downloaded and uploaded serially on a single pin with an additional line for the clock. Two additional lines are required for the power supply. The technical details regarding the in-circuit programming of the device are beyond the scope of this document and will be supplied in supplementary literature.

During the programming process, taking control of the ICPDA and ICPCK pins for data and clock programming purposes. The user must there take care to ensure that no other outputs are connected to these two pins.



Note: * may be resistor or capacitor. The resistance of * must be greater than 1kΩ or the capacitance of * must be less than 1nF.

On-Chip Debug Support – OCDS

An EV chip exists for the purposes of device emulation. This EV chip device also provides an "On-Chip Debug" function to debug the device during the development process. The EV chip and the real MCU device are almost functionally compatible except for the "On-Chip Debug" function. Users can use the EV chip device to emulate the real chip device behavior by connecting the OCDSDA and OCDSCK pins to the Holtek HT-IDE development tools. The OCDSDA pin is the OCDS Data/Address input/output pin while the OCDSCK pin is the OCDS clock input pin. When users use the EV chip for debugging, other functions which are shared with the OCDSDA and OCDSCK pins

will have no effect in the EV chip. For a more detailed OCDS description, refer to the corresponding document named “Holtek e-Link for 8-bit MCU OCDS User's Guide”.

Holtek e-Link Pins	EV Chip Pins	Pin Description
OCDSDA	OCDSDA	On-chip Debug Support Data/Address input/output
OCDSCK	OCDSCK	On-chip Debug Support Clock input
VDD	VDD/AVDD	Power Supply
VSS	VSS/AVSS	Ground

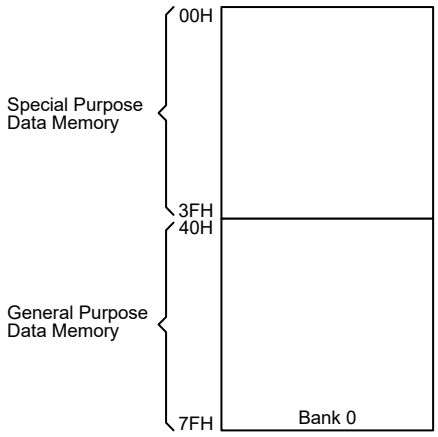
RAM Data Memory

The Data Memory is a volatile area of 8-bit wide RAM internal memory and is the location where temporary information is stored.

Structure

Categorized into two types, the first of these is an area of RAM, known as the Special Function Data Memory. These registers have fixed locations and are necessary for correct operation of the device. Many of these registers can be read from and written to directly under program control, however, some remain protected from user manipulation. The second area of Data Memory is known as the General Purpose Data Memory, which is reserved for general purpose use. All locations within this area are read and write accessible under program control.

The start address of the Data Memory for the device is the address 00H. The address range of the Special Purpose Data Memory for the device is from 00H to 3FH while the address range of the General Purpose Data Memory is from 40H to 7FH.



Data Memory Structure

General Purpose Data Memory

All microcontroller programs require an area of read/write memory where temporary data can be stored and retrieved for use later. It is this area of RAM memory that is known as General Purpose Data Memory. This area of Data Memory is fully accessible by the user programing for both reading and writing operations. By using the bit operation instructions individual bits can be set or reset under program control giving the user a large range of flexibility for bit manipulation in the Data Memory.

Special Purpose Data Memory

This area of Data Memory is where registers, necessary for the correct operation of the microcontroller, are stored. Most of the registers are both readable and writeable but some are protected and are readable only, the details of which are located under the relevant Special Function Register section. Note that for locations that are unused, any read instruction to these addresses will return the value “00H”.

	Bank 0
00H	IAR0
01H	MP0
02H	IAR1
03H	MP1
04H	
05H	ACC
06H	PCL
07H	TBLP
08H	TBLH
09H	
0AH	STATUS
0BH	VBGRC
0CH	
0DH	
0EH	
0FH	RSTFC
10H	TB0C
11H	TB1C
12H	SCC
13H	HIRCC
14H	PA
15H	PAC
16H	PAPU
17H	PAWU
18H	PSCR
19H	SDSW
1AH	SDPGAC0
1BH	SDPGAC1
1CH	SDA0C
1DH	SDA0VOS
1EH	SDA1C
1FH	SDA1VOS

	Bank 0
20H	SADOL
21H	SADOH
22H	SADC0
23H	SADC1
24H	INTEG
25H	INTC0
26H	INTC1
27H	LVRC
28H	
29H	PAS0
2AH	PTMC0
2BH	PTMC1
2CH	PTMC2
2DH	PTMDL
2EH	PTMDH
2FH	PTMAL
30H	PTMAH
31H	PTMBL
32H	PTMBH
33H	PTMRPL
34H	PTMRPH
35H	ISGENC
36H	ISGDATA0
37H	ISGDATA1
38H	ECR
39H	EAR
3AH	EDL
3BH	EDH
3CH	
3DH	WDTC
3EH	
3FH	

: Unused, read as 00H

Special Purpose Data Memory

Special Function Register Description

Most of the Special Function Register details will be described in the relevant functional sections; however several registers require a separate description in this section.

Indirect Addressing Register – IAR0, IAR1

The Indirect Addressing Registers, IAR0 and IAR1, although having their locations in normal RAM register space, do not actually physically exist as normal registers. The method of indirect addressing for RAM data manipulation uses these Indirect Addressing Registers and Memory Pointers, in contrast to direct memory addressing, where the actual memory address is specified. Actions on the IAR0 and IAR1 registers will result in no actual read or write operation to these registers but rather to the memory location specified by their corresponding Memory Pointers, MP0 or MP1. Acting as a pair, IAR0 and MP0 can together access data from Bank 0 while the IAR1 and MP1 register pair can access data from any bank. As the Indirect Addressing Registers are not physically implemented, reading the Indirect Addressing Registers indirectly will return a result of "00H" and writing to the registers indirectly will result in no operation.

Memory Pointers – MP0, MP1

Two Memory Pointers, known as MP0 and MP1 are provided. These Memory Pointers are physically implemented in the Data Memory and can be manipulated in the same way as normal registers providing a convenient way with which to address and track data. When any operation to the relevant Indirect Addressing Registers is carried out, the actual address that the microcontroller is directed to, is the address specified by the related Memory Pointer.

The following example shows how to clear a section of four Data Memory locations already defined as locations adres1 to adres4.

Indirect Addressing Program Example

```
data .section   'data'
adres1   db ?
adres2   db ?
adres3   db ?
adres4   db ?
block    db ?
code .section at   0 code
org 00h
start:
mov a, 04h            ; setup size of block
mov block, a
mov a, offset adres1   ; Accumulator loaded with first RAM address
mov mp0, a            ; setup memory pointer with first RAM address
loop:
clr IAR0              ; clear the data at address defined by MP0
inc mp0               ; increment memory pointer
sdz block             ; check if last memory location has been cleared
jmp loop
continue:
```

The important point to note here is that in the example shown above, no reference is made to specific Data Memory addresses.

Accumulator – ACC

The Accumulator is central to the operation of any microcontroller and is closely related with operations carried out by the ALU. The Accumulator is the place where all intermediate results from the ALU are stored. Without the Accumulator it would be necessary to write the result of each calculation or logical operation such as addition, subtraction, shift, etc., to the Data Memory resulting in higher programming and timing overheads. Data transfer operations usually involve the temporary storage function of the Accumulator; for example, when transferring data between one user defined register and another, it is necessary to do this by passing the data through the Accumulator as no direct transfer between two registers is permitted.

Program Counter Low Byte Register – PCL

To provide additional program control functions, the low byte of the Program Counter is made accessible to programmers by locating it within the Special Purpose area of the Data Memory. By manipulating this register, direct jumps to other program locations are easily implemented. Loading a value directly into this PCL register will cause a jump to the specified Program Memory location, however, as the register is only 8-bit wide, only jumps within the current Program Memory page are permitted. When such operations are used, note that a dummy cycle will be inserted.

Look-up Table Registers – TBLP, TBLH

These two special function registers are used to control operation of the look-up table which is stored in the Program Memory. TBLP is the table pointer and indicates the location where the table data is located. The value must be setup before any table read commands are executed. The value can be changed, for example using the “INC” or “DEC” instructions, allowing for easy table data pointing and reading. TBLH is the location where the high order byte of the table data is stored after a table read data instruction has been executed. Note that the lower order table data byte is transferred to a user defined location.

Status Register – STATUS

This 8-bit register contains the zero flag (Z), carry flag (C), auxiliary carry flag (AC), overflow flag (OV), power down flag (PDF), and watchdog time-out flag (TO). These arithmetic/logical operation and system management flags are used to record the status and operation of the microcontroller.

With the exception of the TO and PDF flags, bits in the status register can be altered by instructions like most other registers. Any data written into the status register will not change the TO or PDF flag. In addition, operations related to the status register may give different results due to the different instruction operations. The TO flag can be affected only by a system power-up, a WDT time-out or by executing the “CLR WDT” or “HALT” instruction. The PDF flag is affected only by executing the “HALT” or “CLR WDT” instruction or during a system power-up.

The Z, OV, AC and C flags generally reflect the status of the latest operations.

- C is set if an operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation; otherwise C is cleared. C is also affected by a rotate through carry instruction.
- AC is set if an operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction; otherwise AC is cleared.
- Z is set if the result of an arithmetic or logical operation is zero; otherwise Z is cleared.
- OV is set if an operation results in a carry into the highest-order bit but not a carry out of the highest-order bit, or vice versa; otherwise OV is cleared.

- PDF is cleared by a system power-up or executing the “CLR WDT” instruction. PDF is set by executing the “HALT” instruction.
- TO is cleared by a system power-up or executing the “CLR WDT” or “HALT” instruction. TO is set by a WDT time-out.

In addition, on entering an interrupt sequence or executing a subroutine call, the status register will not be pushed onto the stack automatically. If the contents of the status registers are important and if the subroutine can corrupt the status register, precautions must be taken to correctly save it.

• STATUS Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	TO	PDF	OV	Z	AC	C
R/W	—	—	R	R	R/W	R/W	R/W	R/W
POR	—	—	0	0	x	x	x	x

“x”: Unknown

Bit 7~6 Unimplemented, read as “0”

Bit 5 **TO**: Watchdog Time-Out flag
0: After power up or executing the “CLR WDT” or “HALT” instruction
1: A watchdog time-out occurred.

Bit 4 **PDF**: Power down flag
0: After power up or executing the “CLR WDT” instruction
1: By executing the “HALT” instruction

Bit 3 **OV**: Overflow flag
0: No overflow
1: An operation results in a carry into the highest-order bit but not a carry out of the highest-order bit or vice versa.

Bit 2 **Z**: Zero flag
0: The result of an arithmetic or logical operation is not zero
1: The result of an arithmetic or logical operation is zero

Bit 1 **AC**: Auxiliary flag
0: No auxiliary carry
1: An operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction

Bit 0 **C**: Carry flag
0: No carry-out
1: An operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation

The C flag is also affected by a rotate through carry instruction.

Emulated EEPROM Data Memory

The device contains an Emulated EEPROM Data Memory, which is by its nature a non-volatile form of re-programmable memory, with data retention even when its power supply is removed. By incorporating this kind of data memory, a whole new host of application possibilities are made available to the designer. The availability of the Emulated EEPROM storage allows information such as product identification numbers, calibration values, specific user data, system setup data or other product information to be stored directly within the product microcontroller.

Emulated EEPROM Data Memory Structure

The Emulated EEPROM Data Memory capacity is 32×14 bits for the device. The Emulated EEPROM Erase operation is carried out in a page format while the Write and Read operations are carried out in a word format. The page size is assigned with a capacity of 16 words. Note that the Erase operation should be executed before the Write operation is executed.

Operations	Format
Erase	16 words/page
Write	1 word/time
Read	1 word/time
Note: Page size = 16 words.	

Emulated EEPROM Erase/Write/Read Format

Erase Page	EAR4	EAR[3:0]
0	0	xxxx
1	1	xxxx

"x": don't care

Erase Page Number and Selection

Emulated EEPROM Registers

Four registers control the overall operation of the Emulated EEPROM Data Memory. These are the address register, EAR, the data registers, EDL and EDH, and a single control register, ECR.

Register Name	Bit							
	7	6	5	4	3	2	1	0
EAR	—	—	—	EAR4	EAR3	EAR2	EAR1	EAR0
EDL	D7	D6	D5	D4	D3	D2	D1	D0
EDH	—	—	D13	D12	D11	D10	D9	D8
ECR	EWRTS1	EWRTS0	EEREN	EER	EWREN	EWR	ERDEN	ERD

Emulated EEPROM Register List

- **EAR Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	EAR4	EAR3	EAR2	EAR1	EAR0
R/W	—	—	—	R/W	R/W	R/W	R/W	R/W
POR	—	—	—	0	0	0	0	0

Bit 7~5 Unimplemented, read as "0"

Bit 4~0 **EAR4~EAR0**: Emulated EEPROM address bit 4 ~ bit 0

• **EDL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: Emulated EEPROM data bit 7 ~ bit 0

• **EDH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	D13	D12	D11	D10	D9	D8
R/W	—	—	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

Bit 7~6 Unimplemented, read as "0"

Bit 5~0 **D13~D8**: Emulated EEPROM data bit 13 ~ bit 8

• **ECR Register**

Bit	7	6	5	4	3	2	1	0
Name	EWRTS1	EWRTS0	EEREN	EER	EWREN	EWR	ERDEN	ERD
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **EWRTS1~EWRTS0**: Emulated EEPROM Erase/Write time selection
00: 2ms
01: 4ms
10: 8ms
11: 16ms

Bit 5 **EEREN**: Emulated EEPROM Erase enable
0: Disable
1: Enable
This bit is used to enable the Emulated EEPROM erase function and must be set high before erase operations are carried out. This bit will be automatically reset to zero by the hardware after the erase cycle has finished. Clearing this bit to zero will inhibit the Emulated EEPROM erase operations.

Bit 4 **EER**: Emulated EEPROM Erase control
0: Erase cycle has finished
1: Activate an erase cycle
When this bit is set high by the application program, an erase cycle will be activated. This bit will be automatically reset to zero by the hardware after the erase cycle has finished. Setting this bit high will have no effect if the EEREN has not first been set high.

Bit 3 **EWREN**: Emulated EEPROM Write enable
0: Disable
1: Enable
This bit is used to enable the Emulated EEPROM write function and must be set high before write operations are carried out. This bit will be automatically reset to zero by the hardware after the write cycle has finished. Clearing this bit to zero will inhibit the Emulated EEPROM write operations.

Bit 2 **EWR**: Emulated EEPROM Write control
0: Write cycle has finished
1: Activate a write cycle
When this bit is set high by the application program, a write cycle will be activated. This bit will be automatically reset to zero by the hardware after the write cycle has finished. Setting this bit high will have no effect if the EWREN has not first been set high.

Bit 1 **ERDEN**: Emulated EEPROM Read enable
0: Disable
1: Enable
This bit is used to enable the Emulated EEPROM read function and must be set high before read operations are carried out. Clearing this bit to zero will inhibit the Emulated EEPROM read operations.

Bit 0 **ERD**: Emulated EEPROM Read control
0: Read cycle has finished
1: Activate a read cycle
When this bit is set high by the application program, a read cycle will be activated. This bit will be automatically reset to zero by the hardware after the read cycle has finished. Setting this bit high will have no effect if the ERDEN has not first been set high.

Note: 1. The EEREN, EER, EWREN, EWR, ERDEN and ERD cannot be set to "1" at the same time in one instruction.
2. Note that the CPU will be stopped when a read, write or erase operation is successfully activated.
3. Ensure that the f_{SYS} clock frequency is equal to or greater than 2MHz and the f_{SUB} clock is stable before executing the erase or write operation.
4. Ensure that the read, write or erase operation is totally complete before executing other operations.

Erasing the Emulated EEPROM

For Emulated EEPROM erase operation the desired erase page address should first be placed in the EAR register. The number of the page erase operation is 16 words per page, therefore, the available page erase address is only specified by the EAR4 bit in the EAR register and the content of EAR3~EAR0 in the EAR register is not used to specify the page address. To erase the Emulated EEPROM page, the EEREN bit in the ECR register must first be set high to enable the erase function. After this the EER bit in the ECR register must be immediately set high to initiate an erase cycle. These two instructions must be executed in two consecutive instruction cycles to activate an erase operation successfully. The global interrupt bit EMI should also first be cleared before implementing any erase operations, and then set high again after the a valid erase activation procedure has completed. Note that the CPU will be stopped when an erase operation is successfully activated. When the erase cycle terminates, the CPU will resume executing the application program. And the EER bit will be automatically cleared to zero by the microcontroller, informing the user that the data has been erased. The Emulated EEPROM erased page content will all be zero after an erase operation.

Writing Data to the Emulated EEPROM

For Emulated EEPROM write operation the data and desired write address should first be placed in the EDH/EDL and EAR registers respectively. To write data to the Emulated EEPROM, the EWREN bit in the ECR register must first be set high to enable the write function. After this the EWR bit in the ECR register must be immediately set high to initiate a write cycle. These two instructions must be executed in two consecutive instruction cycles to activate a write operation successfully. The global interrupt bit EMI should also first be cleared before implementing any write operations, and then set high again after a valid write activation procedure has completed. Note that the CPU will be stopped when a write operation is successfully activated. When the write cycle terminates, the CPU will resume executing the application program. And the EWR bit will be automatically cleared to zero by the microcontroller, informing the user that the data has been written to the Emulated EEPROM.

Reading Data from the Emulated EEPROM

For Emulated EEPROM read operation the desired read address should first be placed in the EAR register. To read data from the Emulated EEPROM, the ERDEN bit in the ECR register must first be set high to enable the read function. After this a read cycle will be initiated if the ERD bit in the ECR register is now set high. Note that the CPU will be stopped when the read operation is successfully activated. When the read cycle terminates, the CPU will resume executing the application program. And the ERD bit will be automatically cleared to zero by the microcontroller, informing the user that the data has been read from the Emulated EEPROM. Then the data can be read from the EDH/EDL data register pair by application program. The data will remain in the data register pair until another read, write or erase operation is executed.

Programming Considerations

Care must be taken that data is not inadvertently written to the Emulated EEPROM. Protection can be enhanced by ensuring that the Write Enable bit is normally cleared to zero when not writing. Although certainly not necessary, consideration might be given in the application program to the checking of the validity of new write data by a simple read back process. When writing or erasing data the EWR or EER bit must be set high immediately after the EWREN or EEREN bit has been set high, to ensure the write or erase cycle executes correctly. The global interrupt bit EMI should also be cleared before a write or erase cycle is executed and then set again after a valid write or erase activation procedure has completed. Note that the device should not enter the IDLE or SLEEP mode until Emulated EEPROM read, write or erase operation is totally complete. Otherwise, Emulated EEPROM read, write or erase operation will fail.

Programming Examples

Erase a Data Page of the Emulated EEPROM – polling method

```
MOV A, EEPROM_ADRES       ; user-defined page
MOV EAR, A
MOV  A, 00H               ; Erase time=2ms (40H for 4ms, 80H for 8ms, C0H for 16ms)
MOV  ECR, A
CLR  EMI
SET  EEREN                ; set EEREN bit, enable erase operation
SET  EER                  ; start Erase Cycle - set EER bit - executed immediately
                          ; after setting EEREN bit
SET  EMI
BACK:
SZ   EER                  ; check for erase cycle end
JMP  BACK
:
```

Writing Data to the Emulated EEPROM – polling method

```
MOV  A, EEPROM_ADRES      ; user defined address
MOV  EAR, A
MOV  A, EEPROM_DATA_L     ; user defined data
MOV  EDL, A
MOV  A, EEPROM_DATA_H
MOV  EDH, A
MOV  A, 00H               ; Write time=2ms (40H for 4ms, 80H for 8ms, C0H for 16ms)
MOV  ECR, A
CLR  EMI
SET  EWREN                ; set EWREN bit, enable write operation
SET  EWR                  ; start Write Cycle - set EWR bit - executed immediately
                          ; after set EWREN bit
```

```
SET  EMI
BACK:
SZ   EWR                ; check for write cycle end
JMP  BACK
:
```

Reading Data from the Emulated EEPROM – polling method

```
MOV  A, EEPROM_ADRES     ; user defined address
MOV  EAR, A
SET  ERDEN               ; set ERDEN bit, enable read operation
SET  ERD                 ; start Read Cycle - set ERD bit
BACK:
SZ   ERD                 ; check for read cycle end
JMP  BACK
CLR  ECR                 ; disable Emulated EEPROM read if no more read operations
                         ; are required
MOV  A, EDL              ; move read data to register
MOV  READ_DATA_L, A
MOV  A, EDH
MOV  READ_DATA_H, A
```

Note: For each read operation, the address register should be re-specified followed by setting the ERD bit high to activate a read cycle even if the target address is consecutive.

Oscillators

Various oscillator options offer the user a wide range of functions according to their various application requirements. The flexible features of the oscillator functions ensure that the best optimisation can be achieved in terms of speed and power saving. Oscillator selections and operation are selected through the application program by using relevant control registers.

Oscillator Overview

In addition to being the source of the main system clock the oscillators also provide clock sources for the Watchdog Timer. Fully integrated internal oscillators, requiring no external components, are provided to form a wide range of both fast and slow system oscillators. All oscillator options are selected through registers. The higher frequency oscillator provides higher performance but carry with it the disadvantage of higher power requirements, while the opposite is of course true for the lower frequency oscillator. With the capability of dynamically switching between fast and slow system clock, the device has the flexibility to optimize the performance/power ratio, a feature especially important in power sensitive portable applications.

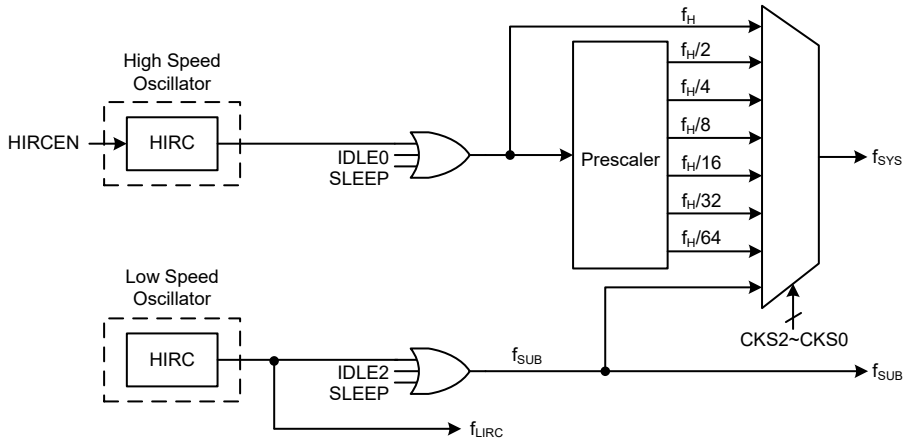
Type	Name	Frequency
Internal High Speed RC	HIRC	8MHz
Internal Low Speed RC	LIRC	32kHz

Oscillator Types

System Clock Configurations

There are two methods of generating the system clock, one high speed oscillator and one low speed oscillator. The high speed oscillator is the internal 8MHz RC oscillator, HIRC. The low speed oscillator is the internal 32kHz RC oscillator, LIRC. Selecting whether the low or high speed oscillator is used as the system oscillator is implemented using the CKS2~CKS0 bits in the SCC register and as the system clock can be dynamically selected.

Note that two oscillator selections must be made namely one high speed and one low speed system oscillator. It is not possible to choose a no-oscillator selection for either the high or low speed oscillator.



System Clock Configurations

Internal RC Oscillator – HIRC

The internal RC oscillator is a fully integrated system oscillator requiring no external components. The internal RC oscillator has a fixed frequencies of 8MHz. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised.

Internal 32kHz Oscillator – LIRC

The Internal 32kHz System Oscillator is the low frequency oscillator. It is a fully integrated RC oscillator with a typical frequency of 32kHz, requiring no external components for its implementation. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised.

Operating Modes and System Clocks

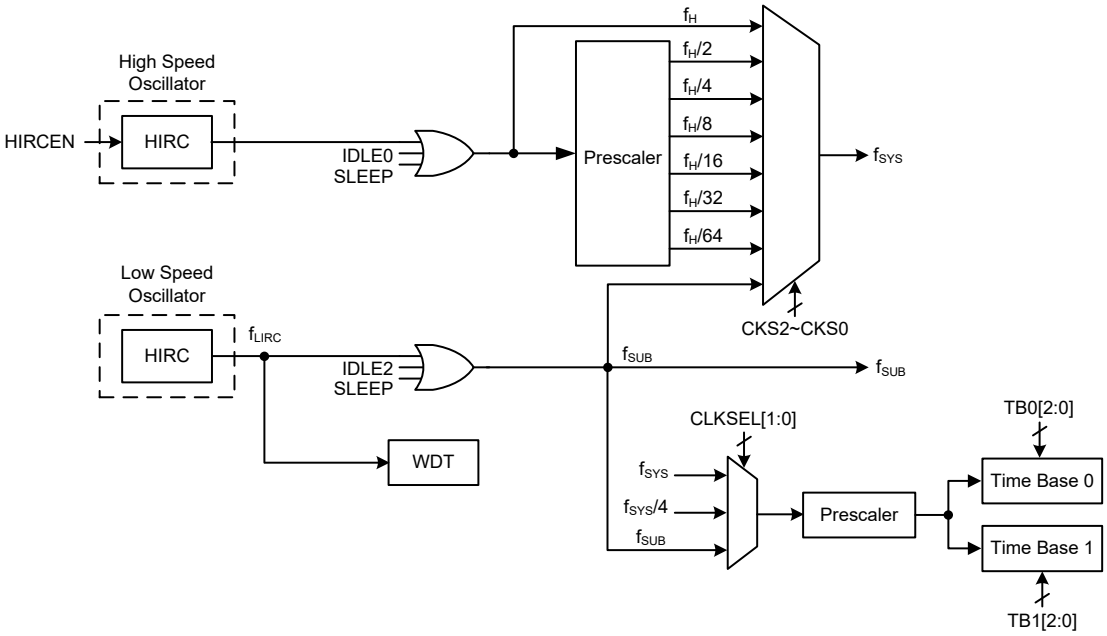
Present day applications require that their microcontrollers have high performance but often still demand that they consume as little power as possible, conflicting requirements that are especially true in battery powered portable applications. The fast clocks required for high performance will by their nature increase current consumption and of course vice versa, lower speed clocks reduce current consumption. As both high and low speed clock sources are provided the means to switch between them dynamically, the user can optimise the operation of their microcontroller to achieve the best performance/power ratio.

System Clocks

The device has different clock sources for both the CPU and peripheral function operation. By providing the user with a wide range of clock selections using register programming, a clock system can be configured to obtain maximum application performance.

The main system clock, can come from either a high frequency, f_H, or low frequency, f_{SUB}, source, and is selected using the CKS2~CKS0 bits in the SCC register. The high speed system clock is

sourced from the HIRC oscillator. The low speed system clock source can be sourced from the internal clock f_{SUB}. If f_{SUB} is selected then it is sourced from the LIRC oscillator. The other choice, which is a divided version of the high speed system oscillator has a range of $f_H/2$~$f_H/64$.



Device Clock Configurations

Note: When the system clock source f_{SYS} is switched to f_{SUB} from f_H, the high speed oscillator can be stopped to conserve the power or continue to oscillate to provide the clock source, f_H~$f_H/64$, for peripheral circuit to use.

System Operation Modes

There are six different modes of operation for the microcontroller, each one with its own special characteristics and which can be chosen according to the specific performance and power requirements of the application. There are two modes allowing normal operation of the microcontroller, the FAST Mode and SLOW Mode. The remaining four modes, the SLEEP, IDLE0, IDLE1 and IDLE2 Mode are used when the microcontroller CPU is switched off to conserve power.

Operation Mode	CPU	Register Setting			f_{SYS}	f_H	f_{SUB}	f_{LIRC}
		FHIDEN	FSIDEN	CKS2~CKS0				
FAST	On	x	x	000~110	f_H~$f_H/64$	On	On	On
SLOW	On	x	x	111	f_{SUB}	On/Off (1)	On	On
IDLE0	Off	0	1	000~110	Off	Off	On	On
				111	On			
IDLE1	Off	1	1	xxx	On	On	On	On
IDLE2	Off	1	0	000~110	On	On	Off	On
				111	Off			
SLEEP	Off	0	0	xxx	Off	Off	Off	On(2)

"x": Don't care

Note:1. The f_H clock will be switched on or off by configuring the corresponding oscillator enable bit in the SLOW mode.

2. The f_{LIRC} clock will be switched on since the WDT function is always enabled even in the SLEEP mode.

FAST Mode

This is one of the main operating modes where the microcontroller has all of its functions operational and where the system clock is provided by the high speed oscillator. This mode operates allowing the microcontroller to operate normally with a clock source will come from the HIRC oscillator. The high speed oscillator will however first be divided by a ratio ranging from 1 to 64, the actual ratio being selected by the CKS2~CKS0 bits in the SCC register. Although a high speed oscillator is used, running the microcontroller at a divided clock ratio reduces the operating current.

SLOW Mode

This is also a mode where the microcontroller operates normally although now with a slower speed clock source. The clock source used will be from f_{SUB}. The f_{SUB} clock is derived from the LIRC oscillator.

SLEEP Mode

The SLEEP Mode is entered when a HALT instruction is executed and when the FHIDEN and FSIDEN bit are low. In the SLEEP mode the CPU will be stopped, and the f_{SUB} clock to peripheral will be stopped too. However the f_{LIRC} clock will continue to operate since the WDT function is always enabled.

IDLE0 Mode

The IDLE0 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is low and the FSIDEN bit in the SCC register is high. In the IDLE0 Mode the CPU will be switched off but the low speed oscillator will be turned on to drive some peripheral functions.

IDLE1 Mode

The IDLE1 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is high. In the IDLE1 Mode the CPU will be switched off but both the high and low speed oscillators will be turned on to provide a clock source to keep some peripheral functions operational.

IDLE2 Mode

The IDLE2 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is low. In the IDLE2 Mode the CPU will be switched off but the high speed oscillator will be turned on to provide a clock source to keep some peripheral functions operational.

Control Registers

The registers, SCC and HIRCC, are used to control the system clock and the corresponding oscillator configurations.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SCC	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
HIRCC	—	—	—	—	—	—	HIRCF	HIRCEN

System Operating Mode Control Register List

• **SCC Register**

Bit	7	6	5	4	3	2	1	0
Name	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
R/W	R/W	R/W	R/W	—	—	—	R/W	R/W
POR	0	0	0	—	—	—	0	0

Bit 7~5 **CKS2~CKS0**: System clock selection
000: f_H
001: $f_H/2$
010: $f_H/4$
011: $f_H/8$
100: $f_H/16$
101: $f_H/32$
110: $f_H/64$
111: f_{SUB}
These three bits are used to select which clock is used as the system clock source. In addition to the system clock source directly derived from f_H or f_{SUB}, a divided version of the high speed system oscillator can also be chosen as the system clock source.

Bit 4~2 Unimplemented, read as "0"

Bit 1 **FHIDEN**: High Frequency oscillator control when CPU is switched off
0: Disable
1: Enable
This bit is used to control whether the high speed oscillator is activated or stopped when the CPU is switched off by executing an "HALT" instruction.

Bit 0 **FSIDEN**: Low Frequency oscillator control when CPU is switched off
0: Disable
1: Enable
This bit is used to control whether the low speed oscillator is activated or stopped when the CPU is switched off by executing an "HALT" instruction.

Note: A certain delay is required before the relevant clock is successfully switched to the target clock source after any clock switching setup using the CKS2~CKS0 bits . A proper delay time must be arranged before executing the following operations which require immediate reaction with the target clock source.

Clock switching delay time = $4\times t_{SYS} + [0\sim(1.5\times t_{Curr.}+0.5\times t_{Tar.})]$, where $t_{Curr.}$ indicates the current clock period, $t_{Tar.}$ indicates the target clock period and t_{SYS} indicates the current system clock period.

• **HIRCC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	HIRCF	HIRCEN
R/W	—	—	—	—	—	—	R	R/W
POR	—	—	—	—	—	—	0	1

Bit 7~2 Unimplemented, read as "0"

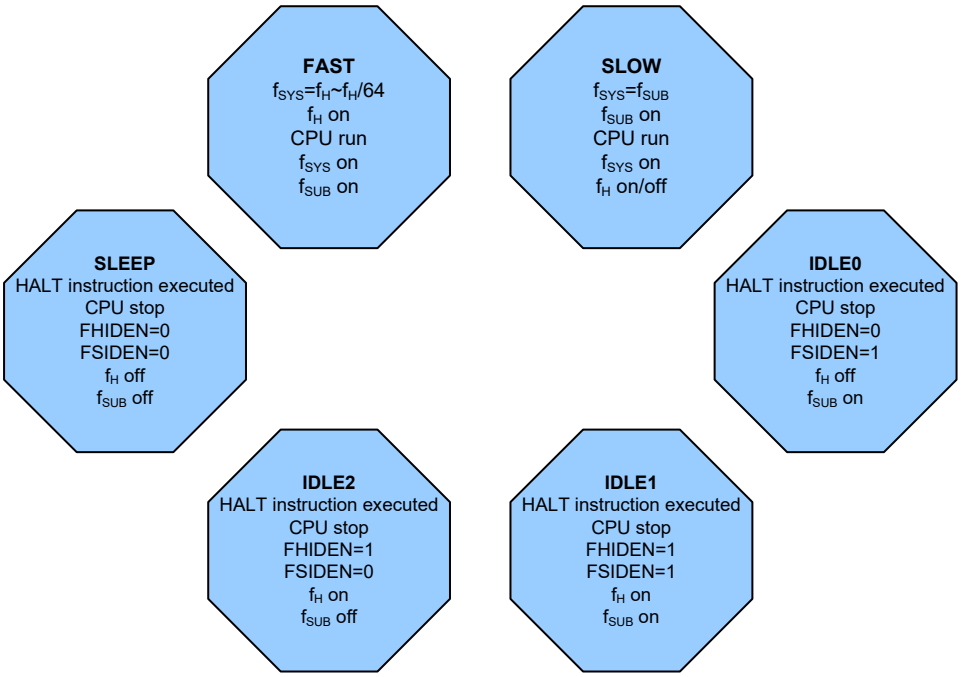
Bit 1 **HIRCF**: HIRC oscillator stable flag
0: HIRC unstable
1: HIRC stable
This bit is used to indicate whether the HIRC oscillator is stable or not. When the HIRCEN bit is set to 1 to enable the HIRC oscillator or the HIRC frequency selection is changed by application program, the HIRCF bit will first be cleared to 0 and then set to 1 after the HIRC oscillator is stable.

Bit 0 **HIRCEN**: HIRC oscillator enable control
0: Disable
1: Enable

Operating Mode Switching

The device can switch between operating modes dynamically allowing the user to select the best performance/power ratio for the present task in hand. In this way microcontroller operations that do not require high performance can be executed using slower clocks thus requiring less operating current and prolonging battery life in portable applications.

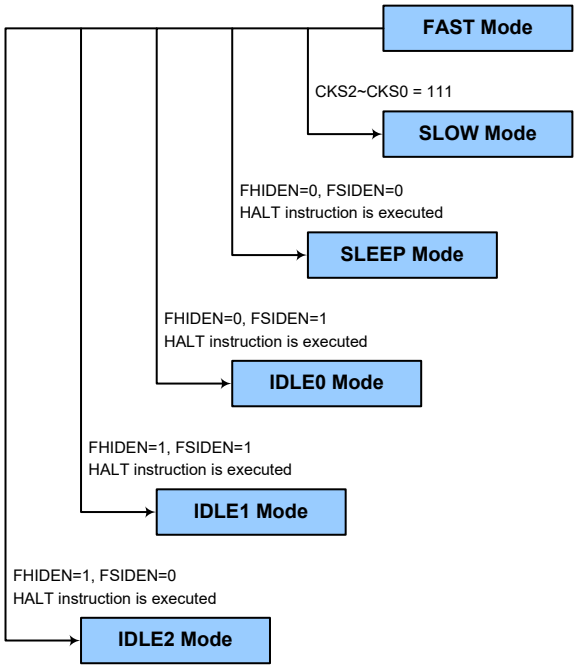
In simple terms, Mode Switching between the FAST Mode and SLOW Mode is executed using the CKS2~CKS0 bits in the SCC register while Mode Switching from the FAST/SLOW Modes to the SLEEP/IDLE Modes is executed via the HALT instruction. When a HALT instruction is executed, whether the device enters the IDLE Mode or the SLEEP Mode is determined by the condition of the FHIDEN and FSIDEN bits in the SCC register.



FAST Mode to SLOW Mode Switching

When running in the FAST Mode, which uses the high speed system oscillator, and therefore consumes more power, the system clock can switch to run in the SLOW Mode by set the CKS2~CKS0 bits to “111” in the SCC register. This will then use the low speed system oscillator which will consume less power. Users may decide to do this for certain operations which do not require high performance and can subsequently reduce power consumption.

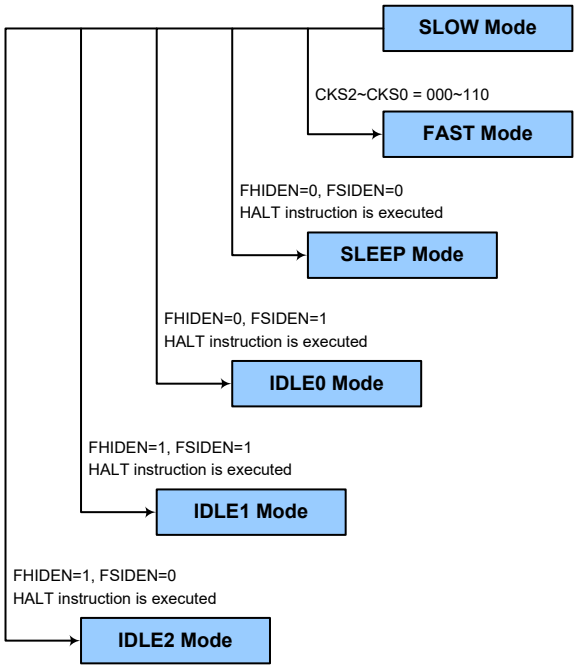
The SLOW Mode is sourced from the LIRC oscillator and therefore requires the oscillator to be stable before full mode switching occurs.



SLOW Mode to FAST Mode Switching

In SLOW mode the system clock is derived from f_{SUB}. When system clock is switched back to the FAST mode from f_{SUB}, the CKS2~CKS0 bits should be set to "000"~"110" and then the system clock will respectively be switched to f_H~f_H/64.

However, if f_H is not used in SLOW mode and thus switched off, it will take some time to re-oscillate and stabilise when switching to the FAST mode from the SLOW Mode. This is monitored using the HIRCF bit in the HIRCC register. The time duration required for the high speed system oscillator stabilization is specified in the relevant characteristics.



Entering the SLEEP Mode

There is only one way for the device to enter the SLEEP Mode and that is to execute the "HALT" instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to "0". In this mode all the clocks and functions will be switched off except the WDT function. When this instruction is executed under the conditions described above, the following will occur:

- The system clock will be stopped and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

Entering the IDLE0 Mode

There is only one way for the device to enter the IDLE0 Mode and that is to execute the "HALT" instruction in the application program with the FHIDEN bit in the SCC register equal to "0" and the FSIDEN bit in the SCC register equal to "1". When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be stopped and the application program will stop at the "HALT" instruction, but the f_{SUB} clock will be on.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

Entering the IDLE1 Mode

There is only one way for the device to enter the IDLE1 Mode and that is to execute the "HALT" instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to "1". When this instruction is executed under the conditions described above, the following will occur:

- The f_H and f_{SUB} clocks will be on but the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

Entering the IDLE2 Mode

There is only one way for the device to enter the IDLE2 Mode and that is to execute the "HALT" instruction in the application program with the FHIDEN bit in the SCC register equal to "1" and the FSIDEN bit in the SCC register equal to "0". When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be on but the f_{SUB} clock will be off and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

Standby Current Considerations

As the main reason for entering the SLEEP or IDLE Mode is to keep the current consumption of the device to as low a value as possible, perhaps only in the order of several micro-amps except in the IDLE1 and IDLE2 Mode, there are other considerations which must also be taken into account by the circuit designer if the power consumption is to be minimised. Special attention must be made to the I/O pins on the device. All high-impedance input pins must be connected to either a fixed high or low level as any floating input pins could create internal oscillations and result in increased current consumption. This also applies to devices which have different package types, as there may be unbonbed pins. These must either be setup as outputs or if setup as inputs must have pull-high resistors connected.

Care must also be taken with the loads, which are connected to I/O pins, which are setup as outputs. These should be placed in a condition in which minimum current is drawn or connected only to external circuits that do not draw current, such as other CMOS inputs.

In the IDLE1 and IDLE2 Mode the high speed oscillator is on, if the peripheral function clock source is derived from the high speed oscillator, the additional standby current will also be perhaps in the order of several hundred micro-amps.

Wake-up

To minimise power consumption the device can enter the SLEEP or any IDLE Mode, where the CPU will be switched off. However, when the device is woken up again, it will take a considerable time for the original system oscillator to restart, stablise and allow normal operation to resume.

After the system enters the SLEEP or IDLE Mode, it can be woken up from one of various sources listed as follows:

- An external falling edge on Port A
- A system interrupt
- A WDT overflow

When the device executes the “HALT” instruction, the PDF flag will be set to 1. The PDF flag will be cleared to 0 if the device experiences a system power-up or executes the clear Watchdog Timer instruction. If the system is woken up by a WDT overflow, a Watchdog Timer reset will be initiated and the TO flag will be set to 1. The TO flag is set if a WDT time-out occurs and causes a wake-up that only resets the Program Counter and Stack Pointer, other flags remain in their original status.

Each pin on Port A can be setup using the PAWU register to permit a negative transition on the pin to wake up the system. When a Port A pin wake-up occurs, the program will resume execution at the instruction following the “HALT” instruction. If the system is woken up by an interrupt, then two possible situations may occur. The first is where the related interrupt is disabled or the interrupt is enabled but the stack is full, in which case the program will resume execution at the instruction following the “HALT” instruction. In this situation, the interrupt which woke up the device will not be immediately serviced, but will rather be serviced later when the related interrupt is finally enabled or when a stack level becomes free. The other situation is where the related interrupt is enabled and the stack is not full, in which case the regular interrupt response takes place. If an interrupt request flag is set high before entering the SLEEP or IDLE Mode, the wake-up function of the related interrupt will be disabled.

Watchdog Timer

The Watchdog Timer is provided to prevent program malfunctions or sequences from jumping to unknown locations, due to certain uncontrollable external events such as electrical noise.

Watchdog Timer Clock Source

The Watchdog Timer clock source is provided by the internal clock, f_{LIRC}, which is sourced from the LIRC oscillator. The LIRC internal oscillator has an approximate period of 32kHz and this specified internal clock period can vary with V_{DD}, temperature and process variations. The Watchdog Timer source clock is then subdivided by a ratio of 2^8 to 2^{18} to give longer timeouts, the actual value being chosen using the WS2~WS0 bits in the WDTC register.

Watchdog Timer Control Register

A single register, WDTC, controls the required timeout period as well as the enable and reset MCU operation.

• **WDTC Register**

Bit	7	6	5	4	3	2	1	0
Name	WE4	WE3	WE2	WE1	WE0	WS2	WS1	WS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	0	0	1	1

Bit 7~3 **WE4~WE0**: WDT function software control
10101 or 01010: Enable
Other: Reset MCU
When these bits are changed by the environmental noise or software setting to reset the microcontroller, the reset operation will be activated after a delay time, t_{SRESET}, and the WRF bit in the RSTFC register will be set to 1.

Bit 2~0 **WS2~WS0**: WDT time-out period selection
000: $2^8/f_{LIRC}$
001: $2^{10}/f_{LIRC}$
010: $2^{12}/f_{LIRC}$
011: $2^{14}/f_{LIRC}$
100: $2^{15}/f_{LIRC}$
101: $2^{16}/f_{LIRC}$
110: $2^{17}/f_{LIRC}$
111: $2^{18}/f_{LIRC}$

• **RSTFC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

Bit 7~3 Unimplemented, read as "0"

Bit 2 **LVRF**: LVR function reset flag
Refer to the Low Voltage Reset section.

Bit 1 **LRF**: LVR control register software reset flag
Refer to the Low Voltage Reset section.

Bit 0 **WRF**: WDT Control register software reset flag
0: Not occured
1: Occurred
This bit is set to 1 by the WDT Control register software reset and cleared to 0 by the application program. Note that this bit can only be cleared to 0 by the application program.

Watchdog Timer Operation

The Watchdog Timer operates by providing a device reset when its timer overflows. This means that in the application program and during normal operation the user has to strategically clear the Watchdog Timer before it overflows to prevent the Watchdog Timer from executing a reset. This is done using the clear watchdog instruction. If the program malfunctions for whatever reason, jumps to an unknown location, or enters an endless loop, the clear instruction will not be executed in the correct manner, in which case the Watchdog Timer will overflow and reset the device. There are five bits, WE4~WE0, in the WDTC register to offer additional enable and reset control of the Watchdog Timer. If the WE4~WE0 bits value are equal to 01010B or 10101B, the WDT function is enabled. However, if the WE4~WE0 bits are changed to any other values except 01010B and 10101B, which could be caused by adverse environmental conditions such as noise, it will reset the device after a delay time, t_{SRESET}. After power on these bits will have a value of 01010B.

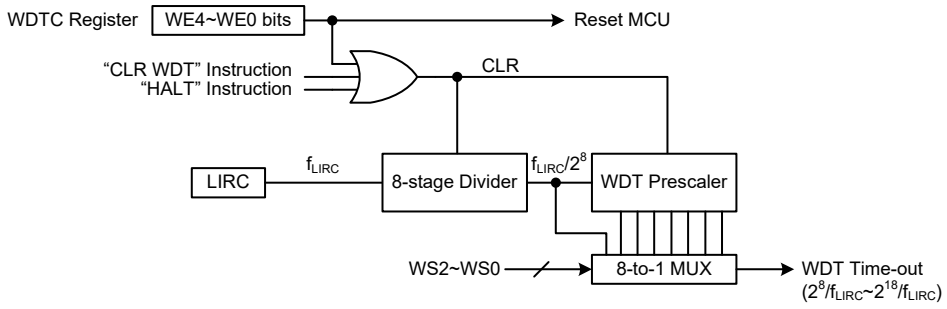
WE4~WE0 Bits	WDT Function
01010B or 10101B	Enable
Any other value	Reset MCU

Watchdog Timer Function Control

Under normal program operation, a Watchdog Timer time-out will initialise a device reset and set the status bit TO. However, if the system is in the SLEEP or IDLE Mode, when a Watchdog Timer time-out occurs, the TO bit in the status register will be set and only the Program Counter and Stack Pointer will be reset. Three methods can be adopted to clear the contents of the Watchdog Timer. The first is a WDT software reset, which means a certain value except 01010B and 10101B written into the WE4~WE0 bit filed, the second is using the Watchdog Timer software clear instruction and the third is via a HALT instruction.

There is only one method of using software instruction to clear the Watchdog Timer. That is to use the single "CLR WDT" instruction to clear the WDT.

The maximum time out period is when the 2^{18} division ratio is selected. As an example, with a 32kHz LIRC oscillator as its source clock, this will give a maximum watchdog period of around 8 seconds for the 2^{18} division ratio, and a minimum timeout of 8ms for the 2^8 division ratio.



Watchdog Timer

Reset and Initialisation

A reset function is a fundamental part of any microcontroller ensuring that the device can be set to some predetermined condition irrespective of outside parameters. The most important reset condition is after power is first applied to the microcontroller. In this case, internal circuitry will ensure that the microcontroller, after a short delay, will be in a well-defined state and ready to execute the first program instruction. After this power-on reset, certain important internal registers will be set to defined states before the program commences. One of these registers is the Program Counter, which will be reset to zero forcing the microcontroller to begin program execution from the lowest Program Memory address.

Another reset exists in the form of a Low Voltage Reset, LVR, where a full reset is implemented in situations where the power supply voltage falls below a certain threshold.

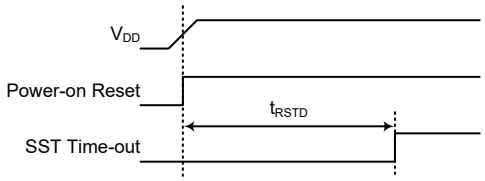
Another type of reset is when the Watchdog Timer overflows and resets the micricontroller. All types of reset operations result in different register conditions being setup.

Reset Functions

There are several ways in which a reset can occur, each of which will be described as follows.

Power-on Reset

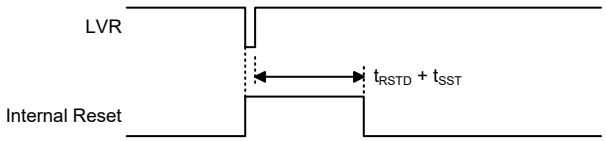
The most fundamental and unavoidable reset is the one that occurs after power is first applied to the microcontroller. As well as ensuring that the Program Memory begins execution from the first memory address, a power-on reset also ensures that certain other registers are preset to known conditions. All the I/O port and port control registers will power up in a high condition ensuring that all I/O ports will be first set to inputs.



Power-On Reset Timing Chart

Low Voltage Reset – LVR

The microcontroller contains a low voltage reset circuit in order to monitor the supply voltage of the device and provides an MCU reset should the value fall below a certain predefined level. If the supply voltage of the device drops to within a range of 0.9V~V_{LVR} such as might occur when changing the battery in battery powered applications, the LVR will automatically reset the device internally and the LVRF bit in the RSTFC register will also be set high. For a valid LVR signal, a low supply voltage, i.e., a voltage in the range between 0.9V~V_{LVR} must exist for a time greater than that specified by t_{LVR} in the LVR characteristics. If the low supply voltage state does not exceed this value, the LVR will ignore the low supply voltage and will not perform a reset function. If the LVS7~LVS0 bits are set to 01011010B, the LVR function is enabled with a fixed LVR voltage of 2.1V. If the LVS7~LVS0 bits are set to 10100101B, the LVR function is disabled. If the LVS7~LVS0 bits are changed to some different values by environmental noise, the LVR will reset the device after a delay time, t_{SRESET}. When this happens, the LRF bit in the RSTFC register will be set high. After power on the register will have the value of 01011010B. Note that the LVR function will be automatically disabled when the device enters the IDLE or SLEEP mode.



Low Voltage Reset Timing Chart

- **LVRC Register**

Bit	7	6	5	4	3	2	1	0
Name	LVS7	LVS6	LVS5	LVS4	LVS3	LVS2	LVS1	LVS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	1	0	1	0

Bit 7~0 **LVS7~LVS0**: LVR voltage select control
01011010: 2.1V
10100101: disable
Any other value: Generates MCU reset – register is reset to POR value

When an actual low voltage condition occurs, as specified above, an MCU reset will be generated. The reset operation will be activated after the low voltage condition keeps more than a t_{LVR} time. In this situation the register contents will remain the same after such a reset occurs.

Any register value, other than 01011010B and 10100101B, will also result in the generation of an MCU reset. The reset operation will be activated after a delay time, t_{SRESET}. However in this situation the register contents will be reset to the POR value.

- **RSTFC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

"x": unknown

Bit 7~3 Unimplemented, read as "0"

Bit 2 **LVRF**: LVR function reset flag
0: Not occurred
1: Occurred

This bit is set high when a specific Low Voltage Reset situation condition occurs. This bit can only be cleared to zero by the application program.

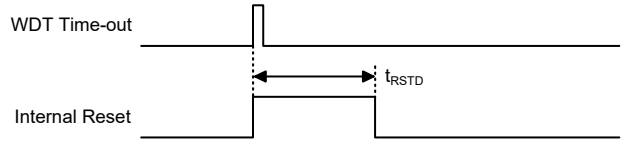
Bit 1 **LRF**: LVR control register software reset flag
0: Not occurred
1: Occurred

This bit is set high if the LVRC register contains any non-defined LVRC register values. This in effect acts like a software-reset function. This bit can only be cleared to zero by the application program.

Bit 0 **WRF**: WDT control register software reset flag
Refer to the Watchdog Timer Control Register section.

Watchdog Time-out Reset during Normal Operation

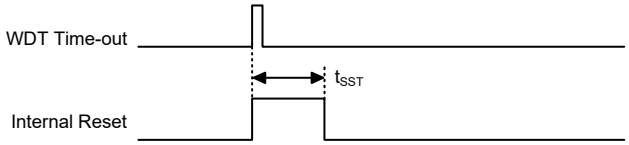
When the Watchdog time-out Reset during normal operation occurs, the Watchdog time-out flag TO will be set to "1".



WDT Time-out Reset during Normal Operation Timing Chart

Watchdog Time-out Reset during SLEEP or IDLE Mode

The Watchdog time-out Reset during SLEEP or IDLE Mode is a little different from other kinds of reset. Most of the conditions remain unchanged except that the Program Counter and the Stack Pointer will be cleared to "0" and the TO flag will be set to "1". Refer to the System Start Up Time Characteristics for t_{SST} details.



WDT Time-out Reset during SLEEP or IDLE Timing Chart

Reset Initial Conditions

The different types of reset described affect the reset flags in different ways. These flags, known as PDF and TO are located in the status register and are controlled by various microcontroller operations, such as the SLEEP or IDLE Mode function or Watchdog Timer. The reset flags are shown in the table:

TO	PDF	Reset Conditions
0	0	Power-on reset
u	u	LVR reset during FAST or SLOW Mode operation
1	u	WDT time-out reset during FAST or SLOW Mode operation
1	1	WDT time-out reset during IDLE or SLEEP Mode operation

"u": Unchanged

The following table indicates the way in which the various components of the microcontroller are affected after a power-on reset occurs.

Item	Condition after Reset
Program Counter	Reset to zero
Interrupts	All interrupts will be disabled
WDT, Time Bases	Clear after reset, WDT begins counting
Timer Module	Timer Module will be turned off
Input/Output Ports	I/O ports will be setup as inputs
Stack Pointer	Stack Pointer will point to the top of the stack

The different kinds of resets all affect the internal registers of the microcontroller in different ways. To ensure reliable continuation of normal program execution after a reset occurs, it is important to know what condition the microcontroller is in after a particular reset occurs. The following table describes how each type of reset affects each of the microcontroller internal registers.

Register	Reset (Power On)	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
IAR0	xxxx xxxx	uuuu uuuu	uuuu uuuu
MP0	xxxx xxxx	uuuu uuuu	uuuu uuuu
IAR1	xxxx xxxx	uuuu uuuu	uuuu uuuu
MP1	xxxx xxxx	uuuu uuuu	uuuu uuuu
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	0000 0000
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBLH	--xx xxxx	--uu uuuu	--uu uuuu
STATUS	--00 xxxx	--1u uuuu	--11 uuuu
VBGRC	---- ---0	---- ---0	---- ---u
RSTFC	---- -x00	---- -uuu	---- -uuu
TB0C	0--- -000	0--- -000	u--- -uuu
TB1C	0--- -000	0--- -000	u--- -uuu
SCC	000- --00	000- --00	uuu- --uu
HIRCC	---- --01	---- --01	---- --uu
PA	---- 1111	---- 1111	---- uuuu
PAC	---- 1111	---- 1111	---- uuuu
PAPU	---- 0000	---- 0000	---- uuuu
PAWU	---- 0000	---- 0000	---- uuuu
PSCR	---- --00	---- --00	---- --uu
SDSW	-000 0000	-000 0000	-uuu uuuu
SDPGAC0	--00 0000	--00 0000	--uu uuuu
SDPGAC1	0000 0000	0000 0000	uuuu uuuu
SDA0C	-00- --00	-00- --00	-uu- --uu
SDA0VOS	0010 0000	0010 0000	uuuu uuuu
SDA1C	-00- --00	-00- --00	-uu- --uu
SDA1VOS	0010 0000	0010 0000	uuuu uuuu
SADOL	xx-- ----	xx-- ----	uu-- ----(ADRFS=0)
			uuuu uuuu(ADRFS=1)
SADOH	xxxx xxxx	xxxx xxxx	uuuu uuuu(ADRFS=0)
			---- --uu(ADRFS=1)
SADC0	0000 0000	0000 0000	uuuu uuuu
SADC1	0000 0000	0000 0000	uuuu uuuu
INTEG	---- --00	---- --00	---- --uu
INTC0	-000 0000	-000 0000	-uuu uuuu
INTC1	-000 -000	-000 -000	-uuu -uuu
LVRC	0101 1010	0101 1010	uuuu uuuu
PAS0	0000 0000	0000 0000	uuuu uuuu
PTMC0	0000 0---	0000 0---	uuuu u---
PTMC1	0000 0000	0000 0000	uuuu uuuu
PTMC2	---- -000	---- -000	---- -uuu
PTMDL	0000 0000	0000 0000	uuuu uuuu
PTMDH	---- --00	---- --00	---- --uu
PTMAL	0000 0000	0000 0000	uuuu uuuu
PTMAH	---- --00	---- --00	---- --uu
PTMBL	0000 0000	0000 0000	uuuu uuuu
PTMBH	---- --00	---- --00	---- --uu

Register	Reset (Power On)	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
PTMRPL	0000 0000	0000 0000	uuuu uuuu
PTMRPH	---- --00	---- --00	---- --uu
ISGENC	0--- --00	0--- --00	u--- --uu
ISGDATA0	---0 0000	---0 0000	---u uuuu
ISGDATA1	---0 0000	---0 0000	---u uuuu
WDTC	0101 0011	0101 0011	uuuu uuuu
ECR	0000 0000	0000 0000	uuuu uuuu
EAR	---0 0000	---0 0000	---u uuuu
EDL	0000 0000	0000 0000	uuuu uuuu
EDH	--00 0000	--00 0000	--uu uuuu

Note: "u" stands for unchanged
"x" stands for unknown
"-" stands for unimplemented

Input/Output Ports

Holtek microcontrollers offer considerable flexibility on their I/O ports. With the input or output designation of every pin fully under user program control, pull-high selections for all ports and wake-up selections on certain pins, the user is provided with an I/O structure to meet the needs of a wide range of application possibilities.

The device provides bidirectional input/output lines labeled with port names PA. These I/O ports are mapped to the RAM Data Memory with specific addresses as shown in the Special Purpose Data Memory table. All of these I/O ports can be used for input and output operations. For input operation, these ports are non-latching, which means the inputs must be ready at the T2 rising edge of instruction "MOV A, [m]", where m denotes the port address. For output operation, all the data is latched and remains unchanged until the output latch is rewritten.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PA	—	—	—	—	PA3	PA2	PA1	PA0
PAC	—	—	—	—	PAC3	PAC2	PAC1	PAC0
PAPU	—	—	—	—	PAPU3	PAPU2	PAPU1	PAPU0
PAWU	—	—	—	—	PAWU3	PAWU2	PAWU1	PAWU0

"—": Unimplemented, read as "0"

I/O Logic Function Register List

Pull-high Resistors

Many product applications require pull-high resistors for their switch inputs usually requiring the use of an external resistor. To eliminate the need for these external resistors, all I/O pins, when configured as an input have the capability of being connected to an internal pull-high resistor. These pull-high resistors are selected using registers PAPU and are implemented using weak PMOS transistors.

Note that the pull-high resistor can be controlled by the relevant pull-high control register only when the pin-shared functional pin is selected as a digital input or NMOS output. Otherwise, the pull-high resistors cannot be enabled.

• **PAPU Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	PAPU3	PAPU2	PAPU1	PAPU0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3~0 **PAPU3~PAPU0**: I/O Port PA3~PA0 pin pull-high function control
0: Disable
1: Enable

Port A Wake-up

The HALT instruction forces the microcontroller into the SLEEP or IDLE Mode which preserves power, a feature that is important for battery and other low-power applications. Various methods exist to wake-up the microcontroller, one of which is to change the logic condition on one of the Port A pins from high to low. This function is especially suitable for applications that can be woken up via external switches. Each pin on Port A can be selected individually to have this wake-up feature using the PAWU register.

Note that the wake-up function can be controlled by the wake-up control registers only when the pin is selected as a general purpose input and the MCU enters the IDLE or SLEEP mode.

• **PAWU Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	PAWU3	PAWU2	PAWU1	PAWU0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3~0 **PAWU3~PAWU0**: I/O Port PA3~PA0 pin Wake-up Control
0: Disable
1: Enable

I/O Port Control Registers

The I/O port has its own control register known as PAC, to control the input/output configuration. With this control register, each CMOS output or input can be reconfigured dynamically under software control. Each pin of the I/O ports is directly mapped to a bit in its associated port control register. For the I/O pin to function as an input, the corresponding bit of the control register must be written as a "1". This will then allow the logic state of the input pin to be directly read by instructions. When the corresponding bit of the control register is written as a "0", the I/O pin will be setup as a CMOS output. If the pin is currently setup as an output, instructions can still be used to read the output register. However, it should be noted that the program will in fact only read the status of the output data latch and not the actual logic status of the output pin.

• **PAC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	PAC3	PAC2	PAC1	PAC0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	1	1	1	1

Bit 7~4 Unimplemented, read as "0"

Bit 3~0 **PAC3~PAC0**: I/O Port PA3~PA0 pin type selection
0: Output
1: Input

Sink Current Generator

The sink current source generator could provide constant current no matter what V_{ISINK} voltage is ranging from 1.0V to 4.5V. The constant current value is controlled by the ISGDATA0/ISGDATA1 register, and the sink current range is 50mA~360mA.

• ISGENC Register

Bit	7	6	5	4	3	2	1	0
Name	ISGEN	—	—	—	—	—	ISGS1	ISGS0
R/W	R/W	—	—	—	—	—	R/W	R/W
POR	0	—	—	—	—	—	0	0

Bit 7 **ISGEN**: Sink current generator enable control
0: Disable
1: Enable
When ISGEN = 0, the ISINK0 and ISINK1 pin status will be $V_{ISINK0\&1}=V_{DD}$, $I_{SINK0\&1}=0$.

Bit 6~2 Unimplemented, read as "0"

Bit 1 **ISGS1**: ISINK1 pin sink current enable control
0: Disable
1: Enable

Bit 0 **ISGS0**: ISINK0 pin sink current enable control
0: Disable
1: Enable

• ISGDATA0 Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	D4	D3	D2	D1	D0
R/W	—	—	—	R/W	R/W	R/W	R/W	R/W
POR	—	—	—	0	0	0	0	0

Bit 7~5 Unimplemented, read as "0"

Bit 4~0 **D4~D0**: Sink current generator control for ISINK0 pin
Current value (mA)=50+10×D[4:0]
Refer to "Sink Current Generator Electrical Characteristics" table for more details.

• ISGDATA1 Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	D4	D3	D2	D1	D0
R/W	—	—	—	R/W	R/W	R/W	R/W	R/W
POR	—	—	—	0	0	0	0	0

Bit 7~5 Unimplemented, read as "0"

Bit 4~0 **D4~D0**: Sink current generator control for ISINK1 pin
Current value (mA)=50+5×D[4:0]
Refer to "Sink Current Generator Electrical Characteristics" table for more details.

Pin-shared Functions

The flexibility of the microcontroller range is greatly enhanced by the use of pins that have more than one function. Limited numbers of pins can force serious design constraints on designers but by supplying pins with multi-functions, many of these difficulties can be overcome. For these pins, the desired function of the multi-function I/O pins is selected by a series of registers via the application program control.

Pin-shared Function Selection Registers

The limited number of supplied pins in a package can impose restrictions on the amount of functions a certain device can contain. However by allowing the same pins to share several different functions and providing a means of function selection, a wide range of different functions can be incorporated into even relatively small package sizes. The device includes an Output Function Selection register, labeled as PAS0, which can select the desired functions of the multi-function pin-shared pins.

The most important point to note is to make sure that the desired pin-shared function is properly selected and also deselected. For most pin-shared functions, to select the desired pin-shared function, the pin-shared function should first be correctly selected using the corresponding pin-shared control register. After that the corresponding peripheral functional setting should be configured and then the peripheral function can be enabled. However, a special point must be noted for some digital input pins, such as INT, PTCK etc, which share the same pin-shared control configuration with their corresponding general purpose I/O functions when setting the relevant pin-shared control bit fields. To select these pin functions, in addition to the necessary pin-shared control and peripheral functional setup aforementioned, they must also be setup as an input by setting the corresponding bit in the I/O port control register. To correctly deselect the pin-shared function, the peripheral function should first be disabled and then the corresponding pin-shared function control register can be modified to select other pin-shared functions.

- **PAS0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PAS07	PAS06	PAS05	PAS04	PAS03	PAS02	PAS01	PAS00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PAS07~PAS06**: PA3 Pin-shared function selection
00: PA3
01: PTPB
10: A0PB
11: VREF

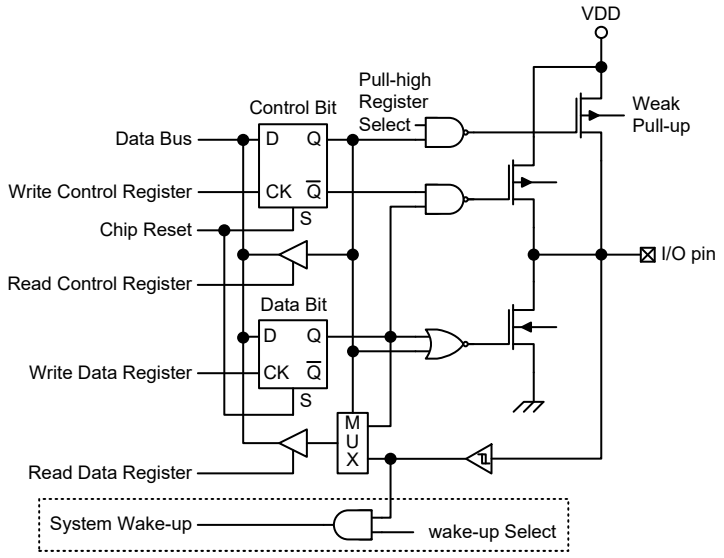
Bit 5~4 **PAS05~PAS04**: PA2 Pin-shared function selection
00/11: PA2/INT/PTCK
01: AN2
10: A1PI

Bit 3~2 **PAS03~PAS02**: PA1 Pin-shared function selection
00/11: PA1/PTPI
01: AN0
10: A0O

Bit 1~0 **PAS01~PAS00**: PA0 Pin-shared function selection
00: PA0
01: AN1
10: PTP
11: A1O

I/O Pin Structures

The accompanying diagram illustrates the internal structures of the I/O logic function. As the exact logical construction of the I/O pin will differ from this diagram, it is supplied as a guide only to assist with the functional understanding of the logic function I/O pins. The wide range of pin-shared structures does not permit all types to be shown.



Logic Function Input/Output Structure

Programming Considerations

Within the user program, one of the first things to consider is port initialisation. After a reset, all of the I/O data and port control registers will be set high. This means that all I/O pins will default to an input state, the level of which depends on the other connected circuitry and whether pull-high selections have been chosen. If the port control registers are then programmed to setup some pins as outputs, these output pins will have an initial high output value unless the associated port data registers are first programmed. Selecting which pins are inputs and which are outputs can be achieved byte-wide by loading the correct values into the appropriate port control register or by programming individual bits in the port control register using the "SET [m].i" and "CLR [m].i" instructions. Note that when using these bit control instructions, a read-modify-write operation takes place. The microcontroller must first read in the data on the entire port, modify it to the required new bit values and then rewrite this data back to the output ports.

Port A has the additional capability of providing wake-up functions. When the device is in the SLEEP or IDLE Mode, various methods are available to wake the device up. One of these is a high to low transition of any of the Port A pins. Single or multiple pins on Port A can be setup to have this function.

Timer Modules – TM

One of the most fundamental functions in any microcontroller devices is the ability to control and measure time. To implement time related functions the device includes several Timer Modules, generally abbreviated to the name TM. The TMs are multi-purpose timing units and serve to provide operations such as Timer/Counter, Input Capture, Compare Match Output and Single Pulse Output as well as being the functional unit for the generation of PWM signals. Each of the TMs has two interrupts. The addition of input and output pins for each TM ensures that users are provided with timing units with a wide and flexible range of features.

The brief features of the Periodic Type TM are described here with more detailed information provided in the individual Periodic Type TM section.

Introduction

The device contains only one TM, namely the Periodic Type TM. Although similar in nature, the different TM types vary in their feature complexity. The features to the Periodic Type TM will be described in this section and the detailed operation will be described in the individual section. The main features of the PTM are summarised in the accompanying table.

TM Function	PTM
Timer/Counter	√
Input Capture	√
Compare Match Output	√
PWM Output	√
Single Pulse Output	√
PWM Alignment	Edge
PWM Adjustment Period & Duty	Duty or Period

TM Function Summary

TM Operation

The TM offers a diverse range of functions, from simple timing operations to PWM signal generation. The key to understanding how the TM operates is to see it in terms of a free running count-up counter whose value is then compared with the value of pre-programmed internal comparators. When the free running count-up counter has the same value as the pre-programmed comparator, known as a compare match situation, a TM interrupt signal will be generated which can clear the counter and perhaps also change the condition of the TM output pin. The internal TM counter is driven by a user selectable clock source, which can be an internal clock or an external pin.

TM Clock Source

The clock source which drives the main counter in the TM can originate from various sources. The selection of the required clock source is implemented using the PTCK2~PTCK0 bits in the PTM control register. The clock source can be a ratio of the system clock, f_{SYS}, or the internal high clock, f_H, the f_{SUB} clock source or the external PTCK pin. The PTCK pin clock source is used to allow an external signal to drive the TM as an external clock source for event counting.

TM Interrupts

The Periodic Type TM has two internal interrupt, one for each of the internal comparator A or comparator P, which generate a TM interrupt when a compare match condition occurs. When a TM interrupt is generated, it can be used to clear the counter and also to change the state of the TM output pin.

TM External Pins

The TM has an input pin, with the label PTCK. The PTM input pin, PTCK, is essentially a clock source for the PTM and is selected using the PTCK2~PTCK0 bits in the PTMC0 register. This external TM input pin allows an external clock source to drive the internal TM. The PTCK input pin can be chosen to have either a rising or falling active edge.

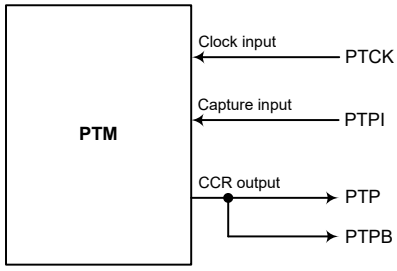
The Periodic Type TM has another input pin, PTPI, which is the capture input whose active edge can be a rising edge, a falling edge or both rising and falling edges and the active edge transition type is selected using the PTIO1~PTIO0 bits in the PTMC1 register.

The TM has two output pins, PTP and PTPB, the PTPB pin outputs the inverted signal of the PTP. The TM output pins can be selected using the corresponding pin-shared function selection bits described in the Pin-shared Function section. When the TM is in the Compare Match Output Mode, these pins can be controlled by the TM to switch to a high or low level or to toggle when a compare match situation occurs. The external PTP and PTPB output pins are also the pins where the TM generates the PWM output waveform.

As the TM input/output pins are pin-shared with other functions, the TM input/output function must first be setup using relevant pin-shared function selection register. The details of the pin-shared function selection are described in the pin-shared function section.

PTM	
Input	**Output**
PTCK, PTPI	PTP, PTPB

TM External Pins

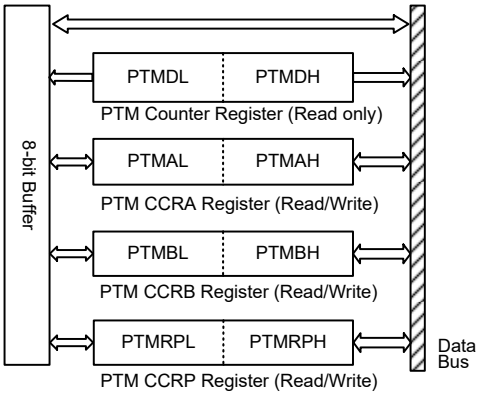


PTM Function Pin Block Diagram

Programming Considerations

The TM Counter Registers and the Capture/Compare CCRA registers as well as the PTM CCRB register, all have a low and high byte structure. The high bytes can be directly accessed, but as the low bytes can only be accessed via an internal 8-bit buffer, reading or writing to these register pairs must be carried out in a specific way. The important point to note is that data transfer to and from the 8-bit buffer and its related low byte only takes place when a write or read operation to its corresponding high byte is executed.

As the CCRA, CCRP and CCRB registers are implemented in the way shown in the following diagram and accessing these register pairs is carried out in a specific way as described above, it is recommended to use the “MOV” instruction to access the CCRA, CCRP and CCRB low byte registers, named PTMAL, PTMRPL, PTMBL, using the following access procedures. Accessing the CCRA, CCRP or CCRP low byte registers without following these access procedures will result in unpredictable values.

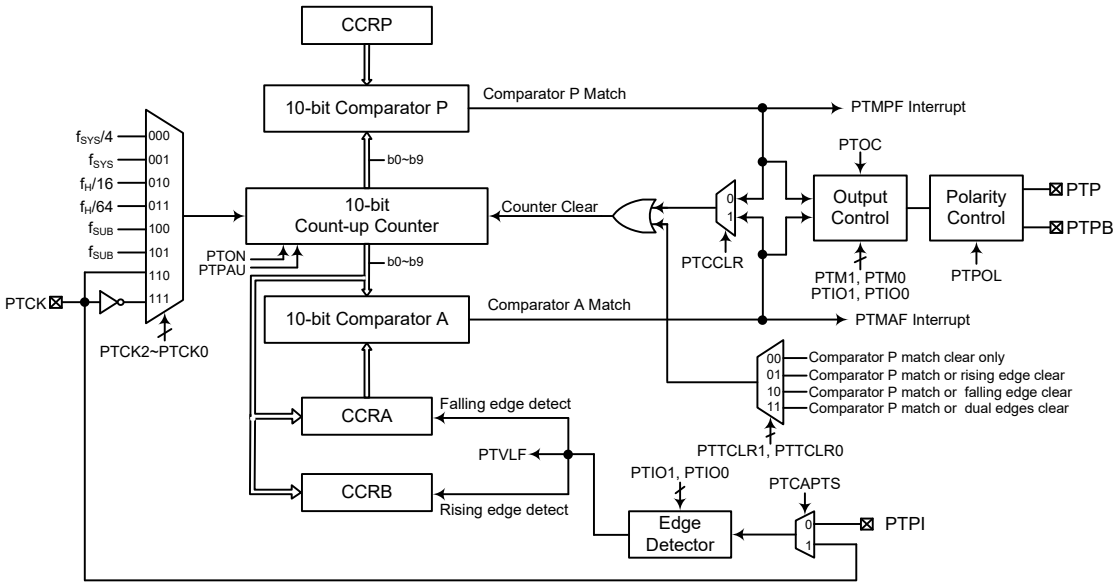


The following steps show the read and write procedures:

- Writing Data to CCRA, CCRB or CCRP
  - Step 1. Write data to Low Byte PTMAL, PTMBL or PTMRPL
    – Note that here data is only written to the 8-bit buffer.
  - Step 2. Write data to High Byte PTMAH, PTMBH or PTMRPH
    – Here data is written directly to the high byte registers and simultaneously data is latched from the 8-bit buffer to the Low Byte registers.
- Reading Data from the Counter Registers and CCRA, CCRB or CCRP
  - Step 1. Read data from the High Byte PTMDH, PTMAH, PTMBH or PTMRPH
    – Here data is read directly from the High Byte registers and simultaneously data is latched from the Low Byte register into the 8-bit buffer.
  - Step 2. Read data from the Low Byte PTMDL, PTMAL, PTMBL or PTMRPL
    – This step reads data from the 8-bit buffer.

Periodic Type TM – PTM

The Periodic Type TM contains five operating modes, which are Compare Match Output, Timer/Event Counter, Capture Input, Single Pulse Output and PWM Output modes. The Periodic Type TM can be controlled with two external input pins and can drive two external output pins.



Note: 1. The PTPB pin is the inverted output of PTP pin.
2. If the PTM external pins will be used and as these pins are pin-shared with other functions, before using the PTM function, the pin-shared function registers should be set properly.

10-bit Periodic Type TM Block Diagram

Periodic Type TM Operation

The Periodic Type TM core is a 10-bit count-up counter which is driven by a user selectable internal or external clock source. There are also two internal comparators with the names, Comparator A and Comparator P. These comparators will compare the value in the counter with CCRP and CCRA registers. The CCRA and CCRP comparators are 10-bit wide whose value is respectively compared with all counter bits.

The only way of changing the value of the 10-bit counter using the application program, is to clear the counter by changing the PTON bit from low to high. The counter will also be cleared automatically by a counter overflow or a compare match with one of its associated comparators. When these conditions occur, a PTM interrupt signal will also usually be generated. The Periodic Type TM can operate in a number of different operational modes, can be driven by different clock sources including an input pin and can also control different outputs. All operating setup conditions are selected using relevant internal registers.

Periodic Type TM Register Description

Overall operation of the Periodic Type TM is controlled using a series of registers. A read only register pair exists to store the internal counter 10-bit value, while three read/write register pairs exist to store the internal 10-bit CCRA value, CCRP value and CCRB value. The remaining three registers are control registers which setup the different operating and control modes.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PTMC0	PTPAU	PTCK2	PTCK1	PTCK0	PTON	—	—	—
PTMC1	PTM1	PTM0	PTIO1	PTIO0	PTOC	PTPOL	PTCAPTS	PTCCLR
PTMC2	—	—	—	—	—	PTTCLR1	PTTCLR0	PTVLF
PTMDL	D7	D6	D5	D4	D3	D2	D1	D0
PTMDH	—	—	—	—	—	—	D9	D8
PTMAL	D7	D6	D5	D4	D3	D2	D1	D0
PTMAH	—	—	—	—	—	—	D9	D8
PTMBL	D7	D6	D5	D4	D3	D2	D1	D0
PTMBH	—	—	—	—	—	—	D9	D8
PTMRPL	D7	D6	D5	D4	D3	D2	D1	D0
PTMRPH	—	—	—	—	—	—	D9	D8

10-bit Periodic Type TM Register List

- **PTMC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PTPAU	PTCK2	PTCK1	PTCK0	PTON	—	—	—
R/W	R/W	R/W	R/W	R/W	R/W	—	—	—
POR	0	0	0	0	0	—	—	—

Bit 7 **PTPAU**: PTM Counter Pause control
0: Run
1: Pause
The counter can be paused by setting this bit high. Clearing the bit to zero restores normal counter operation. When in a Pause condition the PTM will remain powered up and continue to consume power. The counter will retain its residual value when this bit changes from low to high and resume counting from this value when the bit changes to a low value again.

Bit 6~4 **PTCK2~PTCK0**: Select PTM Counter clock
000: $f_{SYS}/4$
001: f_{SYS}
010: $f_H/16$
011: $f_H/64$
100: f_{SUB}
101: f_{SUB}
110: PTCK rising edge clock
111: PTCK falling edge clock
These three bits are used to select the clock source for the PTM. The external pin clock source can be chosen to be active on the rising or falling edge. The clock source f_{SYS} is the system clock, while f_H and f_{SUB} are other internal clocks, the details of which can be found in the oscillator section.

Bit 3 **PTON**: PTM Counter on/off control
0: Off
1: On
This bit controls the overall on/off function of the PTM. Setting the bit high enables the counter to run, clearing the bit disables the PTM. Clearing this bit to zero will stop the counter from counting and turn off the PTM which will reduce its power consumption. When the bit changes state from low to high the internal counter value will be reset to zero, however when the bit changes from high to low, the internal counter will retain its residual value until the bit returns high again.

If the PTM is in the Compare Match Output Mode, PWM output Mode or Single Pulse Output Mode then the PTM output pin will be reset to its initial condition, as specified by the PTOC bit, when the PTON bit changes from low to high.

Bit 2~0 Unimplemented, read as "0"

- **PTMC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	PTM1	PTM0	PTIO1	PTIO0	PTOC	PTPOL	PTCAPTS	PTCCLR
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PTM1~PTM0**: Select PTM Operating Mode
00: Compare Match Output Mode
01: Capture Input Mode
10: PWM Output Mode or Single Pulse Output Mode
11: Timer/Counter Mode

These bits setup the required operating mode for the PTM. To ensure reliable operation the PTM should be switched off before any changes are made to the PTM1 and PTM0 bits. In the Timer/Counter Mode, the PTM output pin state is undefined.

Bit 5~4 **PTIO1~PTIO0**: Select PTM pin (PTP or PTPI/PTCK) function

Compare Match Output Mode
00: No change
01: Output low
10: Output high
11: Toggle output

PWM Output Mode/Single Pulse Output Mode
00: PWM output inactive state
01: PWM output active state
10: PWM output
11: Single pulse output

Capture Input Mode

PTTCLR[1:0]=00B:
00: Input capture at rising edge of PTPI or PTCK and the counter value will be latched into CCRA
01: Input capture at falling edge of PTPI or PTCK and the counter value will be latched into CCRA
10: Input capture at falling/rising edge of PTPI or PTCK and the counter value will be latched into CCRA
11: Input capture disabled

PTTCLR[1:0]=01B or 10B or 11B:
00: Input capture at rising edge of PTPI or PTCK and the counter value will be latched into CCRB
01: Input capture at falling edge of PTPI or PTCK and the counter value will be latched into CCRA
10: Input capture at falling/rising edge of PTPI or PTCK and the counter value will be latched into CCRA at falling edge and into CCRB at rising edge
11: Input capture disabled

Timer/Counter Mode
Unused

These two bits are used to determine how the PTM operates when a certain condition is reached. The function that these bits select depends upon in which mode the PTM is running.

In the Compare Match Output Mode, the PTIO1 and PTIO0 bits determine how the PTM output pin changes state when a compare match occurs from the Comparator A. The PTM output pin can be setup to switch high, switch low or to toggle its present state when a compare match occurs from the Comparator A. When the bits are both zero, then no change will take place on the output. The initial value of the PTM output pin should be setup using the PTOC bit in the PTMC1 register. Note that the output level requested by the PTIO1 and PTIO0 bits must be different from the initial value setup using the PTOC bit otherwise no change will occur on the PTM output pin when a compare match occurs. After the PTM output pin changes state, it can be reset to its initial level by changing the level of the PTON bit from low to high.

In the PWM Output Mode, the PTIO1 and PTIO0 bits determine how the PTM output pin changes state when a certain compare match condition occurs. The PWM output function is modified by changing these two bits. It is necessary to only change the values of the PTIO1 and PTIO0 bits after the PTM has been switched off. Unpredictable PWM outputs will occur if the PTIO1 and PTIO0 bits are changed when the PTM is running.

Bit 3 **PTOC**: PTM Output control bit

Compare Match Output Mode
0: Initial low
1: Initial high

PWM Output Mode/Single Pulse Output Mode
0: Active low
1: Active high

This is the output control bit for the PTM output pin. Its operation depends upon whether PTM is being used in the Compare Match Output Mode or in the PWM Output Mode/Single Pulse Output Mode. It has no effect if the PTM is in the Timer/Counter Mode. In the Compare Match Output Mode it determines the logic level of the PTM output pin before a compare match occurs. In the PWM Output Mode it determines if the PWM signal is active high or active low. In the Single Pulse Output Mode it determines the logic level of the PTM output pin when the PTON bit changes from low to high.

Bit 2 **PTPOL**: PTM Output polarity control
0: Non-invert
1: Invert

This bit controls the polarity of the output pins. When the bit is set high the PTM output pin will be inverted and not inverted when the bit is zero. It has no effect if the PTM is in the Timer/Counter Mode.

Bit 1 **PTCAPTS**: PTM Capture Trigger Source selection
0: From PTPI pin
1: From PTCK pin

Bit 0 **PTCCLR**: Select PTM Counter clear condition
0: PTM Comparator P match
1: PTM Comparator A match

This bit is used to select the method which clears the counter. Remember that the Periodic Type TM contains two comparators, Comparator A and Comparator P, either of which can be selected to clear the internal counter. With the PTCCLR bit set high, the counter will be cleared when a compare match occurs from the Comparator A. When the bit is low, the counter will be cleared when a compare match occurs from the Comparator P or with a counter overflow. A counter overflow clearing method can only be implemented if the CCRP bits are all cleared to zero. The PTCCLR bit is not used in the PWM Output Mode, Single Pulse Output or Capture Input Mode or Capture Input Mode.

• **PTMC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	PTTCLR1	PTTCLR0	PTVLF
R/W	—	—	—	—	—	R/W	R/W	R
POR	—	—	—	—	—	0	0	0

Bit 7~3 Unimplemented, read as "0"

Bit 2~1 **PTTCLR1~PTTCLR0**: Select PTM Timer clear condition (for capture input mode only)
00: Comparator P match clear only
01: Comparator P match clear or rising edge clear
10: Comparator P match clear or falling edge clear
11: Comparator P match clear or dual edges clear

Bit 0 **PTVLF**: PTM Counter Value Latch trigger edge flag
0: Falling edge trigger the counter value latch
1: Rising edge trigger the counter value latch
When setting PTTCLR1~PTTCLR0 bits equal to 00B, ignore this flag status.

• **PTMDL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTM Counter Low Byte Register bit 7 ~ bit 0
PTM 10-bit Counter bit 7 ~ bit 0

• **PTMDH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R	R
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: PTM Counter High Byte Register bit 1 ~ bit 0
PTM 10-bit Counter bit 9 ~ bit 8

• **PTMAL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTM CCRA Low Byte Register bit 7 ~ bit 0
PTM 10-bit CCRA bit 7 ~ bit 0

• **PTMAH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: PTM CCRA High Byte Register bit 1 ~ bit 0
PTM 10-bit CCRA bit 9 ~ bit 8

• **PTMBL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTM CCRB Low Byte Register bit 7 ~ bit 0
PTM 10-bit CCRB bit 7 ~ bit 0

• **PTMBH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: PTM CCRB High Byte Register bit 1 ~ bit 0
PTM 10-bit CCRB bit 9 ~ bit 8

• **PTMRPL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTM CCRP Low Byte Register bit 7 ~ bit 0
PTM 10-bit CCRP bit 7 ~ bit 0

• **PTMRPH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: PTM CCRP High Byte Register bit 1 ~ bit 0
PTM 10-bit CCRP bit 9 ~ bit 8

Periodic Type TM Operating Modes

The Periodic Type TM can operate in one of five operating modes, Compare Match Output Mode, PWM Output Mode, Single Pulse Output Mode, Capture Input Mode or Timer/Counter Mode. The operating mode is selected using the PTM1 and PTM0 bits in the PTMC1 register.

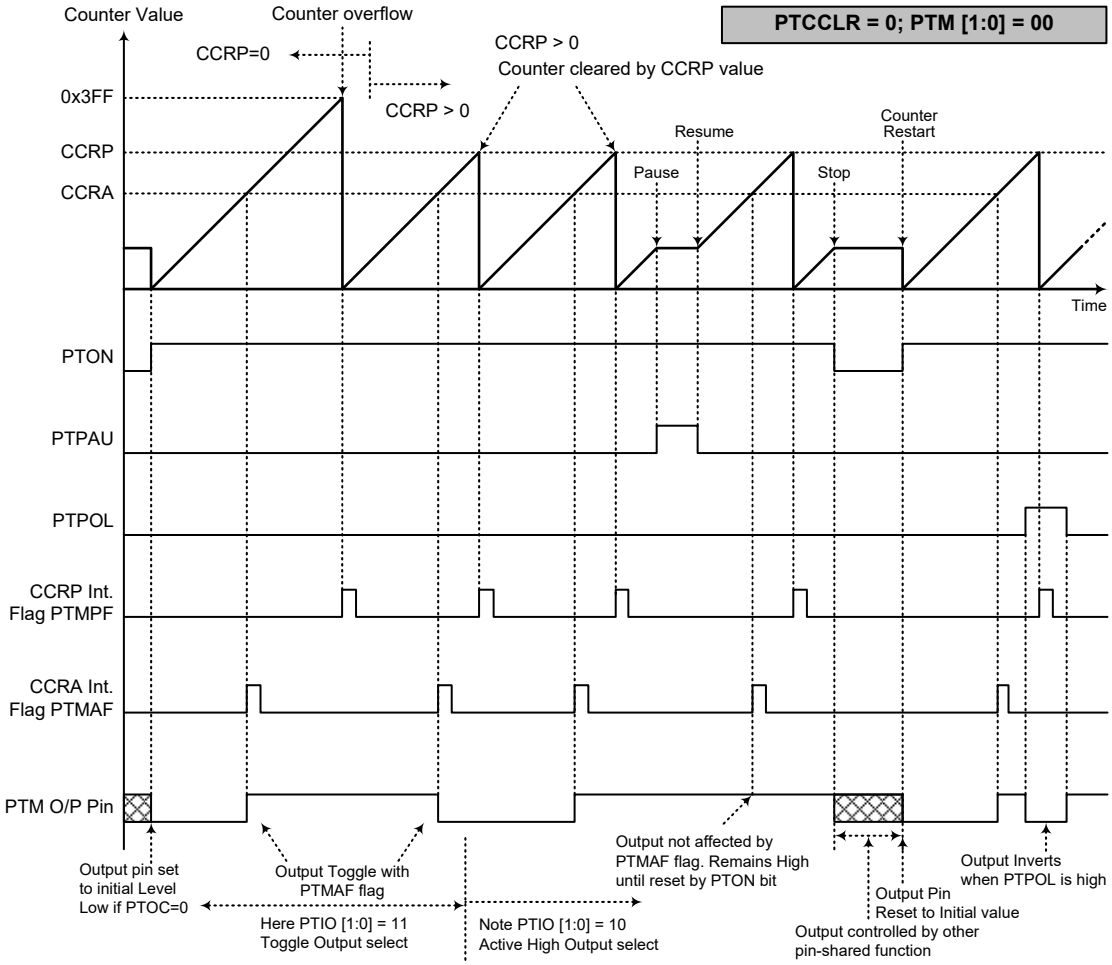
Compare Match Output Mode

To select this mode, bits PTM1 and PTM0 in the PTMC1 register, should be set to 00 respectively. In this mode once the counter is enabled and running it can be cleared by three methods. These are a counter overflow, a compare match from Comparator A and a compare match from Comparator P. When the PTCCLR bit is low, there are two ways in which the counter can be cleared. One is when a compare match from Comparator P, the other is when the CCRP bits are all zero which allows the counter to overflow. Here both PTMAF and PTMPF interrupt request flags for Comparator A and Comparator P respectively, will both be generated.

If the PTCCLR bit in the PTMC1 register is high then the counter will be cleared when a compare match occurs from Comparator A. However, here only the PTMAF interrupt request flag will be generated even if the value of the CCRP bits is less than that of the CCRA registers. Therefore when PTCCLR is high no PTMPF interrupt request flag will be generated. In the Compare Match Output Mode, the CCRA can not be cleared to zero.

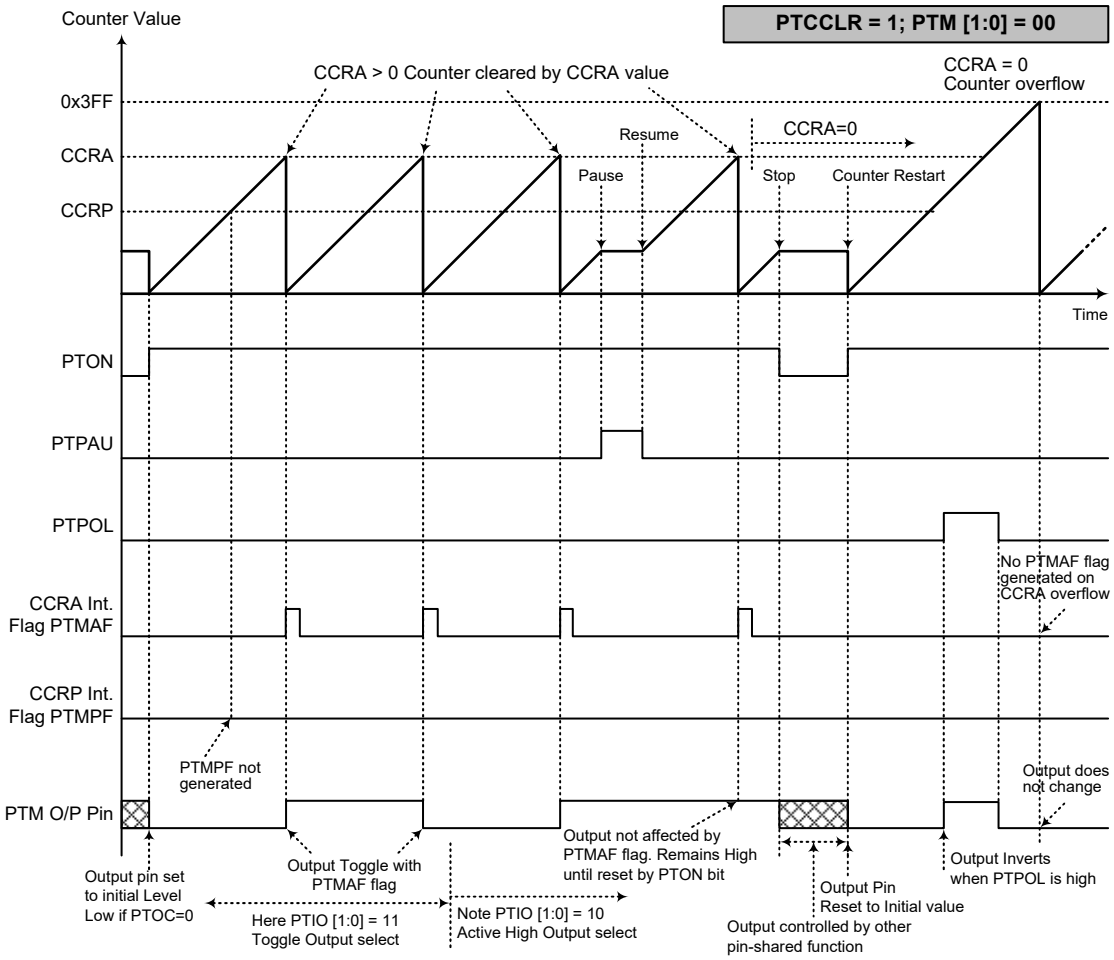
If the CCRA bits are all zero, the counter will overflow when its reaches its maximum value 3FFH, however here the PTMAF interrupt request flag will not be generated.

As the name of the mode suggests, after a comparison is matched, the PTM output pin will change state. The PTM output pin condition however only changes state when a PTMAF interrupt request flag is generated after a compare match occurs from Comparator A. The PTMPF interrupt request flag, generated from a compare match occurs from Comparator P, will have no effect on the PTM output pin. The way in which the PTM output pin changes state are determined by the condition of the PTIO1 and PTIO0 bits in the PTMC1 register. The PTM output pin can be selected using the PTIO1 and PTIO0 bits to go high, to go low or to toggle from its present condition when a compare match occurs from Comparator A. The initial condition of the PTM output pin, which is setup after the PTON bit changes from low to high, is setup using the PTOC bit. Note that if the PTIO1 and PTIO0 bits are zero then no pin change will take place.



Compare Match Output Mode – PTCCLR=0

Note: 1. With PTCCLR=0 a Comparator P match will clear the counter
2. The PTM output pin controlled only by the PTMAF flag
3. The output pin reset to its initial state by a PTON bit rising edge



Compare Match Output Mode – PTCCLR=1

Note: 1. With PTCCLR=1 a Comparator A match clear the counter
2. The PTM output pin controlled only by the PTMAF flag
3. The output pin reset to its initial state by a PTON bit rising edge
4. A PTMPF flag is not generated when PTCCLR=1

Timer/Counter Mode

To select this mode, bits PTM1 and PTM0 in the PTMC1 register should be set to 11 respectively. The Timer/Counter Mode operates in an identical way to the Compare Match Output Mode generating the same interrupt flags. The exception is that in the Timer/Counter Mode the PTM output pin is not used. Therefore the above description and Timing Diagrams for the Compare Match Output Mode can be used to understand its function. As the TM output pin is not used in this mode, the pin can be used as a normal I/O pin or other pin-shared function.

PWM Output Mode

To select this mode, bits PTM1 and PTM0 in the PTMC1 register should be set to 10 respectively and also the PTIO1 and PTIO0 bits should be set to 10 respectively. The PWM function within the PTM is useful for applications which require functions such as motor control, heating control, illumination control etc. By providing a signal of fixed frequency but of varying duty cycle on the PTM output pin, a square wave AC waveform can be generated with varying equivalent DC RMS values.

As both the period and duty cycle of the PWM waveform can be controlled, the choice of generated waveform is extremely flexible. In the PWM Output Mode, the PTCCLR bit has no effect on the PWM operation. Both of the CCRA and CCRP registers are used to generate the PWM waveform, CCRP register is used to clear the internal counter and thus control the PWM waveform frequency, while CCRA register is used to control the duty cycle. The PWM waveform frequency and duty cycle can therefore be controlled by the values in the CCRA and CCRP registers.

An interrupt flag, one for each of the CCRA and CCRP, will be generated when a compare match occurs from either Comparator A or Comparator P. The PTOC bit in the PTMC1 register is used to select the required polarity of the PWM waveform while the two PTIO1 and PTIO0 bits are used to enable the PWM output or to force the PTM output pin to a fixed high or low level. The PTPOL bit is used to reverse the polarity of the PWM output waveform.

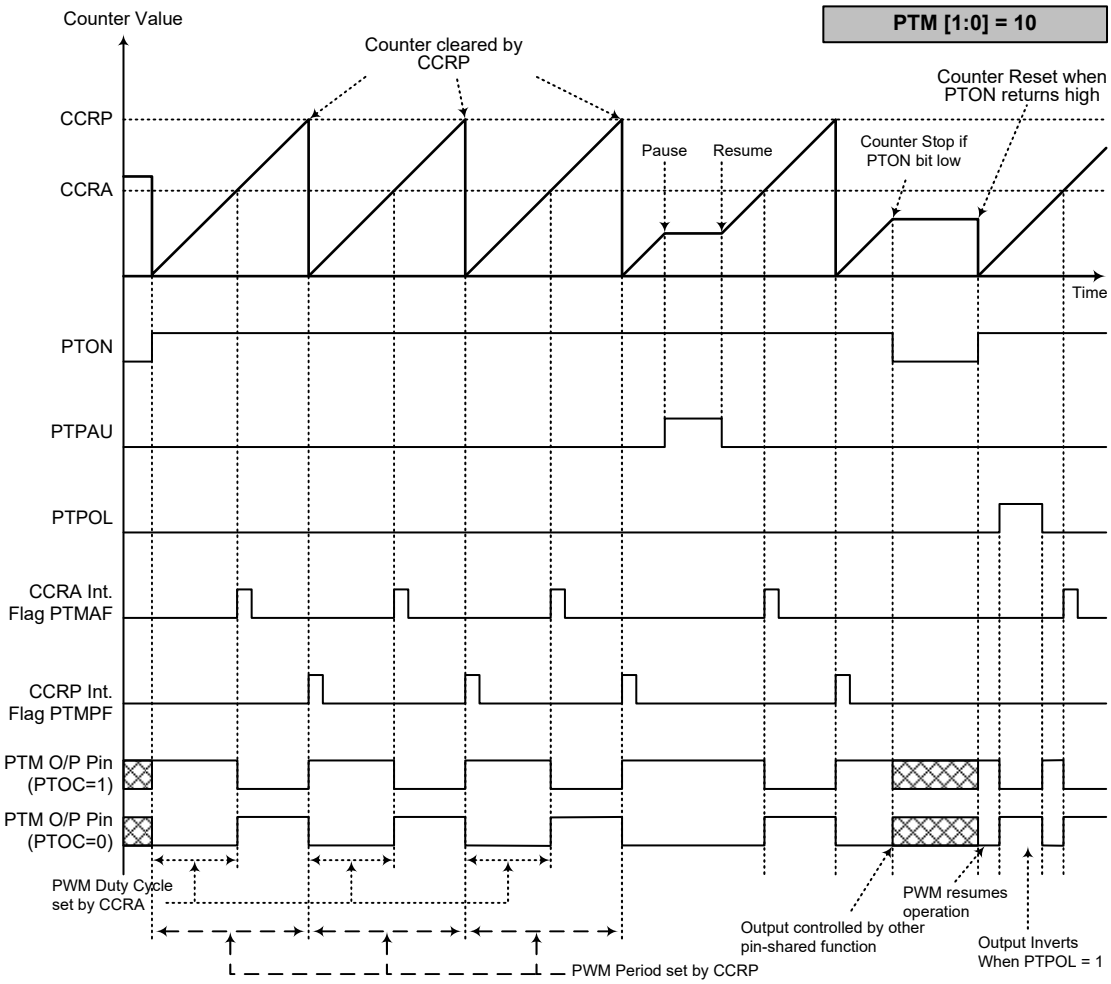
- **10-bit PTM, PWM Output Mode, Edge-aligned Mode**

CCRP	1~1023	0
Period	1~1023	1024
Duty	CCRA	

If f_{SYS}=8MHz, PTM clock source select $f_{SYS}/4$, CCRP=512 and CCRA=128,

The PTM PWM output frequency=($f_{SYS}/4$)/512=$f_{SYS}/2048$=4kHz, duty=128/512=25%.

If the Duty value defined by the CCRA register is equal to or greater than the Period value, then the PWM output duty is 100%.



PWM Output Mode

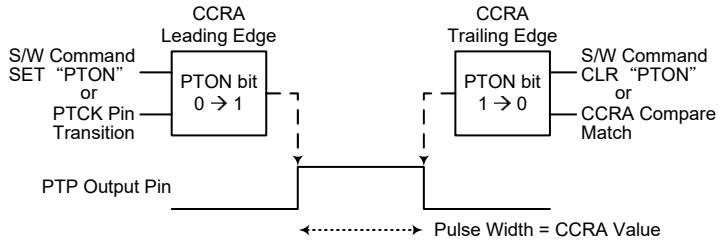
Note: 1. Counter cleared by CCRP
2. A counter clear sets the PWM Period
3. The internal PWM function continues running even when PTIO[1:0] = 00 or 01
4. The PTCCLR bit has no influence on PWM operation

Single Pulse Output Mode

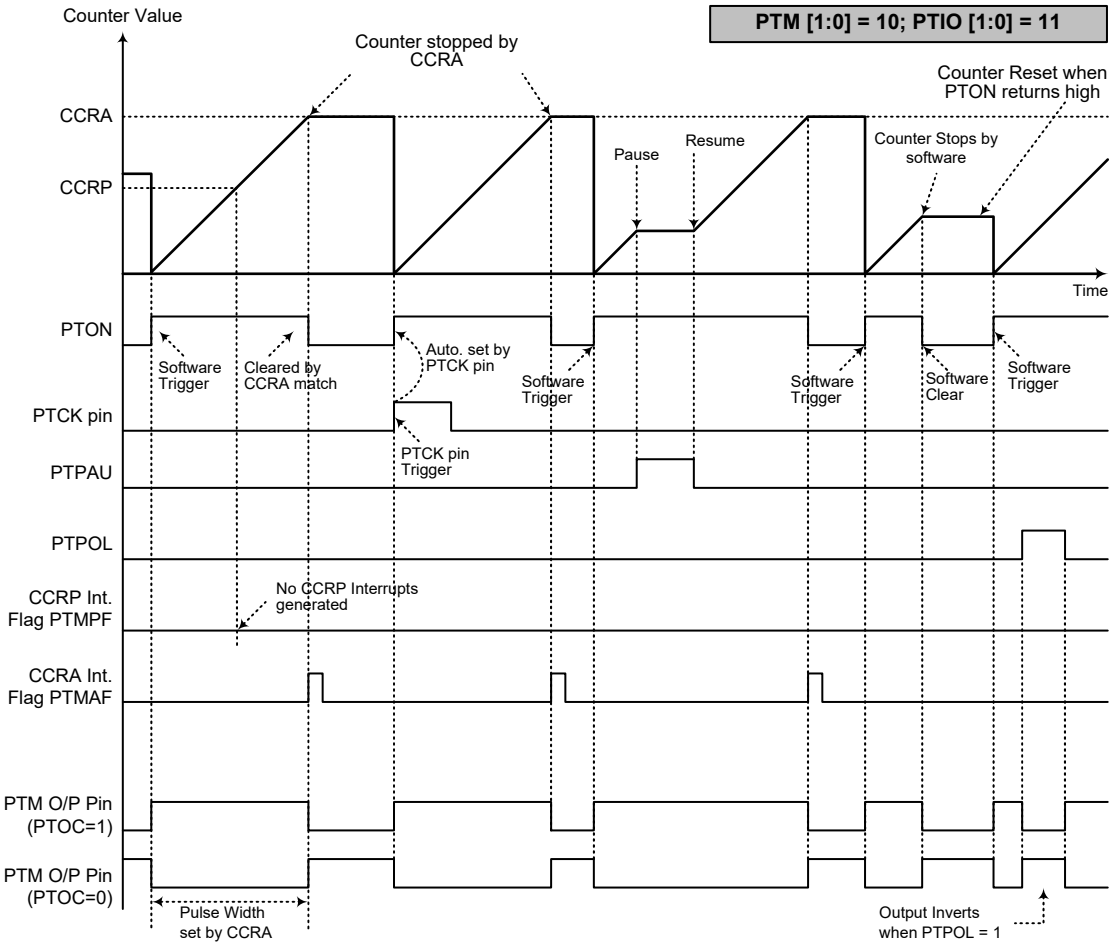
To select this mode, bits PTM1 and PTM0 in the PTMC1 register should be set to 10 respectively and also the PTIO1 and PTIO0 bits should be set to 11 respectively. The Single Pulse Output Mode, as the name suggests, will generate a single shot pulse on the PTM output pin.

The trigger for the pulse output leading edge is a low to high transition of the PTON bit, which can be implemented using the application program. However in the Single Pulse Output Mode, the PTON bit can also be made to automatically change from low to high using the external PTCK pin, which will in turn initiate the Single Pulse output. When the PTON bit transitions to a high level, the counter will start running and the pulse leading edge will be generated. The PTON bit should remain high when the pulse is in its active state. The generated pulse trailing edge will be generated when the PTON bit is cleared to zero, which can be implemented using the application program or when a compare match occurs from Comparator A.

However a compare match from Comparator A will also automatically clear the PTON bit and thus generate the Single Pulse output trailing edge. In this way the CCRA value can be used to control the pulse width. A compare match from Comparator A will also generate a PTM interrupt. The counter can only be reset back to zero when the PTON bit changes from low to high when the counter restarts. In the Single Pulse Output Mode CCRP is not used. The PTCCLR bit is not used in this Mode.



Single Pulse Generation



Single Pulse Output Mode

Note: 1. Counter stopped by CCRA
2. CCRP is not used
3. The pulse is triggered by the PTCK pin or by setting the PTON bit high
4. A PTCK pin active edge will automatically set the PTON bit high
5. In the Single Pulse Output Mode, PTIO[1:0] must be set to “11” and cannot be changed

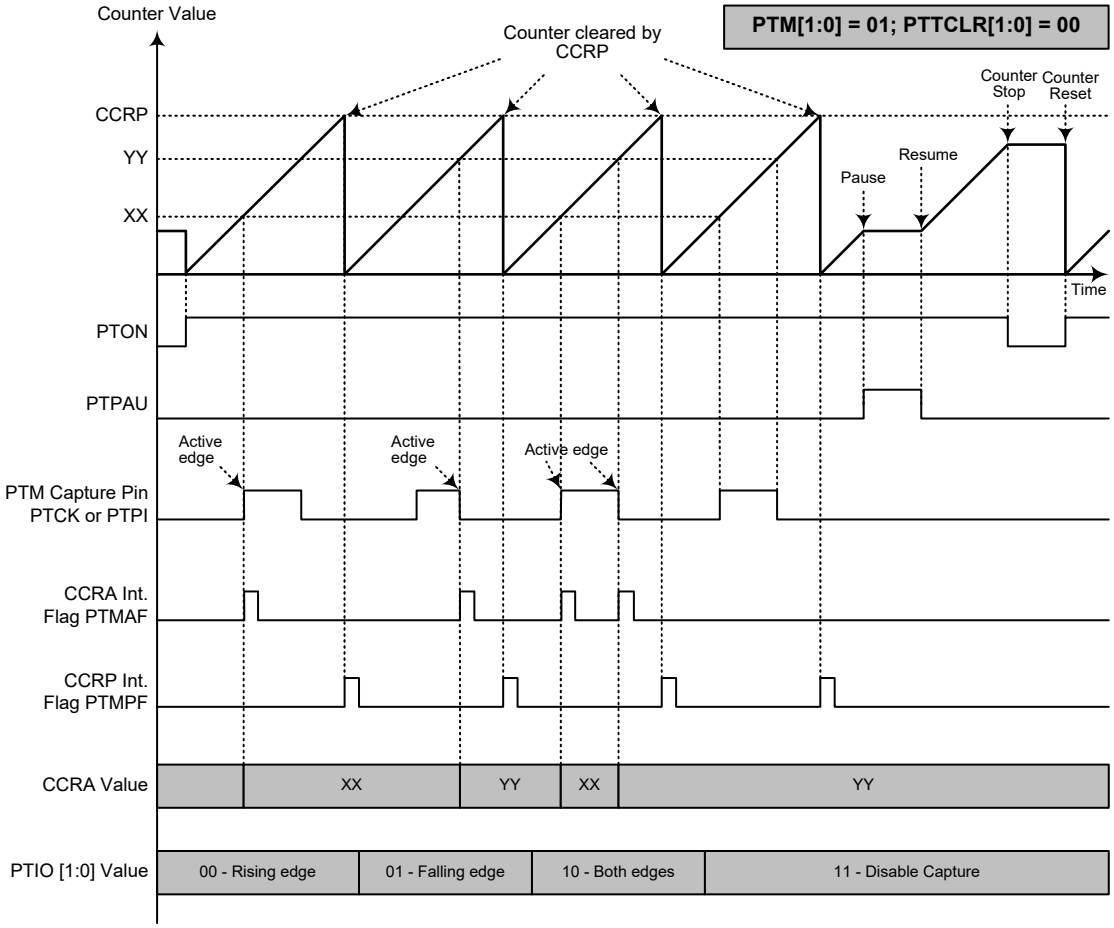
Capture Input Mode

To select this mode bits PTM1 and PTM0 in the PTMC1 register should be set to 01 respectively. This mode enables external signals to capture and store the present value of the internal counter and can therefore be used for applications such as pulse width measurements. The external signal is supplied on the PTPI or PTCK pin which is selected using the PTCAPTS bit in the PTMC1 register, whose active edge can be either a rising edge, a falling edge or both rising and falling edges; the active edge transition type is selected using the PTIO1 and PTIO0 bits in the PTMC1 register. The counter is started when the PTON bit changes from low to high which is initiated using the application program.

The PTIO1 and PTIO0 bits decide which active edge transition type to be latched and to generate an interrupt. The PTTCLR1 and PTTCLR0 bits decide the condition that the counter reset back to zero. The present counter value latched into CCRA or CCRB is decided by PTIO1~PTIO0 together with PTTCLR1~PTTCLR0 setting. The PTIO1~PTIO0 and PTTCLR1~PTTCLR0 bits are setup independently on each other.

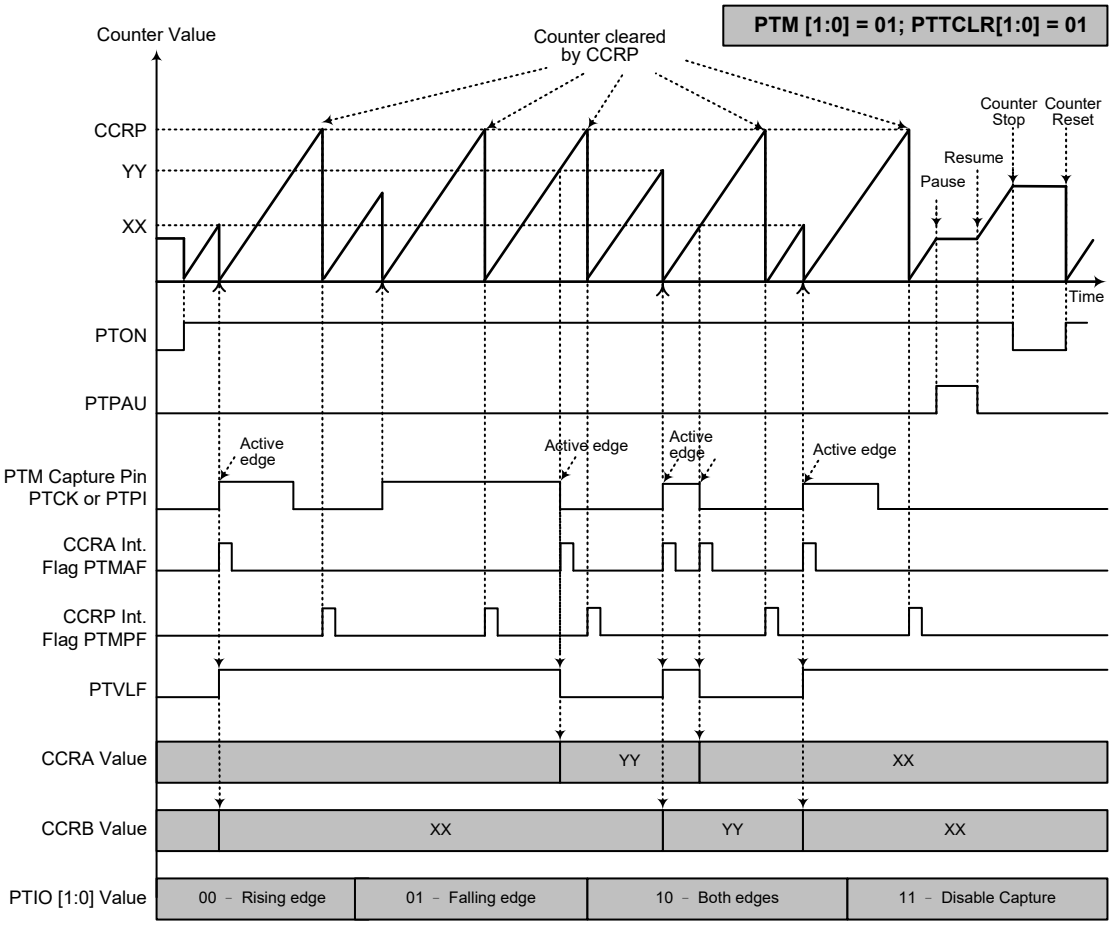
When the required edge transition appears on the PTPI or PTCK pin, the present value in the counter will be latched into the CCRA or CCRB registers and a PTM interrupt generated. Irrespective of what events occur on the input signal, the counter will continue to free run until the PTON bit changes from high to low. When a CCRP compare match occurs the counter will reset back to zero; in this way the CCRP value can be used to control the maximum counter value. When a CCRP compare match occurs from Comparator P, a PTM interrupt will also be generated. Counting the number of overflow interrupt signals from the CCRP can be a useful method in measuring long pulse widths. The PTIO1 and PTIO0 bits can select the active trigger edge on the PTPI or PTCK pin to be a rising edge, falling edge or both edge types. If the PTIO1 and PTIO0 bits are both set high, then no capture operation will take place irrespective of what happens on the PTPI or PTCK pin, however it must be noted that the counter will continue to run.

There are some considerations that should be noted. If PTCK is used as the capture input source, then it cannot be selected as the PTM clock source. If the captured pulse width is less than 2 timer clock periods, it may be ignored by hardware. After the counter value is latched to the CCRA or CCRB registers by an active capture edge, the PTMAF flag will be set high and the PTVLF flag status will be changed after 0.5 timer clock periods. The delay time from the active capture edge received to the action of latching counter value to CCRA or CCRB registers is less than 1.5 timer clock periods. The PTCCLR, PTOC and PTPOL bits are not used in this Mode.



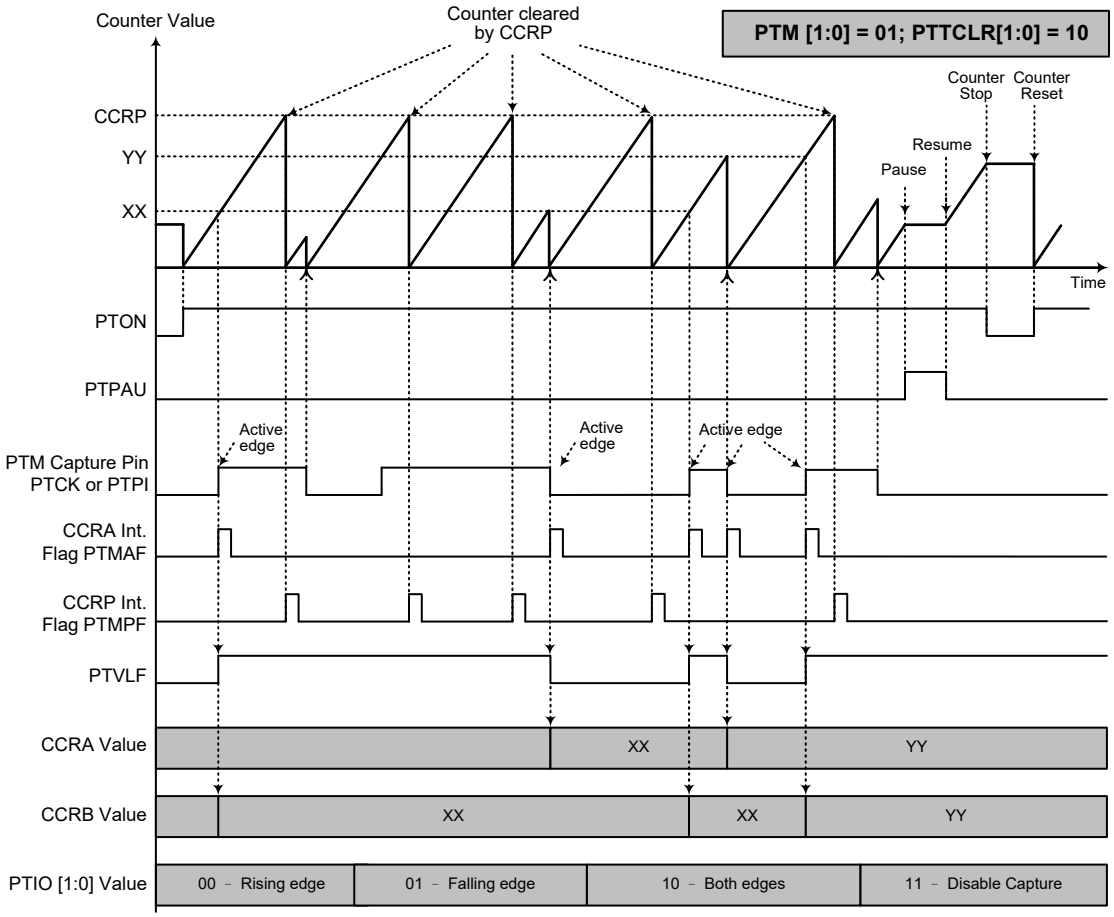
Capture Input Mode – PTTCLR[1:0]=00

Note: 1. PTM[1:0]=01, PTTCLR[1:0]=00 and active edge set by the PTIO[1:0] bits
2. A PTM Capture input pin active edge transfers the counter value to CCRA
3. Comparator P match will clear the counter
4. PTCCLR bit not used
5. No output function – PTOC and PTPOL bits are not used
6. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero
7. Ignore the PTVLF bit status when PTTCLR[1:0]=00



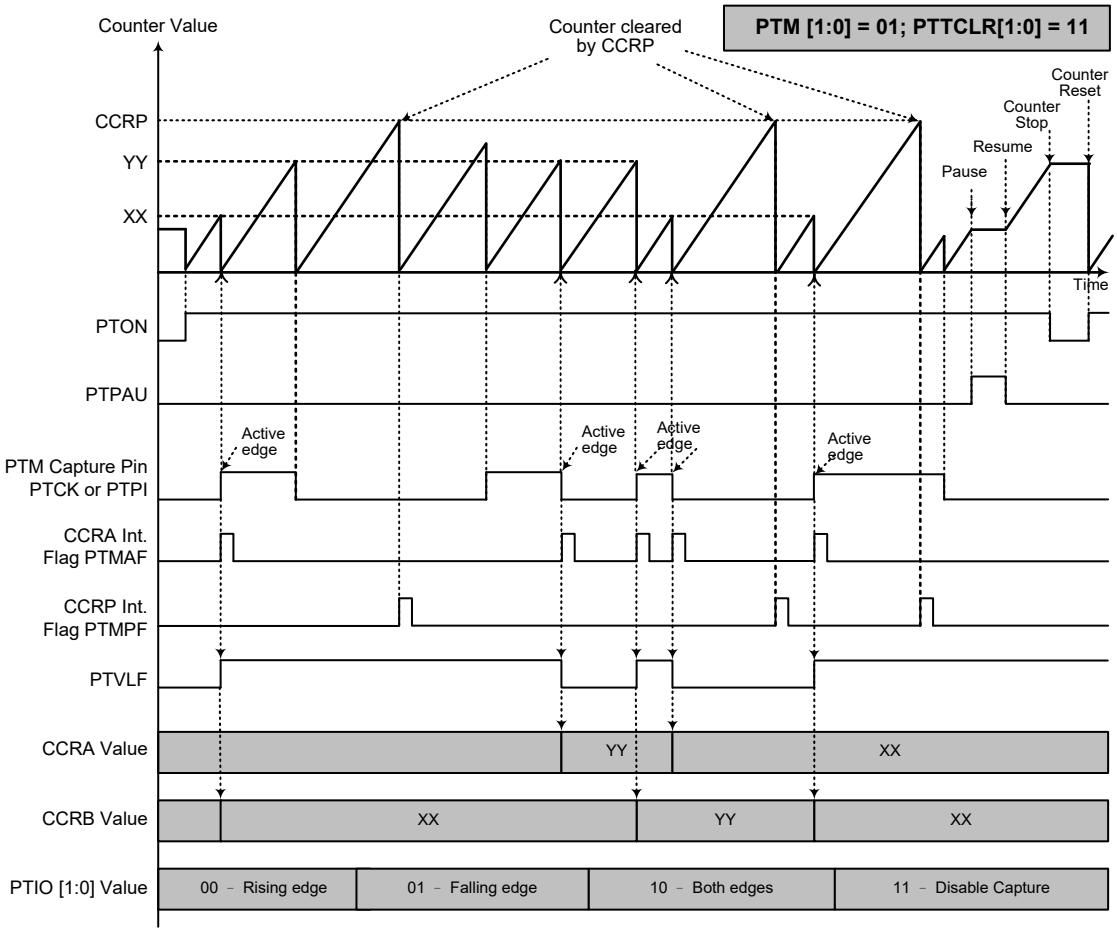
Capture Input Mode – PTTCLR[1:0]=01

Note: 1. PTM[1:0]=01, PTTCLR[1:0]=01 and active edge set by the PTIO[1:0] bits
2. A PTM Capture input pin active edge transfers the counter value to CCRA or CCRB
3. Comparator P match or PTM capture input rising edge will clear the counter
4. PTCCLR bit is not used
5. No output function – PTOC and PTPOL bits are not used
6. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero



Capture Input Mode – PTTCLR[1:0]=10

Note: 1. PTM[1:0]=01, PTTCLR[1:0]=10 and active edge set by the PTIO[1:0] bits
2. A PTM Capture input pin active edge transfers the counter value to CCRA or CCRB
3. Comparator P match or PTM capture input falling edge will clear the counter
4. PTCCLR bit is not used
5. No output function – PTOC and PTPOL bits are not used
6. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero

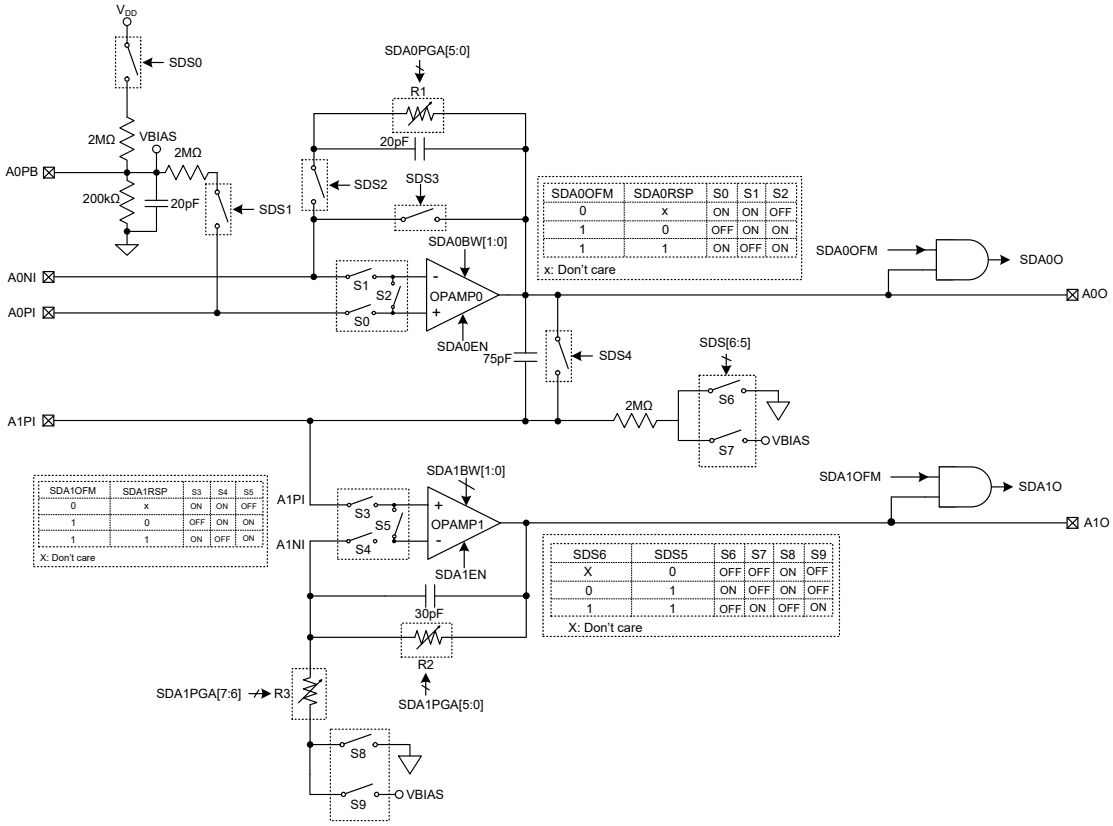


Capture Input Mode – PTnTCLR[1:0] = 11

Note: 1. PTM[1:0]=01, PTTCLR[1:0]=11 and active edge set by the PTIO[1:0] bits
2. A PTM Capture input pin active edge transfers the counter value to CCRA or CCRB
3. Comparator P match or PTM capture input pin rising or falling edge will clear the counter
4. PTCCLR bit is not used
5. No output function, PTOC and PTPOL bits not used
6. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero

Smoke Detector AFE

The device provides a Smoke Detector AFE circuit which can be used for optical signal detection in Smoke Detector applications. The circuit consists of two fully integrated Operational Amplifiers. The optical signal can be detected and processed by the operational amplifiers.



Smoke Detector AFE Block Diagram

Smoke Detector AFE Registers

Overall operation of the Smoke Detector AFE circuit is controlled using a series of registers. The SDSW register is used to control the switches on or off thus controlling the Operational Amplifier operating mode. The SDPGAC0 and SDPGAC1 registers are used to select the R1, R2 and R3 resistance. The SDAnC register where n=0~1, is used to control the SD OPAMPn enable/disable and bandwidth functions as well as stores the output status. The SDAnVOS register is used to select and control the SD OPAMPn input offset voltage calibration function.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SDSW	—	SDS6	SDS5	SDS4	SDS3	SDS2	SDS1	SDS0
SDPGAC0	—	—	SDA0PGA5	SDA0PGA4	SDA0PGA3	SDA0PGA2	SDA0PGA1	SDA0PGA0
SDPGAC1	SDA1PGA7	SDA1PGA6	SDA1PGA5	SDA1PGA4	SDA1PGA3	SDA1PGA2	SDA1PGA1	SDA1PGA0
SDA0C	—	SDA0EN	SDA0O	—	—	—	SDA0BW1	SDA0BW0
SDA0VOS	SDA0OFM	SDA0RSP	SDA0OF5	SDA0OF4	SDA0OF3	SDA0OF2	SDA0OF1	SDA0OF0
SDA1C	—	SDA1EN	SDA1O	—	—	—	SDA1BW1	SDA1BW0
SDA1VOS	SDA1OFM	SDA1RSP	SDA1OF5	SDA1OF4	SDA1OF3	SDA1OF2	SDA1OF1	SDA1OF0

Smoke Detector AFE Register List

• **SDSW Register**

Bit	7	6	5	4	3	2	1	0
Name	—	SDS6	SDS5	SDS4	SDS3	SDS2	SDS1	SDS0
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	0	0	0	0	0	0	0

Bit 7 Unimplemented, read as "0"

Bit 6~5 **SDS6~SDS5**: Mode Control
00: External mode
01: AC coupling mode
10: External mode
11: DC coupling mode

Note: 1. When the Switch S6 and S8 are both on to select the AC couple mode, the OPAMP1 amplification factor will be decreased as the Switch S8 has an on-resistance R_{ON_S8}. The OPAMP1 Gain=1+R2/(R3+R_{ON_S8}), where R_{ON_S8}≈150Ω @ V_{DD}=5V, R_{ON_S8}≈170Ω @ V_{DD}=3V.
2. When the Switch S7 and S9 are both on, connecting to VBIAS, to select the DC couple mode, the original settings of the resistance amplification factor will not be available for reference, which is an especially important point users should pay attention to.

Bit 4 **SDS4**: Switch on/off control
0: Off
1: On

Bit 3 **SDS3**: Switch on/off control
0: Off
1: On

Bit 2 **SDS2**: Switch on/off control
0: Off
1: On

Bit 1 **SDS1**: Switch on/off control
0: Off
1: On

Bit 0 **SDS0**: Switch on/off control
0: Off
1: On

• **SDPGAC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	SDA0PGA5	SDA0PGA4	SDA0PGA3	SDA0PGA2	SDA0PGA1	SDA0PGA0
R/W	—	—	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

Bit 7~6 Unimplemented, read as "0"

Bit 5~0 **SDA0PGA5~ SDA0PGA0**: R1 resistance control
R1=SDA0PGA[5:0]×100kΩ

• **SDPGAC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	SDA1PGA7	SDA1PGA6	SDA1PGA5	SDA1PGA4	SDA1PGA3	SDA1PGA2	SDA1PGA1	SDA1PGA0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **SDA1PGA7~SDA1PGA6**: R3 resistance control
00: 10kΩ
01: 20kΩ
10: 30kΩ
11: 40kΩ

Bit 5~0 **SDA1PGA5~ SDA1PGA0**: R2 resistance control
R2=SDA1PGA[5:0]×100kΩ

• **SDA0C Register**

Bit	7	6	5	4	3	2	1	0
Name	—	SDA0EN	SDA0O	—	—	—	SDA0BW1	SDA0BW0
R/W	—	R/W	R	—	—	—	R/W	R/W
POR	—	0	0	—	—	—	0	0

Bit 7 Unimplemented, read as "0"

Bit 6 **SDA0EN**: SD OPA0 enable control
0: Disable
1: Enable

Bit 5 **SDA0O**: SD OPA0 output status (positive logic)
This bit is read only. When SDA0OFM bit is set to 1, SDA0O is defined as SD OPA0 output status, please refer to offset calibration procedure. When SDA0OFM bit is cleared to 0, this bit will be fixed at a low level.

Bit 4~2 Unimplemented, read as "0"

Bit 1~0 **SDA0BW1~SDA0BW0**: SD OPA0 bandwidth control bits
00: 5kHz
01: 40kHz
10: 600kHz
11: 2MHz
Refer to the "Operational Amplifier Electrical Characteristics" for details.

• **SDA1C Register**

Bit	7	6	5	4	3	2	1	0
Name	—	SDA1EN	SDA1O	—	—	—	SDA1BW1	SDA1BW0
R/W	—	R/W	R	—	—	—	R/W	R/W
POR	—	0	0	—	—	—	0	0

Bit 7 Unimplemented, read as "0"

Bit 6 **SDA1EN**: SD OPA1 enable control
0: Disable
1: Enable

Bit 5 **SDA1O**: SD OPA1 output status (positive logic)
This bit is read only. When SDA1OFM bit is set to 1, SDA1O is defined as SD OPA1 output status, please refer to offset calibration procedure. When SDA1OFM bit is cleared to 0, this bit will be fixed at a low level.

Bit 4~2 Unimplemented, read as "0"

Bit 1~0 **SDA1BW1~SDA1BW0**: SD OPA1 bandwidth control bits
00: 5kHz
01: 40kHz
10: 600kHz
11: 2MHz
Refer to the "Operational Amplifier Electrical Characteristics" for details.

• **SDA0VOS Register**

Bit	7	6	5	4	3	2	1	0
Name	SDA0OFM	SDA0RSP	SDA0OF5	SDA0OF4	SDA0OF3	SDA0OF2	SDA0OF1	SDA0OF0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	1	0	0	0	0	0

Bit 7 **SDA0OFM**: SD OPA0 operating mode selection
0: Normal operation
1: Offset calibration mode

Bit 6 **SDA0RSP**: SD OPA0 input offset voltage calibration reference selection
0: Input reference voltage comes from A0NI
1: Input reference voltage comes from A0PI

Bit 5~0 **SDA0OF5~SDA0OF0**: SD OPA0 input offset voltage calibration control
This 6-bit field is used to perform the operational amplifier input offset calibration operation and the value for the SD OPAMP0 input offset calibration can be restored into this bit field. More detailed information is described in the "Operational Amplifier Input Offset Calibration" section.

• **SDA1VOS Register**

Bit	7	6	5	4	3	2	1	0
Name	SDA1OFM	SDA1RSP	SDA1OF5	SDA1OF4	SDA1OF3	SDA1OF2	SDA1OF1	SDA1OF0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	1	0	0	0	0	0

Bit 7 **SDA1OFM**: SD OPA1 operating mode selection
0: Normal operation
1: Offset calibration mode

Bit 6 **SDA1RSP**: SD OPA1 input offset voltage calibration reference selection
0: Input reference voltage comes from A1NI
1: Input reference voltage comes from A1PI

Bit 5~0 **SDA1OF5~SDA1OF0**: SD OPA1 input offset voltage calibration control
This 6-bit field is used to perform the operational amplifier input offset calibration operation and the value for the SD OPAMP1 input offset calibration can be restored into this bit field. More detailed information is described in the "Operational Amplifier Input Offset Calibration" section.

Operational Amplifier Operation

There are two fully integrated Operational Amplifiers in the device, OPAMP1 and OPAMP0. These OPAMPs can be used for signal amplification according to specific user requirements. The OPAMPs can be disabled or enabled entirely under software control using internal registers. With specific control registers, some OPAMP related applications can be more flexible and easier to be implemented, such as Unit Gain Buffer, Non-Inverting Amplifier, Inverting Amplifier and various kinds of filters, etc.

Offset calibration procedure

The following steps show the OPAMP input offset calibration procedures. Note that if OPAMP inputs are pin shared with I/O, they should be configured as OPAMP input before the Input Offset Calibration.

Step 1. Set SDAnOFM=1 and SDAnRSP=1, the SD Operational Amplifier n is now under the input offset calibration mode (S0 and S2 on). To make sure V_{AnOS} as minimize as possible after calibration, the input reference voltage in calibration should be the same as input DC operating voltage in normal mode operation.

Step 2. Set SDAnOF[5:0]=000000 and then read SDAnO bit

Step 3. Increase the SDAnOF[5:0] value by 1 and then read the SDAnO bit.

If the SDAnO bit state has not changed, then repeat Step 3 until the SDAnO bit state has changed.

If the SDAnO bit state has changed, record the SDAnOF[5:0] value as V_{AnOS1} and then go to Step 4.

Step 4. Set SDAnOF[5:0]=111111 then read SDAnO bit.

Step 5. Decrease the SDAnOF[5:0] value by 1 and then read the SDAnO bit.

If the SDAnO bit state has not changed, then repeat Step 5 until the SDAnO bit state has changed.

If the SDAnO bit state has changed, record the SDAnOF[5:0] value as V_{AnOS2} and then go to Step 6.

Step 6. Restore the SD Operational Amplifier n input offset calibration value V_{AnOS} into the SDAnOF[5:0] bit field. The offset calibration procedure is now finished.

$V_{AnOS}=(V_{AnOS1}+V_{AnOS2})/2$, if $(V_{AnOS1}+V_{AnOS2})/2$ is not integral, discard the decimal.

Analog to Digital Converter

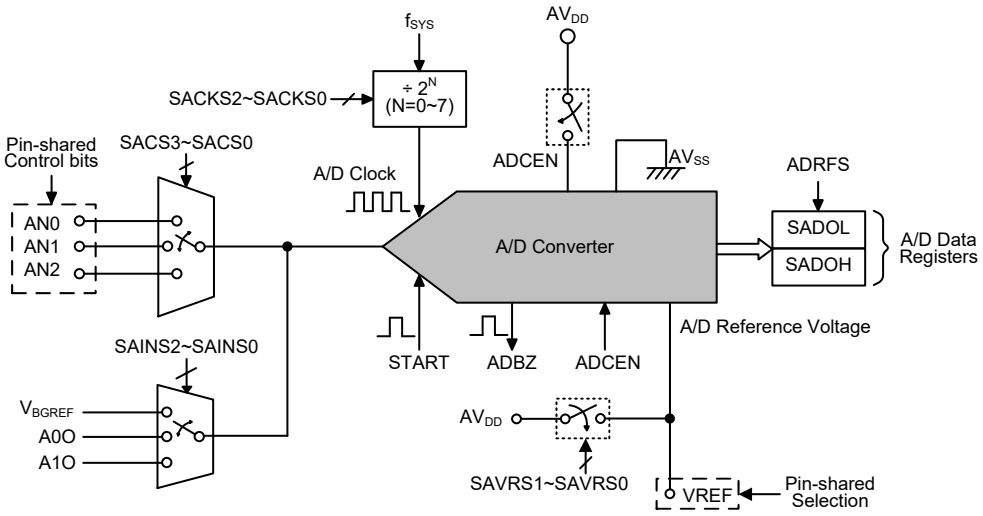
The need to interface to real world analog signals is a common requirement for many electronic systems. However, to properly process these signals by a microcontroller, they must first be converted into digital signals by A/D converters. By integrating the A/D conversion electronic circuitry into the microcontroller, the need for external components is reduced significantly with the corresponding follow-on benefits of lower costs and reduced component space requirements.

A/D Overview

The device contains a multi-channel 10-bit analog to digital converter, a “Successive Approximation” analog to digital converter which can directly interface to external analog signals, such as that from sensors or other control signals and convert these signals directly into a 10-bit digital value. It also can convert the internal signals, such as the internal reference voltage, into a 10-bit digital value. The external or internal analog signal to be converted is determined by the SAINS and SACS bit fields. More detailed information about the A/D input signal selection will be described in the “A/D Converter Input Signals” section.

The accompanying block diagram shows the overall internal structure of the A/D converter, together with its associated registers and control bits.

External Input Channels	Internal Input Signal	A/D Signal Select Bits
AN0~AN2	V_{BGREF}, A0O, A1O	SAINS2~SAINS0 SACS3~SACS0



A/D Converter Structure

Registers Descriptions

Overall operation of the A/D converter is controlled using five registers. A read only register pair exists to store the A/D Converter data 10-bit value. Two registers, SADC0 and SADC1, are the control registers which setup the operating conditions and control function of the A/D converter. There is also a register, VBGRC, used to control the internal reference voltage.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SADOL (ADRFS=0)	D1	D0	—	—	—	—	—	—
SADOL (ADRFS=1)	D7	D6	D5	D4	D3	D2	D1	D0
SADOH (ADRFS=0)	D9	D8	D7	D6	D5	D4	D3	D2
SADOH (ADRFS=1)	—	—	—	—	—	—	D9	D8
SADC0	START	ADBZ	ADCEN	ADRFS	SACS3	SACS2	SACS1	SACS0
SADC1	SAINS2	SAINS1	SAINS0	SAVRS1	SAVRS0	SACKS2	SACKS1	SACKS0
VBGRC	—	—	—	—	—	—	—	VBGREN

A/D Converter Register List

A/D Converter Data Registers – SADOL, SADOH

As the device contains an internal 10-bit A/D converter, it requires two data registers to store the converted value. These are a high byte register, known as SADOH, and a low byte register, known as SADOL. After the conversion process takes place, these registers can be directly read by the microcontroller to obtain the digitised conversion value. As only 10 bits of the 16-bit register space is utilised, the format in which the data is stored is controlled by the ADRFS bit in the SADC0 register as shown in the accompanying table. D0~D9 are the A/D conversion result data bits. Any unused bits will be read as zero. The A/D data registers contents will be unchanged if the A/D converter is disabled.

ADRFS	SADOH								SADOL							
	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
0	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	0	0	0	0	0	0
1	0	0	0	0	0	0	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0

A/D Converter Data Registers

A/D Converter Control Registers – SADC0, SADC1

To control the function and operation of the A/D converter, two control registers known as SADC0 and SADC1 are provided. These 8-bit registers define functions such as the selection of which analog signal is connected to the internal A/D converter, the digitised data format, the A/D clock source as well as controlling the start function and monitoring the A/D converter busy status. As the device contains only one actual analog to digital converter hardware circuit, each of the external and internal analog signals must be routed to the converter. The SAINS field in the SADC1 register and SACS field in the SADC0 register are used to determine which analog signal derived from the external or internal signals will be connected to the A/D converter.

The relevant pin-shared function selection bits determine which pins on I/O Ports are used as analog inputs for the A/D converter input and which pins are not. When the pin is selected to be an A/D input, its original function whether it is an I/O or other pin-shared function will be removed. In addition, any internal pull-high resistor connected to the pin will be automatically removed if the pin is selected to be an A/D converter input.

- **SADC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	START	ADBZ	ADCEN	ADRFS	SACS3	SACS2	SACS1	SACS0
R/W	R/W	R	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **START**: Start the A/D Conversion
0→1→0: Start A/D conversion
This bit is used to initiate an A/D conversion process. The bit is normally low but if set high and then cleared low again, the A/D converter will initiate a conversion process.

Bit 6 **ADBZ**: A/D Converter busy flag
0: No A/D conversion is in progress
1: A/D conversion is in progress
This read only flag is used to indicate whether the A/D conversion is in progress or not. When the START bit is set from low to high and then to low again, the ADBZ flag will be set to 1 to indicate that the A/D conversion is initiated. The ADBZ flag will be cleared to 0 after the A/D conversion is complete.

Bit 5 **ADCEN**: A/D Converter function enable control
0: Disable
1: Enable
This bit controls the A/D internal function. This bit should be set to one to enable the A/D converter. If the bit is cleared to zero, then the A/D converter will be switched off reducing the device power consumption. When the A/D converter function is disabled, the contents of the A/D data register pair known as SADOH and SADOL will be unchanged.

Bit 4 **ADRFS**: A/D conversion data format select
0: A/D converter data format → SADOH = D [9:2]; SADOL = D [1:0]
1: A/D converter data format → SADOH = D [9:8]; SADOL = D [7:0]
This bit controls the format of the 10-bit converted A/D value in the two A/D data registers. Details are provided in the A/D converter data register section.

Bit 3~0 **SACS3~SACS0**: A/D converter external analog input channel select
0000: External AN0 input
0001: External AN1 input
0010: External AN2 input
0011~1111: Non-existed channel, the input will be floating if selected.
These bits are used to select which external analog input channel is to be converted. When the external analog input channel is selected, the SAINS bit field must set to "000", "101" or "11x". Details are summarized in the "A/D Converter Input Signal Selection" table.

• **SADC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	SAINS2	SAINS1	SAINS0	SAVRS1	SAVRS0	SACKS2	SACKS1	SACKS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~5 **SAINS2~SAINS0**: A/D converter input signal select
000: External source – External analog channel intput, ANn
001: Internal source – Internal signal derived from V_{BGREF}
010: Internal source – Internal signal derived from A0O
011: Internal source – Internal signal derived from A1O
100: Internal source – Unused, connected to ground
101: External source – External analog channel intput, ANn
11x: External source – External analog channel intput, ANn
Care must be taken if the SAINS2~SAINS0 bits are set to "001", "01x" or "100" to select the internal analog signal to be converted. When the internal analog signal is selected to be converted, the external input pin must never be selected as the A/D input signal by properly setting the SACS3~SACS0 bits with a value from "0011" to "1111". Otherwise, the external channel input will be connected together with the internal analog signal. This will result in unpredictable situations such as an irreversible damage.

Bit 4~3 **SAVRS1~SAVRS0**: A/D converter reference voltage select
00: External VREF pin
01: Internal A/D converter power, AV_{DD}
1x: External VREF pin
These bits are used to select the A/D converter reference voltage. Care must be taken if the SAVRS1~SAVRS0 bits are set to "01" to select the internal A/D converter power as the reference voltage source. When the internal A/D converter power is selected as the reference voltage, the VREF pin cannot be configured as the reference voltage input by properly configuring the corresponding pin-shared function control bits. Otherwise, the external input voltage on VREF pin will be connected to the internal A/D converter power. This will result in unpredictable situations.

Bit 2~0 **SACKS2~SACKS0**: A/D conversion clock source select
000: f_{SYS}
001: $f_{SYS}/2$
010: $f_{SYS}/4$
011: $f_{SYS}/8$
100: $f_{SYS}/16$
101: $f_{SYS}/32$
110: $f_{SYS}/64$
111: $f_{SYS}/128$
These bits are used to select the clock source for the A/D converter.

• **VBGRC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	VBGREN
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as "0"

Bit 0 **VBGREN**: Bandgap enable control
0: Disable
1: Enable
When this bit is cleared to 0, the Bandgap voltage output V_{BGREF} is in a high impedance state.

A/D Converter Reference Voltage

The actual reference voltage supply to the A/D Converter can be supplied from the positive power supply, AV_{DD}, or an external reference source supplied on pin VREF determined by the SAVRS1~SAVRS0 bits in the SADC1 register. As the VREF pin is pin-shared with other functions, when the VREF pin is selected as the reference voltage pin, the VREF pin-shared function selection bits should first be properly configured to disable other pin-shared functions. However, if the internal reference signal is selected as the reference source, the VREF pin must not be configured as the reference voltage input to avoid the internal connection between the VREF pin to A/D converter power AV_{DD}. The analog input values must not be allowed to exceed the value of the selected A/D reference voltage.

A/D Converter Input Signals

All of the external A/D analog input pins are pin-shared with the I/O pins as well as other functions. The corresponding pin-shared function selection bits in the PAS0 register, determine whether the external input pins are setup as A/D converter analog channel inputs or whether they have other functions. If the corresponding pin is setup to be an A/D converter analog channel input, the original pin function will be disabled. In this way, pins can be changed under program control to change their function between A/D inputs and other functions. All pull-high resistors, which are setup through register programming, will be automatically disconnected if the pins are setup as A/D inputs. Note that it is not necessary to first setup the A/D pin as an input in the port control register to enable the A/D input as when the relevant A/D input function selection bits enable an A/D input, the status of the port control register will be overridden.

As the device contains only one actual analog to digital converter hardware circuit, each of the external and internal analog signals must be routed to the converter. The SAINS2~SAINS0 bits in the SADC1 register are used to determine that the analog signal to be converted comes from the external channel input or internal analog signal. The SACS3~SACS0 bits in the SADC0 register are used to determine which external channel input is selected to be converted. If the SAINS2~SAINS0 bits are set to “000” or “101~111”, the external channel input will be selected to be converted and the SACS3~SACS0 bits can determine which external channel is selected. If the internal analog signal is selected to be converted, the SACS3~SACS0 bits must be configured with an appropriate value to switch off the external analog channel input. Otherwise, the internal analog signal will be connected together with the external channel input. This will result in unpredictable situations.

SAINS[2:0]	SACS[3:0]	Input Signals	Description
000, 101~111	0000~0010	AN0~AN2	External pin analog input
	0011~1111	—	Un-existed channel, input is floating.
001	0011~1111	V_{BGREF}	Internal Bandgap reference voltage
010	0011~1111	A0O	OPAMP0 output
011	0011~1111	A1O	OPAMP1 output
010~100	0011~1111	GND	Unused, connected to ground.

A/D Converter Input Signal Selection

A/D Converter Operation

The START bit in the SADC0 register is used to start the A/D conversion. When the microcontroller sets this bit from low to high and then low again, an analog to digital conversion cycle will be initiated.

The ADBZ bit in the SADC0 register is used to indicate whether the analog to digital conversion process is in progress or not. This bit will be automatically set to 1 by the microcontroller after an

A/D conversion is successfully initiated. When the A/D conversion is complete, the ADBZ bit will be cleared to 0. In addition, the corresponding A/D interrupt request flag will be set in the interrupt control register, and if the interrupts are enabled, an internal interrupt signal will be generated. This A/D internal interrupt signal will direct the program flow to the associated A/D internal interrupt address for processing. If the A/D internal interrupt is disabled, the microcontroller can poll the ADBZ bit in the SADC0 register to check whether it has been cleared as an alternative method of detecting the end of an A/D conversion cycle.

The clock source for the A/D converter, which originates from the system clock f_{SYS}, can be chosen to be either f_{SYS} or a subdivided version of f_{SYS}. The division ratio value is determined by the SACKS2~SACKS0 bits in the SADC1 register. Although the A/D clock source is determined by the system clock f_{SYS} and by bits SACKS2~SACKS0, there are some limitations on the A/D clock source speed that can be selected. As the recommended range of permissible A/D clock period, t_{ADCK}, is from 0.5μs to 10μs, care must be taken for system clock frequencies. For example, if the system clock operates at a frequency of 8MHz, the SACKS2~SACKS0 bits should not be set to 000, 001 or 111. Doing so will give A/D clock periods that are less than the minimum or larger than the maximum A/D clock period which may result in inaccurate A/D conversion values. Refer to the following table for examples, where values marked with an asterisk * show where, depending upon the device, special care must be taken, as the values may be less than or larger than the specified A/D Clock Period.

f_{SYS}	A/D Clock Period (t_{ADCK})							
	SACKS [2:0]= 000 (f_{SYS})	SACKS [2:0]= 001 (f_{SYS}/2)	SACKS [2:0]= 010 (f_{SYS}/4)	SACKS [2:0]= 011 (f_{SYS}/8)	SACKS [2:0]= 100 (f_{SYS}/16)	SACKS [2:0]= 101 (f_{SYS}/32)	SACKS [2:0]= 110 (f_{SYS}/64)	SACKS [2:0]= 111 (f_{SYS}/128)
1MHz	1μs	2μs	4μs	8μs	16μs *	32μs *	64μs *	128μs *
2MHz	500ns	1μs	2μs	4μs	8μs	16μs *	32μs *	64μs *
4MHz	250ns *	500ns	1μs	2μs	4μs	8μs	16μs *	32μs *
8MHz	125ns *	250ns *	500ns	1μs	2μs	4μs	8μs	16μs *

A/D Clock Period Examples

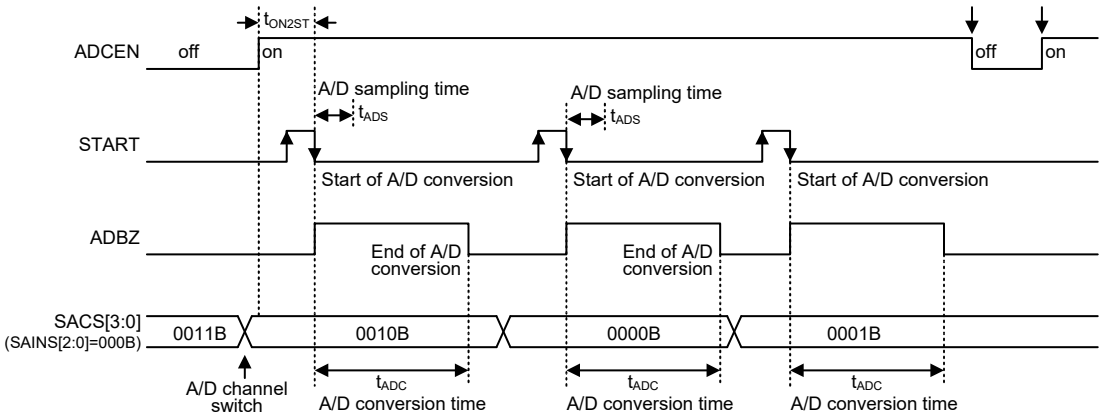
Controlling the power on/off function of the A/D converter circuitry is implemented using the ADCEN bit in the SADC0 register. This bit must be set high to power on the A/D converter. When the ADCEN bit is set high to power on the A/D converter internal circuitry a certain delay, as indicated in the timing diagram, must be allowed before an A/D conversion is initiated. Even if no pins are selected for use as A/D inputs, if the ADCEN bit is high, then some power will still be consumed. In power conscious applications it is therefore recommended that the ADCEN is set low to reduce power consumption when the A/D converter function is not being used.

Conversion Rate and Timing Diagram

A complete A/D conversion contains two parts, data sampling and data conversion. The data sampling which is defined as t_{ADS} takes 4 A/D clock cycles and the data conversion takes 10 A/D clock cycles. Therefore a total of 14 A/D clock cycles for an analog signal A/D conversion which is defined as t_{ADC} are necessary.

Maximum single A/D conversion rate = A/D clock period / 14

The accompanying diagram shows graphically the various stages involved in an analog to digital conversion process and its associated timing. After an A/D conversion process has been initiated by the application program, the microcontroller internal hardware will begin to carry out the conversion, during which time the program can continue with other functions. The time taken for the A/D conversion is 14 t_{ADCK} clock cycles where t_{ADCK} is equal to the A/D clock period.



A/D Conversion Timing

Summary of A/D Conversion Steps

The following summarises the individual steps that should be executed in order to implement an A/D conversion process.

- Step 1
  Select the required A/D conversion clock by correctly programming bits SACKS2~SACKS0 in the SADC1 register.
- Step 2
  Enable the A/D converter by setting the ADCEN bit in the SADC0 register to 1.
- Step 3
  Select which signal is to be connected to the internal A/D converter by correctly configuring the SAINS2~SAINS0 bits
  Select the external channel input to be converted, go to Step 4.
  Select the internal analog signal to be converted, go to Step 5.
- Step 4
  If the A/D input signal comes from the external channel input selected by configuring the SAINS bit field, the corresponding pins should be configured as A/D input function by configuring the relevant pin-shared function control bits. The desired analog channel then should be selected by configuring the SACS bit field. After this step, go to Step 6.
- Step 5
  Before the A/D input signal is selected to come from the internal analog signal by configuring the SAINS bit field, the corresponding external input pin must be switched to a non-existed channel input by properly configured the SACS3~SACS0 bits. The desired internal analog signal then can be selected by configuring the SAINS bit field. After this step, go to Step 6.
- Step 6
  Select the reference voltage source by configuring the SAVRS1~SAVRS0 bits in the SADC1 register.
- Step 7
  Select A/D converter output data format by setting the ADRFS bit in the SADC0 register.
- Step 8
  If A/D conversion interrupt is used, the interrupt control registers must be correctly configured to ensure the A/D interrupt function is active. The master interrupt control bit, EMI, and the A/D conversion interrupt control bit, ADE, must both be set high in advance.

- Step 9
  The A/D conversion procedure can now be initialized by setting the START bit from low to high and then low again.
- Step 10
  If A/D conversion is in progress, the ADBZ flag will be set high. After the A/D conversion process is complete, the ADBZ flag will go low and then the output data can be read from SADOH and SADOL registers.

Note: When checking for the end of the conversion process, if the method of polling the ADBZ bit in the SADC0 register is used, the interrupt enable step above can be omitted.

Programming Considerations

During microcontroller operations where the A/D converter is not being used, the A/D internal circuitry can be switched off to reduce power consumption, by setting bit ADCEN low in the SADC0 register. When this happens, the internal A/D converter circuits will not consume power irrespective of what analog voltage is applied to their input lines. If the A/D converter input lines are used as normal I/O function, then care must be taken as if the input voltage is not at a valid logic level, then this may lead to some increase in power consumption.

A/D Transfer Function

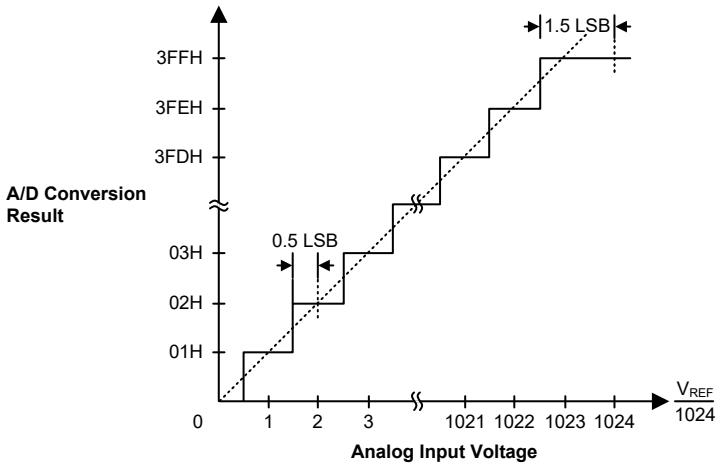
As the device contains a 10-bit A/D converter, its full-scale converted digitised value is equal to 3FFH. Since the full-scale analog input value is equal to the actual A/D converter reference voltage, V_{REF}, this gives a single bit analog input value of reference voltage value divided by 1024.

$$1\ LSB = V_{REF} \div 1024$$

The A/D Converter input voltage value can be calculated using the following equation:

$$\text{A/D input voltage} = \text{A/D output digital value} \times V_{REF} \div 1024$$

The diagram shows the ideal transfer function between the analog input value and the digitised output value for the A/D converter. Except for the digitised zero value, the subsequent digitised values will change at a point 0.5 LSB below where they would change without the offset, and the last full scale digitised value will change at a point 1.5 LSB below the V_{REF} level. Note that here the V_{REF} voltage is the actual A/D converter reference voltage determined by the SAVRS field.



Ideal A/D Transfer Function

A/D Programming Examples

The following two programming examples illustrate how to setup and implement an A/D conversion. In the first example, the method of polling the ADBZ bit in the SADC0 register is used to detect when the conversion cycle is complete, whereas in the second example, the A/D interrupt is used to determine when the conversion is complete.

Example: Using an ADBZ polling method to detect the end of conversion

```
clr  ADE              ; disable ADC interrupt
mov  a,03H
mov  SADC1,a          ; select fSYS/8 as A/D clock
mov  a,04h            ; setup PAS0 register to configure pin AN0
mov  PAS0,a
mov  a,20h
mov  SADC0,a          ; enable and connect AN0 channel to A/D converter
:
start_conversion:
clr  START            ; high pulse on start bit to initiate conversion
set  START            ; reset A/D
clr  START            ; start A/D
polling_EOC:
sz   ADBZ             ; poll the SADC0 register ADBZ bit to detect end of A/D conversion
jmp  polling_EOC      ; continue polling
mov  a,SADOL          ; read low byte conversion result value
mov  SADOL_buffer,a   ; save result to user defined register
mov  a,SADOH          ; read high byte conversion result value
mov  SADOH_buffer,a   ; save result to user defined register
:
:
jmp  start_conversion
```

Example: Using the interrupt method to detect the end of conversion

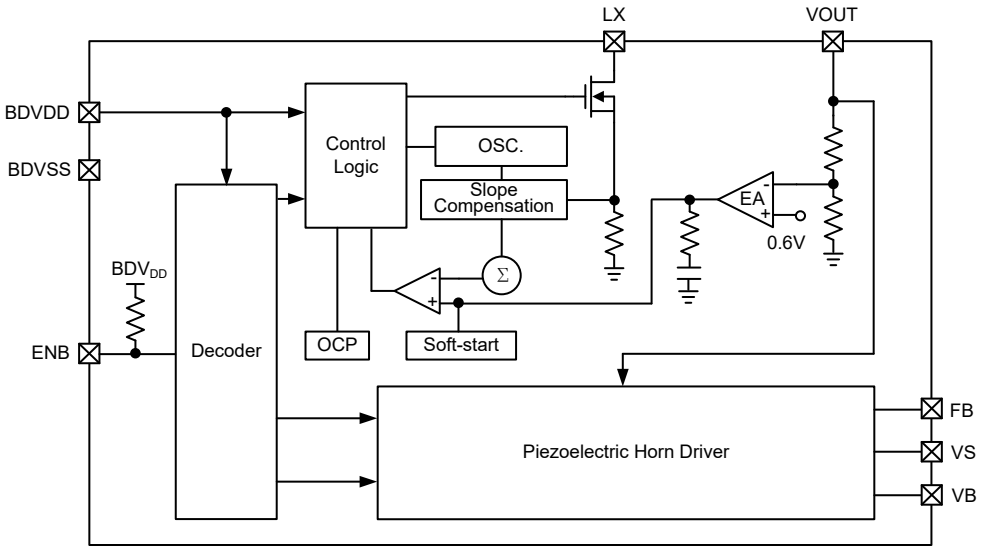
```
clr  ADE              ; disable ADC interrupt
mov  a,03H
mov  SADC1,a          ; select fSYS/8 as A/D clock
mov  a, 04h           ; setup PAS0 register to configure pin AN0
mov  PAS0,a
mov  a,20h
mov  SADC0,a          ; enable and connect AN0 channel to A/D converter
Start_conversion:
clr  START            ; high pulse on START bit to initiate conversion
set  START            ; reset A/D
clr  START            ; start A/D
clr  ADF              ; clear ADC interrupt request flag
set  ADE              ; enable ADC interrupt
set  EMI              ; enable global interrupt
:
:
; ADC interrupt service routine
ADC_ISR:
mov  acc_stack,a      ; save ACC to user defined memory
mov  a,STATUS
mov  status_stack,a   ; save STATUS to user defined memory
:
:
mov  a,SADOL          ; read low byte conversion result value
mov  SADOL_buffer,a   ; save result to user defined register
```

```
mov  a,SADOH          ; read high byte conversion result value
mov  SADOH_buffer,a   ; save result to user defined register
:
:
EXIT_INT_ISR:
mov  a,status_stack
mov  STATUS,a         ; restore STATUS from user defined memory
mov  a,acc_stack      ; restore ACC from user defined memory
reti
```

Piezoelectric Horn Driver

The device contains a piezoelectric horn driver with a 12V boost converter. The driver is used to drive an external-driving(2-pin) buzzer or a self-driving(3-pin) buzzer.

The ENB pin is used to select buzzer mode and boost converter on/off. When the ENB pin is set to high, the driver is in the shutdown mode, the buzzer driver and boost converter are both off.

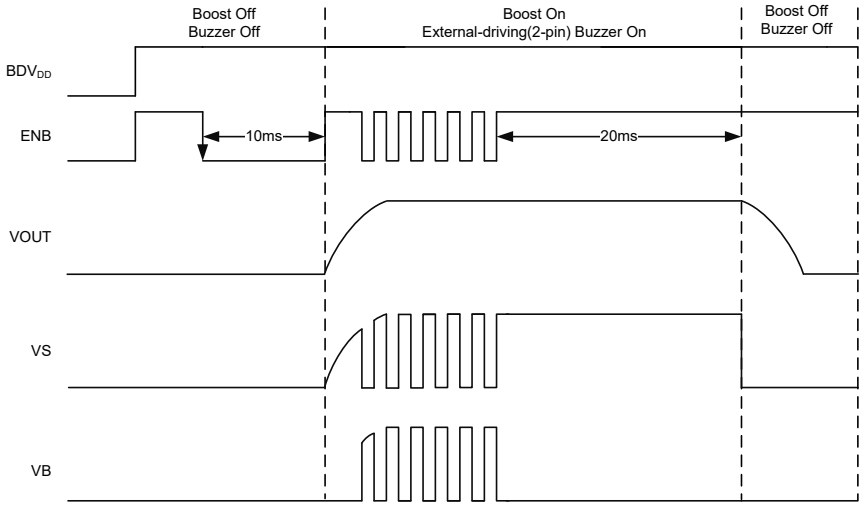


Piezoelectric Horn Driver Diagram

External-driving(2-pin) Buzzer Driver Mode Settings

The driver is in the shutdown mode by default. Clear the ENB pin to 0 for 10ms, the driver will enter external-driving buzzer driver mode. The boost converter will be on. The control signal of external-driving buzzer is generated by the ENB pin. The VS pin outputs the non-inverted signal of the ENB pin, and the VB pin outputs the inverted signal of the ENB pin.The FB pin should be connect to VSS.

If the ENB pin is always high for 20ms, the driver will enter the shutdown mode.



ENB Timing for Driving External-driving(2-pin) Buzzer

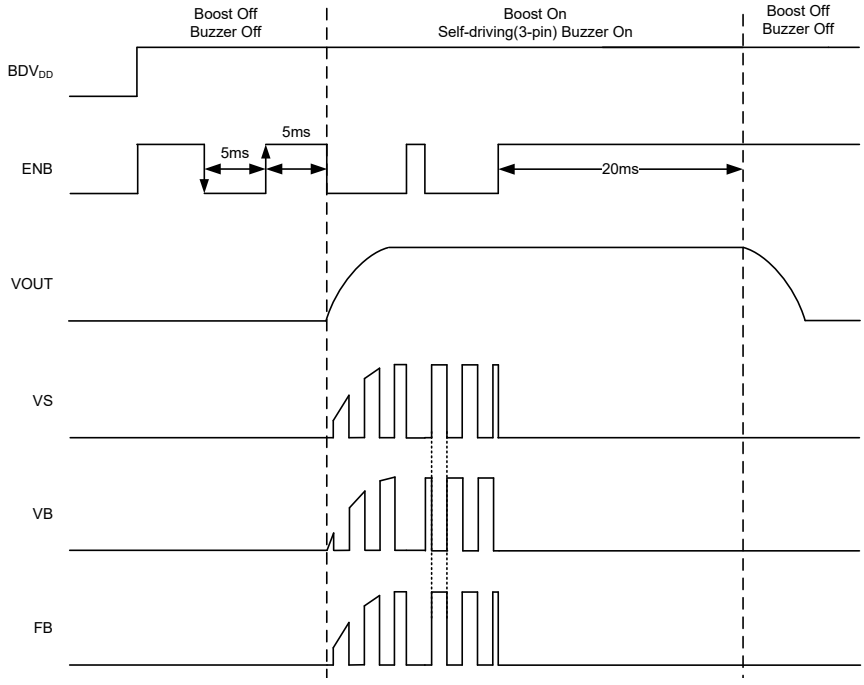
Self-driving(3-pin) Buzzer Driver Mode Settings

The driver is in the shutdown mode by default.Clear the ENB pin to 0 for 5ms, after which set the ENB pin high for 5ms, the driver will enter self-driving buzzer driver mode. The boost converter will be on.

Clear the ENB pin to 0, the self-driving buzzer driver is enabled. Set the ENB pin high, the self-driving buzzer driver is disabled.

If the ENB pin is always high for 20ms, the driver will enter the shutdown mode.

Note: The buzzer mode and shutdown mode settings are achieved by time counting. Attention should be paid to the system noise to avoid IC misjudgment which may reset the internal counter and restart the counting.



ENB Timing for Driving Self-driving(3-pin) Buzzer

Interrupts

Interrupts are an important part of any microcontroller system. When an external event or an internal function such as a Timer Module or an A/D converter requires microcontroller attention, their corresponding interrupt will enforce a temporary suspension of the main program allowing the microcontroller to direct attention to their respective needs. The device contains one external interrupt and several internal interrupts functions. The external interrupt is generated by the action of the external INT pin, while the internal interrupts are generated by various internal functions such as Timer Module, Time Bases and the A/D converter.

Interrupt Registers

Overall interrupt control, which basically means the setting of request flags when certain microcontroller conditions occur and the setting of interrupt enable bits by the application program, is controlled by a series of registers, located in the Special Purpose Data Memory, as shown in the accompanying table. The registers fall into two categories. The first is the INTC0~INTC1 registers which setup the primary interrupts, the second is the INTEG register to setup the external interrupts trigger edge type.

Each register contains a number of enable bits to enable or disable individual registers as well as interrupt flags to indicate the presence of an interrupt request. The naming convention of these follows a specific pattern. First is listed an abbreviated interrupt type, then the (optional) number of that interrupt followed by either an "E" for enable/ disable bit or "F" for request flag.

Function	Enable Bit	Request Flag	Notes
Global	EMI	—	—
INT Pin	INTE	INTF	—
Time Bases	TBnE	TBnF	n=0~1
A/D Converter	ADE	ADF	—
PTM	PTMAE	PTMAF	—
	PTMPE	PTMPF	

Interrupt Register Bit Naming Conventions

Register Name	Bit							
	7	6	5	4	3	2	1	0
INTEG	—	—	—	—	—	—	INTS1	INTS0
INTC0	—	PTMPF	ADF	INTF	PTMPE	ADE	INTE	EMI
INTC1	—	TB1F	TB0F	PTMAF	—	TB1E	TB0E	PTMAE

Interrupt Register List

• INTEG Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	INTS1	INTS0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **INTS1~INTS0**: Interrupt edge control for INT pin
00: Disable
01: Rising edge
10: Falling edge
11: Both rising and falling edges

• **INTC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	PTMPF	ADF	INTF	PTMPE	ADE	INTE	EMI
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	0	0	0	0	0	0	0

Bit 7 Unimplemented, read as "0"

Bit 6 **PTMPF**: PTM Comparator P match interrupt request flag
0: No request
1: Interrupt request

Bit 5 **ADF**: A/D Converter interrupt request flag
0: No request
1: Interrupt request

Bit 4 **INTF**: External Interrupt request flag
0: No request
1: Interrupt request

Bit 3 **PTMPE**: PTM Comparator P match interrupt control
0: Disable
1: Enable

Bit 2 **ADE**: A/D Converter interrupt control
0: Disable
1: Enable

Bit 1 **INTE**: External Interrupt control
0: Disable
1: Enable

Bit 0 **EMI**: Global Interrupt control
0: Disable
1: Enable

• **INTC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	TB1F	TB0F	PTMAF	—	TB1E	TB0E	PTMAE
R/W	—	R/W	R/W	R/W	—	R/W	R/W	R/W
POR	—	0	0	0	—	0	0	0

Bit 7 Unimplemented, read as "0"

Bit 6 **TB1F**: Time Base 1 interrupt request flag
0: No request
1: Interrupt request

Bit 5 **TB0F**: Time Base 0 interrupt request flag
0: No request
1: Interrupt request

Bit 4 **PTMAF**: PTM Comparator A match interrupt request flag
0: No request
1: Interrupt request

Bit 3 Unimplemented, read as "0"

Bit 2 **TB1E**: Time Base 1 interrupt control
0: Disable
1: Enable

Bit 1 **TB0E**: Time Base 0 interrupt control
0: Disable
1: Enable

Bit 0 **PTMAE**: PTM Comparator A match interrupt control
0: Disable
1: Enable

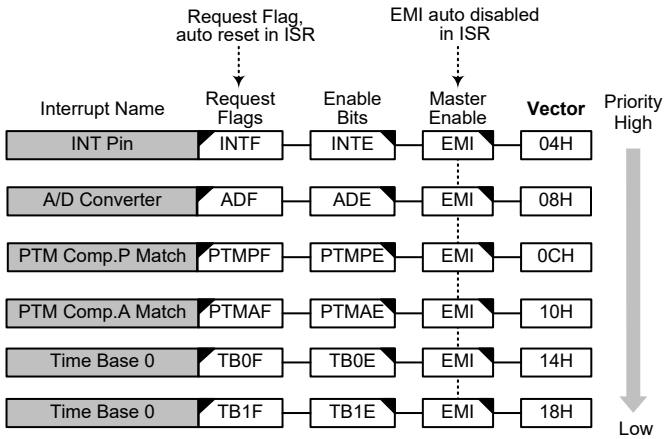
Interrupt Operation

When the conditions for an interrupt event occur, such as a Timer Module compare match or A/D conversion completion etc., the relevant interrupt request flag will be set. Whether the request flag actually generates a program jump to the relevant interrupt vector is determined by the condition of the interrupt enable bit. If the enable bit is set high then the program will jump to its relevant vector, if the enable bit is zero then although the interrupt request flag is set an actual interrupt will not be generated and the program will not jump to the relevant interrupt vector. The global interrupt enable bit, if cleared to zero, will disable all interrupts.

When an interrupt is generated, the Program Counter, which stores the address of the next instruction to be executed, will be transferred onto the stack. The Program Counter will then be loaded with a new address which will be the value of the corresponding interrupt vector. The microcontroller will then fetch its next instruction from this interrupt vector. The instruction at this vector will usually be a "JMP" which will jump to another section of program which is known as the interrupt service routine. Here is located the code to control the appropriate interrupt. The interrupt service routine must be terminated with an "RETI", which retrieves the original Program Counter address from the stack and allows the microcontroller to continue with normal execution at the point where the interrupt occurred.

The various interrupt enable bits, together with their associated request flags, are shown in the Accompanying diagrams with their order of priority. Once an interrupt subroutine is serviced, all the other interrupts will be blocked, as the global interrupt enable bit, EMI bit will be cleared automatically. This will prevent any further interrupt nesting from occurring. However, if other interrupt requests occur during this interval, although the interrupt will not be immediately serviced, the request flag will still be recorded.

If an interrupt requires immediate servicing while the program is already in another interrupt service routine, the EMI bit should be set after entering the routine, to allow interrupt nesting. If the stack is full, the interrupt request will not be acknowledged, even if the related interrupt is enabled, until the Stack Pointer is decremented. If immediate service is desired, the stack must be prevented from becoming full. In case of simultaneous requests, the accompanying diagram shows the priority that is applied. All of the interrupt request flags when set will wake-up the device if it is in SLEEP or IDLE Mode, however to prevent a wake-up from occurring the corresponding flag should be set before the device is in SLEEP or IDLE Mode.



Interrupt Structure

External Interrupt

The external interrupt is controlled by signal transitions on the INT pin. An external interrupt request will take place when the external interrupt request flag, INTF, is set, which will occur when a transition, whose type is chosen by the edge select bits, appears on the external interrupt pin. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and respective external interrupt enable bit, INTE, must first be set. Additionally the correct interrupt edge type must be selected using the related register to enable the external interrupt function and to choose the trigger edge type. As the external interrupt pins are pin-shared with I/O pins, they can only be configured as external interrupt pins if their external interrupt enable bit in the corresponding interrupt register has been set. The pin must also be setup as an input by setting the corresponding bit in the port control register.

When the interrupt is enabled, the stack is not full and the correct transition type appears on the external interrupt pin, a subroutine call to the external interrupt vector, will take place. When the interrupt is serviced, the external interrupt request flag, INTF, will be automatically reset and the EMI bit will be automatically cleared to disable other interrupts. Note that any pull-high resistor selections on the external interrupt pin will remain valid even if the pin is used as an external interrupt input.

The INTEG register is used to select the type of active edge that will trigger the external interrupt. A choice of either rising or falling or both edge types can be chosen to trigger an external interrupt. Note that the INTEG register can also be used to disable the external interrupt function.

Timer Module Interrupts

The Periodic type TM has two interrupts, one comes from the comparator A match situation and the other comes from the comparator P match situation. There are two interrupt request flags and two enable control bits. A TM interrupt request will take place when any of the TM request flags are set, a situation which occurs when a TM comparator P or A match situation happens.

To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and respective TM Interrupt enable bit, must first be set. When the interrupt is enabled, the stack is not full and a TM comparator match situation occurs, a subroutine call to the relevant interrupt vector locations, will take place. When the TM interrupt is serviced, the TM interrupt request flags will be automatically cleared, the EMI bit will also be automatically cleared to disable other interrupts.

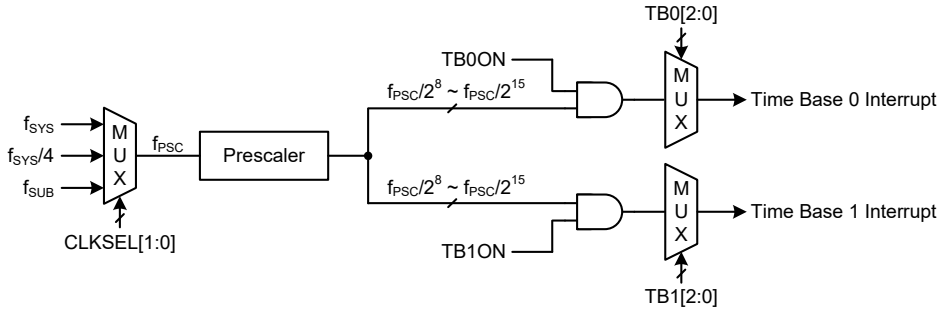
A/D Converter Interrupt

The A/D Converter Interrupt is controlled by the termination of an A/D conversion process. An A/D Converter Interrupt request will take place when the A/D Converter Interrupt request flag, ADF, is set, which occurs when the A/D conversion process finishes. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and A/D Interrupt enable bit, ADE, and associated Multi-function interrupt enable bit, must first be set. When the interrupt is enabled, the stack is not full and the A/D conversion process has ended, a subroutine call to the A/D Converter Interrupt vector, will take place. When the interrupt is serviced, the EMI bit will be automatically cleared to disable other interrupts, however only the Multi-function interrupt request flag will be also automatically cleared. As the ADF flag will not be automatically cleared, it has to be cleared by the application program.

Time Base Interrupts

The function of the Time Base Interrupts is to provide regular time signal in the form of an internal interrupt. They are controlled by the overflow signals from their respective timer functions. When these happens their respective interrupt request flags, TB0F or TB1F will be set. To allow the program to branch to their respective interrupt vector addresses, the global interrupt enable bit, EMI and Time Base enable bits, TB0E or TB1E, must first be set. When the interrupt is enabled, the stack is not full and the Time Base overflows, a subroutine call to their respective vector locations will take place. When the interrupt is serviced, the respective interrupt request flag, TB0F or TB1F, will be automatically reset and the EMI bit will be cleared to disable other interrupts.

The purpose of the Time Base Interrupt is to provide an interrupt signal at fixed time periods. Its clock source, f_{PSC}, originates from the internal clock source f_{SYS}, $f_{SYS}/4$ or f_{SUB} and then passes through a divider, the division ratio of which is selected by programming the appropriate bits in the TB0C and TB1C registers to obtain longer interrupt periods whose value ranges. The clock source which in turn controls the Time Base interrupt period is selected using the CLKSEL1~CLKSEL0 bits in the PSCR register.



Time Base Interrupts

• **PSCR Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	CLKSEL1	CLKSEL0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **CLKSEL1~CLKSEL0**: Prescaler clock source selection
00: f_{SYS}
01: $f_{SYS}/4$
1x: f_{SUB}

• **TB0C Register**

Bit	7	6	5	4	3	2	1	0
Name	TB0ON	—	—	—	—	TB02	TB01	TB00
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

Bit 7 **TB0ON**: Time Base 0 Control
0: Disable
1: Enable

Bit 6~3 Unimplemented, read as "0"

Bit 2~0 **TB02~TB00**: Select Time Base 0 Time-out Period
000: $2^8/f_{PSC}$
001: $2^9/f_{PSC}$
010: $2^{10}/f_{PSC}$
011: $2^{11}/f_{PSC}$
100: $2^{12}/f_{PSC}$
101: $2^{13}/f_{PSC}$
110: $2^{14}/f_{PSC}$
111: $2^{15}/f_{PSC}$

• **TB1C Register**

Bit	7	6	5	4	3	2	1	0
Name	TB1ON	—	—	—	—	TB12	TB11	TB10
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

Bit 7 **TB1ON**: Time Base 1 Control
0: Disable
1: Enable

Bit 6~3 Unimplemented, read as "0"

Bit 2~0 **TB12~TB10**: Select Time Base 1 Time-out Period
000: $2^8/f_{PSC}$
001: $2^9/f_{PSC}$
010: $2^{10}/f_{PSC}$
011: $2^{11}/f_{PSC}$
100: $2^{12}/f_{PSC}$
101: $2^{13}/f_{PSC}$
110: $2^{14}/f_{PSC}$
111: $2^{15}/f_{PSC}$

Interrupt Wake-up Function

Each of the interrupt functions has the capability of waking up the microcontroller when in the SLEEP or IDLE Mode. A wake-up is generated when an interrupt request flag changes from low to high and is independent of whether the interrupt is enabled or not. Therefore, even though the device is in the SLEEP or IDLE Mode and its system oscillator stopped, situations such as external edge transitions on the external interrupt pins may cause their respective interrupt flag to be set high and consequently generate an interrupt. Care must therefore be taken if spurious wake-up situations are to be avoided. If an interrupt wake-up function is to be disabled then the corresponding interrupt request flag should be set high before the device enters the SLEEP or IDLE Mode. The interrupt enable bits have no effect on the interrupt wake-up function.

Programming Considerations

By disabling the relevant interrupt enable bits, a requested interrupt can be prevented from being serviced, however, once an interrupt request flag is set, it will remain in this condition in the interrupt register until the corresponding interrupt is serviced or until the request flag is cleared by the application program.

It is recommended that programs do not use the "CALL" instruction within the interrupt service subroutine. Interrupts often occur in an unpredictable manner or need to be serviced immediately. If only one stack is left and the interrupt is not well controlled, the original control sequence will be damaged once a CALL subroutine is executed in the interrupt subroutine.

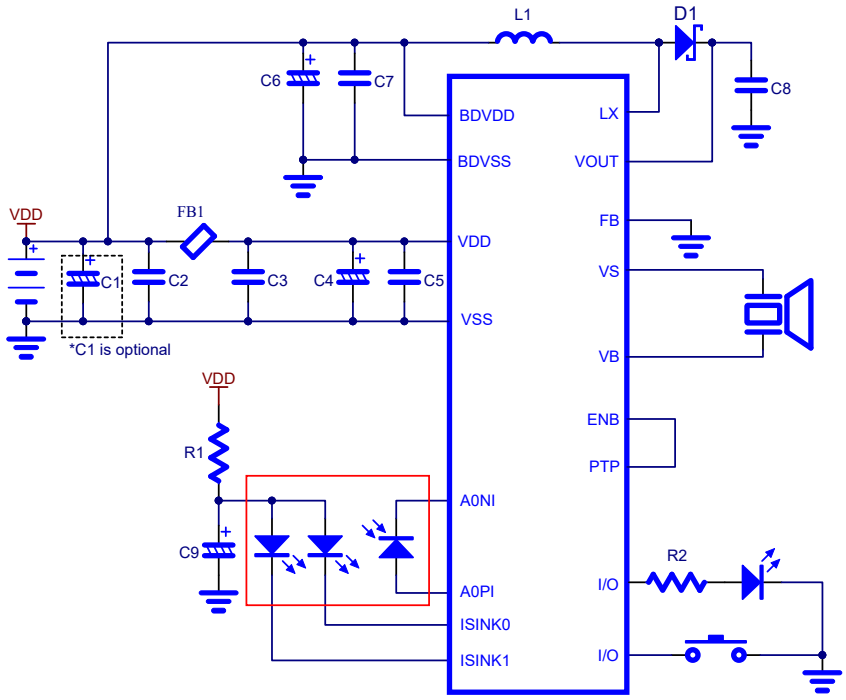
Every interrupt has the capability of waking up the microcontroller when it is in SLEEP or IDLE Mode, the wake up being generated when the interrupt request flag changes from low to high. If it is required to prevent a certain interrupt from waking up the microcontroller then its respective request flag should be first set high before enter SLEEP or IDLE Mode.

As only the Program Counter is pushed onto the stack, then when the interrupt is serviced, if the contents of the accumulator, status register or other registers are altered by the interrupt service program, their contents should be saved to the memory at the beginning of the interrupt service routine.

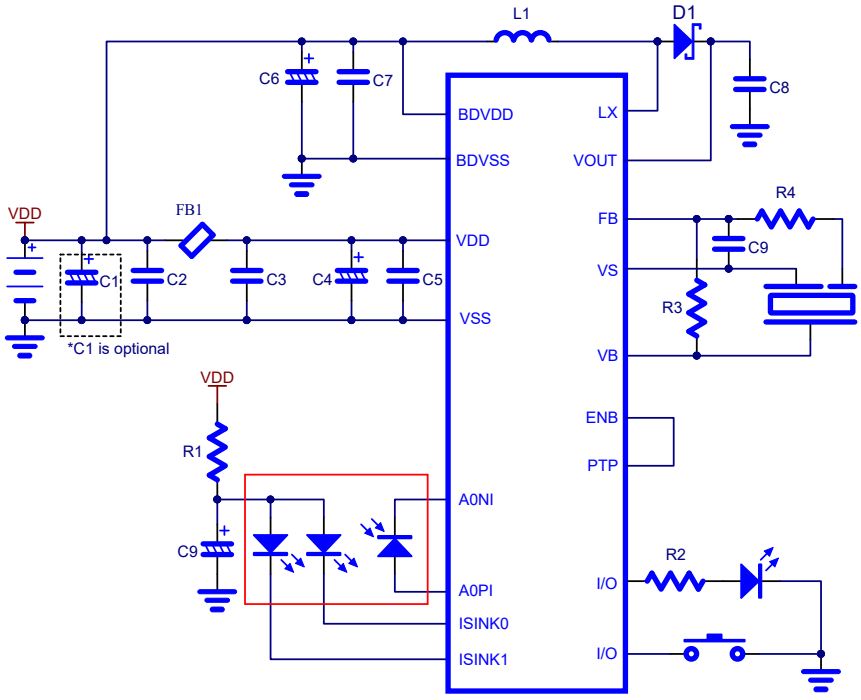
To return from an interrupt subroutine, either an RET or RETI instruction may be executed. The RETI instruction in addition to executing a return to the main program also automatically sets the EMI bit high to allow further interrupts. The RET instruction however only executes a return to the main program leaving the EMI bit in its present zero state and therefore disabling the execution of further interrupts.

Application Circuits

External-driving (2-pin) Buzzer



Self-driving (3-pin) Buzzer



Note: L1=10μH; C8=2.2μF; C6=47μF; C7=0.1μF.

Instruction Set

Introduction

Central to the successful operation of any microcontroller is its instruction set, which is a set of program instruction codes that directs the microcontroller to perform certain operations. In the case of Holtek microcontroller, a comprehensive and flexible set of over 60 instructions is provided to enable programmers to implement their application with the minimum of programming overheads.

For easier understanding of the various instruction codes, they have been subdivided into several functional groupings.

Instruction Timing

Most instructions are implemented within one instruction cycle. The exceptions to this are branch, call, or table read instructions where two instruction cycles are required. One instruction cycle is equal to 4 system clock cycles, therefore in the case of an 8MHz system oscillator, most instructions would be implemented within 0.5μs and branch or call instructions would be implemented within 1μs. Although instructions which require one more cycle to implement are generally limited to the JMP, CALL, RET, RETI and table read instructions, it is important to realize that any other instructions which involve manipulation of the Program Counter Low register or PCL will also take one more cycle to implement. As instructions which change the contents of the PCL will imply a direct jump to that new address, one more cycle will be required. Examples of such instructions would be "CLR PCL" or "MOV PCL, A". For the case of skip instructions, it must be noted that if the result of the comparison involves a skip operation then this will also take one more cycle, if no skip is involved then only one cycle is required.

Moving and Transferring Data

The transfer of data within the microcontroller program is one of the most frequently used operations. Making use of three kinds of MOV instructions, data can be transferred from registers to the Accumulator and vice-versa as well as being able to move specific immediate data directly into the Accumulator. One of the most important data transfer applications is to receive data from the input ports and transfer data to the output ports.

Arithmetic Operations

The ability to perform certain arithmetic operations and data manipulation is a necessary feature of most microcontroller applications. Within the Holtek microcontroller instruction set are a range of add and subtract instruction mnemonics to enable the necessary arithmetic to be carried out. Care must be taken to ensure correct handling of carry and borrow data when results exceed 255 for addition and less than 0 for subtraction. The increment and decrement instructions INC, INCA, DEC and DECA provide a simple means of increasing or decreasing by a value of one of the values in the destination specified.

Logical and Rotate Operation

The standard logical operations such as AND, OR, XOR and CPL all have their own instruction within the Holtek microcontroller instruction set. As with the case of most instructions involving data manipulation, data must pass through the Accumulator which may involve additional programming steps. In all logical data operations, the zero flag may be set if the result of the operation is zero. Another form of logical data manipulation comes from the rotate instructions such as RR, RL, RRC and RLC which provide a simple means of rotating one bit right or left. Different rotate instructions exist depending on program requirements. Rotate instructions are useful for serial port programming applications where data can be rotated from an internal register into the Carry bit from where it can be examined and the necessary serial bit set high or low. Another application which rotate data operations are used is to implement multiplication and division calculations.

Branches and Control Transfer

Program branching takes the form of either jumps to specified locations using the JMP instruction or to a subroutine using the CALL instruction. They differ in the sense that in the case of a subroutine call, the program must return to the instruction immediately when the subroutine has been carried out. This is done by placing a return instruction "RET" in the subroutine which will cause the program to jump back to the address right after the CALL instruction. In the case of a JMP instruction, the program simply jumps to the desired location. There is no requirement to jump back to the original jumping off point as in the case of the CALL instruction. One special and extremely useful set of branch instructions are the conditional branches. Here a decision is first made regarding the condition of a certain data memory or individual bits. Depending upon the conditions, the program will continue with the next instruction or skip over it and jump to the following instruction. These instructions are the key to decision making and branching within the program perhaps determined by the condition of certain input switches or by the condition of internal data bits.

Bit Operations

The ability to provide single bit operations on Data Memory is an extremely flexible feature of all Holtek microcontrollers. This feature is especially useful for output port bit programming where individual bits or port pins can be directly set high or low using either the "SET [m].i" or "CLR [m].i" instructions respectively. The feature removes the need for programmers to first read the 8-bit output port, manipulate the input data to ensure that other bits are not changed and then output the port with the correct new data. This read-modify-write process is taken care of automatically when these bit operation instructions are used.

Table Read Operations

Data storage is normally implemented by using registers. However, when working with large amounts of fixed data, the volume involved often makes it inconvenient to store the fixed data in the Data Memory. To overcome this problem, Holtek microcontrollers allow an area of Program Memory to be set as a table where data can be directly stored. A set of easy to use instructions provides the means by which this fixed data can be referenced and retrieved from the Program Memory.

Other Operations

In addition to the above functional instructions, a range of other instructions also exist such as the "HALT" instruction for Power-down operations and instructions to control the operation of the Watchdog Timer for reliable program operations under extreme electric or electromagnetic environments. For their relevant operations, refer to the functional related sections.

Instruction Set Summary

The following table depicts a summary of the instruction set categorised according to function and can be consulted as a basic instruction reference using the following listed conventions.

Table Conventions

x: Bits immediate data
m: Data Memory address
A: Accumulator
i: 0~7 number of bits
addr: Program memory address

Mnemonic	Description	Cycles	Flag Affected
Arithmetic			
ADD A,[m]	Add Data Memory to ACC	1	Z, C, AC, OV
ADDM A,[m]	Add ACC to Data Memory	1Note	Z, C, AC, OV
ADD A,x	Add immediate data to ACC	1	Z, C, AC, OV
ADC A,[m]	Add Data Memory to ACC with Carry	1	Z, C, AC, OV
ADCM A,[m]	Add ACC to Data memory with Carry	1Note	Z, C, AC, OV
SUB A,x	Subtract immediate data from the ACC	1	Z, C, AC, OV
SUB A,[m]	Subtract Data Memory from ACC	1	Z, C, AC, OV
SUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory	1Note	Z, C, AC, OV
SBC A,[m]	Subtract Data Memory from ACC with Carry	1	Z, C, AC, OV
SBCM A,[m]	Subtract Data Memory from ACC with Carry, result in Data Memory	1Note	Z, C, AC, OV
DAA [m]	Decimal adjust ACC for Addition with result in Data Memory	1Note	C
Logic Operation			
AND A,[m]	Logical AND Data Memory to ACC	1	Z
OR A,[m]	Logical OR Data Memory to ACC	1	Z
XOR A,[m]	Logical XOR Data Memory to ACC	1	Z
ANDM A,[m]	Logical AND ACC to Data Memory	1Note	Z
ORM A,[m]	Logical OR ACC to Data Memory	1Note	Z
XORM A,[m]	Logical XOR ACC to Data Memory	1Note	Z
AND A,x	Logical AND immediate Data to ACC	1	Z
OR A,x	Logical OR immediate Data to ACC	1	Z
XOR A,x	Logical XOR immediate Data to ACC	1	Z
CPL [m]	Complement Data Memory	1Note	Z
CPLA [m]	Complement Data Memory with result in ACC	1	Z
Increment & Decrement			
INCA [m]	Increment Data Memory with result in ACC	1	Z
INC [m]	Increment Data Memory	1Note	Z
DECA [m]	Decrement Data Memory with result in ACC	1	Z
DEC [m]	Decrement Data Memory	1Note	Z
Rotate			
RRA [m]	Rotate Data Memory right with result in ACC	1	None
RR [m]	Rotate Data Memory right	1Note	None
RRCA [m]	Rotate Data Memory right through Carry with result in ACC	1	C
RRC [m]	Rotate Data Memory right through Carry	1Note	C
RLA [m]	Rotate Data Memory left with result in ACC	1	None
RL [m]	Rotate Data Memory left	1Note	None
RLCA [m]	Rotate Data Memory left through Carry with result in ACC	1	C
RLC [m]	Rotate Data Memory left through Carry	1Note	C

Mnemonic	Description	Cycles	Flag Affected
Data Move			
MOV A,[m]	Move Data Memory to ACC	1	None
MOV [m],A	Move ACC to Data Memory	1Note	None
MOV A,x	Move immediate data to ACC	1	None
Bit Operation			
CLR [m].i	Clear bit of Data Memory	1Note	None
SET [m].i	Set bit of Data Memory	1Note	None
Branch Operation			
JMP addr	Jump unconditionally	2	None
SZ [m]	Skip if Data Memory is zero	1Note	None
SZA [m]	Skip if Data Memory is zero with data movement to ACC	1Note	None
SZ [m].i	Skip if bit i of Data Memory is zero	1Note	None
SNZ [m].i	Skip if bit i of Data Memory is not zero	1Note	None
SIZ [m]	Skip if increment Data Memory is zero	1Note	None
SDZ [m]	Skip if decrement Data Memory is zero	1Note	None
SIZA [m]	Skip if increment Data Memory is zero with result in ACC	1Note	None
SDZA [m]	Skip if decrement Data Memory is zero with result in ACC	1Note	None
CALL addr	Subroutine call	2	None
RET	Return from subroutine	2	None
RET A,x	Return from subroutine and load immediate data to ACC	2	None
RETI	Return from interrupt	2	None
Table Read Operation			
TABRD [m]	Read table (specific page or current page) to TBLH and Data Memory	2Note	None
TABRDL [m]	Read table (last page) to TBLH and Data Memory	2Note	None
Miscellaneous			
NOP	No operation	1	None
CLR [m]	Clear Data Memory	1Note	None
SET [m]	Set Data Memory	1Note	None
CLR WDT	Clear Watchdog Timer	1	TO, PDF
SWAP [m]	Swap nibbles of Data Memory	1Note	None
SWAPA [m]	Swap nibbles of Data Memory with result in ACC	1	None
HALT	Enter power down mode	1	TO, PDF

Note: 1. For skip instructions, if the result of the comparison involves a skip then two cycles are required, if no skip takes place only one cycle is required.
2. Any instruction which changes the contents of the PCL will also require 2 cycles for execution.

Instruction Definition

ADC A,[m] Add Data Memory to ACC with Carry

Description The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the Accumulator.

Operation ACC ← ACC + [m] + C

Affected flag(s) OV, Z, AC, C

ADCM A,[m] Add ACC to Data Memory with Carry

Description The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the specified Data Memory.

Operation [m] ← ACC + [m] + C

Affected flag(s) OV, Z, AC, C

ADD A,[m] Add Data Memory to ACC

Description The contents of the specified Data Memory and the Accumulator are added. The result is stored in the Accumulator.

Operation ACC ← ACC + [m]

Affected flag(s) OV, Z, AC, C

ADD A,x Add immediate data to ACC

Description The contents of the Accumulator and the specified immediate data are added. The result is stored in the Accumulator.

Operation ACC ← ACC + x

Affected flag(s) OV, Z, AC, C

ADDM A,[m] Add ACC to Data Memory

Description The contents of the specified Data Memory and the Accumulator are added. The result is stored in the specified Data Memory.

Operation [m] ← ACC + [m]

Affected flag(s) OV, Z, AC, C

AND A,[m] Logical AND Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical AND operation. The result is stored in the Accumulator.

Operation ACC ← ACC "AND" [m]

Affected flag(s) Z

AND A,x Logical AND immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bit wise logical AND operation. The result is stored in the Accumulator.

Operation ACC ← ACC "AND" x

Affected flag(s) Z

ANDM A,[m] Logical AND ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical AND operation. The result is stored in the Data Memory.

Operation [m] ← ACC "AND" [m]

Affected flag(s) Z

CALL addr Subroutine call

Description Unconditionally calls a subroutine at the specified address. The Program Counter then increments by 1 to obtain the address of the next instruction which is then pushed onto the stack. The specified address is then loaded and the program continues execution from this new address. As this instruction requires an additional operation, it is a two cycle instruction.

Operation Stack ← Program Counter + 1
Program Counter ← addr

Affected flag(s) None

CLR [m] Clear Data Memory

Description Each bit of the specified Data Memory is cleared to 0.

Operation [m] ← 00H

Affected flag(s) None

CLR [m].i Clear bit of Data Memory

Description Bit i of the specified Data Memory is cleared to 0.

Operation [m].i ← 0

Affected flag(s) None

CLR WDT Clear Watchdog Timer

Description The TO, PDF flags and the WDT are all cleared.

Operation WDT cleared
TO ← 0
PDF ← 0

Affected flag(s) TO, PDF

CPL [m] Complement Data Memory

Description Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa.

Operation [m] ← $\overline{[m]}$

Affected flag(s) Z

CPLA [m] Complement Data Memory with result in ACC

Description Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa. The complemented result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC ← $\overline{[m]}$

Affected flag(s) Z

DAA [m] Decimal-Adjust ACC for addition with result in Data Memory

Description Convert the contents of the Accumulator value to a BCD (Binary Coded Decimal) value resulting from the previous addition of two BCD variables. If the low nibble is greater than 9 or if AC flag is set, then a value of 6 will be added to the low nibble. Otherwise the low nibble remains unchanged. If the high nibble is greater than 9 or if the C flag is set, then a value of 6 will be added to the high nibble. Essentially, the decimal conversion is performed by adding 00H, 06H, 60H or 66H depending on the Accumulator and flag conditions. Only the C flag may be affected by this instruction which indicates that if the original BCD sum is greater than 100, it allows multiple precision decimal addition.

Operation [m] ← ACC + 00H or
[m] ← ACC + 06H or
[m] ← ACC + 60H or
[m] ← ACC + 66H

Affected flag(s) C

DEC [m] Decrement Data Memory

Description Data in the specified Data Memory is decremented by 1.

Operation [m] ← [m] − 1

Affected flag(s) Z

DECA [m] Decrement Data Memory with result in ACC

Description Data in the specified Data Memory is decremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation ACC ← [m] − 1

Affected flag(s) Z

HALT Enter power down mode

Description This instruction stops the program execution and turns off the system clock. The contents of the Data Memory and registers are retained. The WDT and prescaler are cleared. The power down flag PDF is set and the WDT time-out flag TO is cleared.

Operation TO ← 0
PDF ← 1

Affected flag(s) TO, PDF

INC [m] Increment Data Memory

Description Data in the specified Data Memory is incremented by 1.

Operation [m] ← [m] + 1

Affected flag(s) Z

INCA [m] Increment Data Memory with result in ACC

Description Data in the specified Data Memory is incremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation ACC ← [m] + 1

Affected flag(s) Z

JMP addr Jump unconditionally

Description The contents of the Program Counter are replaced with the specified address. Program execution then continues from this new address. As this requires the insertion of a dummy instruction while the new address is loaded, it is a two cycle instruction.

Operation Program Counter ← addr

Affected flag(s) None

MOV A,[m] Move Data Memory to ACC

Description The contents of the specified Data Memory are copied to the Accumulator.

Operation ACC ← [m]

Affected flag(s) None

MOV A,x Move immediate data to ACC

Description The immediate data specified is loaded into the Accumulator.

Operation ACC ← x

Affected flag(s) None

MOV [m],A Move ACC to Data Memory

Description The contents of the Accumulator are copied to the specified Data Memory.

Operation [m] ← ACC

Affected flag(s) None

NOP No operation

Description No operation is performed. Execution continues with the next instruction.

Operation No operation

Affected flag(s) None

OR A,[m] Logical OR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical OR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″OR″ [m]

Affected flag(s) Z

OR A,x Logical OR immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bitwise logical OR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″OR″ x

Affected flag(s) Z

ORM A,[m] Logical OR ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical OR operation. The result is stored in the Data Memory.

Operation [m] ← ACC ″OR″ [m]

Affected flag(s) Z

RET Return from subroutine

Description The Program Counter is restored from the stack. Program execution continues at the restored address.

Operation Program Counter ← Stack

Affected flag(s) None

RET A,x Return from subroutine and load immediate data to ACC

Description The Program Counter is restored from the stack and the Accumulator loaded with the specified immediate data. Program execution continues at the restored address.

Operation Program Counter ← Stack
ACC ← x

Affected flag(s) None

RETI Return from interrupt

Description The Program Counter is restored from the stack and the interrupts are re-enabled by setting the EMI bit. EMI is the master interrupt global enable bit. If an interrupt was pending when the RETI instruction is executed, the pending Interrupt routine will be processed before returning to the main program.

Operation Program Counter ← Stack
EMI ← 1

Affected flag(s) None

RL [m] Rotate Data Memory left

Description The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0.

Operation [m].(i+1) ← [m].i; (i=0~6)
[m].0 ← [m].7

Affected flag(s) None

RLA [m] Rotate Data Memory left with result in ACC

Description The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← [m].7

Affected flag(s) None

RLC [m] Rotate Data Memory left through Carry

Description The contents of the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into bit 0.

Operation [m].(i+1) ← [m].i; (i=0~6)
[m].0 ← C
C ← [m].7

Affected flag(s) C

RLCA [m] Rotate Data Memory left through Carry with result in ACC

Description Data in the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into the bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← C
C ← [m].7

Affected flag(s) C

RR [m] Rotate Data Memory right

Description The contents of the specified Data Memory are rotated right by 1 bit with bit 0 rotated into bit 7.

Operation [m].i ← [m].(i+1); (i=0~6)
[m].7 ← [m].0

Affected flag(s) None

RRA [m] Rotate Data Memory right with result in ACC

Description Data in the specified Data Memory is rotated right by 1 bit with bit 0 rotated into bit 7.
The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← [m].0

Affected flag(s) None

RRC [m] Rotate Data Memory right through Carry

Description The contents of the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7.

Operation [m].i ← [m].(i+1); (i=0~6)
[m].7 ← C
C ← [m].0

Affected flag(s) C

RRCA [m] Rotate Data Memory right through Carry with result in ACC

Description Data in the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← C
C ← [m].0

Affected flag(s) C

SBC A,[m] Subtract Data Memory from ACC with Carry

Description The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − [m] − $\overline{C}$

Affected flag(s) OV, Z, AC, C

SBCM A,[m] Subtract Data Memory from ACC with Carry and result in Data Memory

Description The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation [m] ← ACC − [m] − $\overline{C}$

Affected flag(s) OV, Z, AC, C

SDZ [m] Skip if decrement Data Memory is 0

Description The contents of the specified Data Memory are first decremented by 1. If the result is 0 the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation [m] ← [m] − 1
Skip if [m]=0

Affected flag(s) None

SDZA [m] Skip if decrement Data Memory is zero with result in ACC

Description The contents of the specified Data Memory are first decremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation ACC ← [m] − 1
Skip if ACC=0

Affected flag(s) None

SET [m] Set Data Memory

Description Each bit of the specified Data Memory is set to 1.

Operation [m] ← FFH

Affected flag(s) None

SET [m].i Set bit of Data Memory

Description Bit i of the specified Data Memory is set to 1.

Operation [m].i ← 1

Affected flag(s) None

SIZ [m] Skip if increment Data Memory is 0

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation [m] ← [m] + 1
Skip if [m]=0

Affected flag(s) None

SIZA [m] Skip if increment Data Memory is zero with result in ACC

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation ACC ← [m] + 1
Skip if ACC=0

Affected flag(s) None

SNZ [m].i Skip if bit i of Data Memory is not 0

Description If bit i of the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is 0 the program proceeds with the following instruction.

Operation Skip if [m].i ≠ 0

Affected flag(s) None

SUB A,[m] Subtract Data Memory from ACC

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − [m]

Affected flag(s) OV, Z, AC, C

SUBM A,[m] Subtract Data Memory from ACC with result in Data Memory

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation [m] ← ACC − [m]

Affected flag(s) OV, Z, AC, C

SUB A,x Subtract immediate data from ACC

Description The immediate data specified by the code is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − x

Affected flag(s) OV, Z, AC, C

SWAP [m] Swap nibbles of Data Memory

Description The low-order and high-order nibbles of the specified Data Memory are interchanged.

Operation [m].3~[m].0 ↔ [m].7~[m].4

Affected flag(s) None

SWAPA [m] Swap nibbles of Data Memory with result in ACC

Description The low-order and high-order nibbles of the specified Data Memory are interchanged. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation ACC.3~ACC.0 ← [m].7~[m].4
ACC.7~ACC.4 ← [m].3~[m].0

Affected flag(s) None

SZ [m] Skip if Data Memory is 0

Description The contents of the specified Data Memory are read out and then written to the specified Data Memory again. If the contents of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation Skip if [m]=0

Affected flag(s) None

SZA [m] Skip if Data Memory is 0 with data movement to ACC

Description The contents of the specified Data Memory are copied to the Accumulator. If the value is zero, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation ACC ← [m]
Skip if [m]=0

Affected flag(s) None

SZ [m].i Skip if bit i of Data Memory is 0

Description If bit i of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation Skip if [m].i=0

Affected flag(s) None

TABRD [m] Read table (specific page or current page) to TBLH and Data Memory

Description The low byte of the program code addressed by the table pointer (TBHP and TBLP or only TBLP if no TBHP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

TABRDL [m] Read table (last page) to TBLH and Data Memory

Description The low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

XOR A,[m] Logical XOR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical XOR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″XOR″ [m]

Affected flag(s) Z

XORM A,[m]	Logical XOR ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical XOR operation. The result is stored in the Data Memory.
Operation	[m] ← ACC ″XOR″ [m]
Affected flag(s)	Z

XOR A,x	Logical XOR immediate data to ACC
Description	Data in the Accumulator and the specified immediate data perform a bitwise logical XOR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC ″XOR″ x
Affected flag(s)	Z

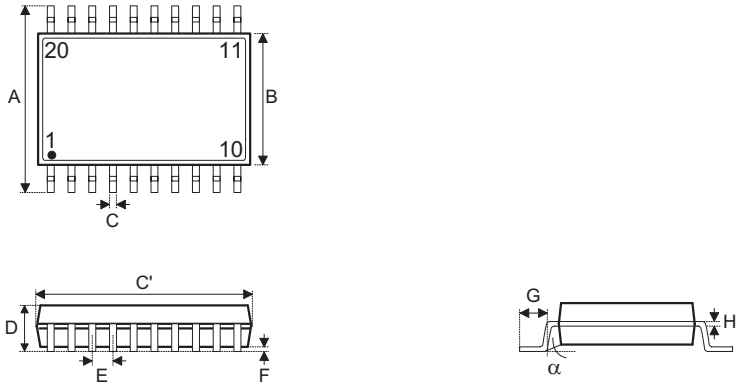
Package Information

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the Holtek website for the latest version of the Package/Carton Information.

Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- The Operation Instruction of Packing Materials
- Carton information

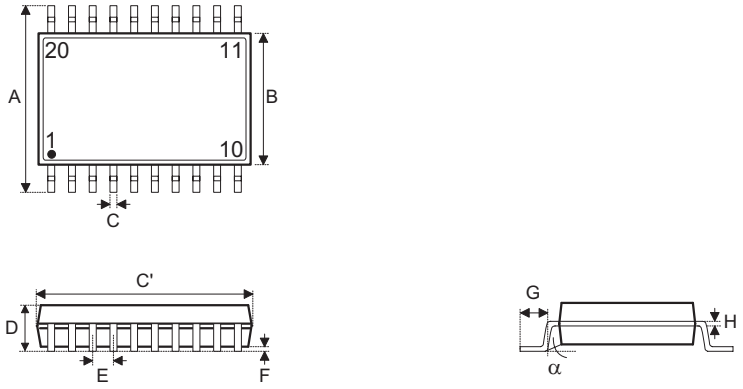
20-pin SOP (300mil) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.406 BSC	—
B	—	0.295 BSC	—
C	0.012	—	0.020
C’	—	0.504 BSC	—
D	—	—	0.104
E	—	0.050 BSC	—
F	0.004	—	0.012
G	0.016	—	0.050
H	0.008	—	0.013
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	10.30 BSC	—
B	—	7.50 BSC	—
C	0.31	—	0.51
C’	—	12.80 BSC	—
D	—	—	2.65
E	—	1.27 BSC	—
F	0.10	—	0.30
G	0.40	—	1.27
H	0.20	—	0.33
α	0°	—	8°

20-pin SSOP (150mil) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.236 BSC	—
B	—	0.154 BSC	—
C	0.008	—	0.012
C’	—	0.341 BSC	—
D	—	—	0.069
E	—	0.025 BSC	—
F	0.004	—	0.0098
G	0.016	—	0.05
H	0.004	—	0.01
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	6.000 BSC	—
B	—	3.900 BSC	—
C	0.20	—	0.30
C’	—	8.660 BSC	—
D	—	—	1.75
E	—	0.635 BSC	—
F	0.10	—	0.25
G	0.41	—	1.27
H	0.10	—	0.25
α	0°	—	8°